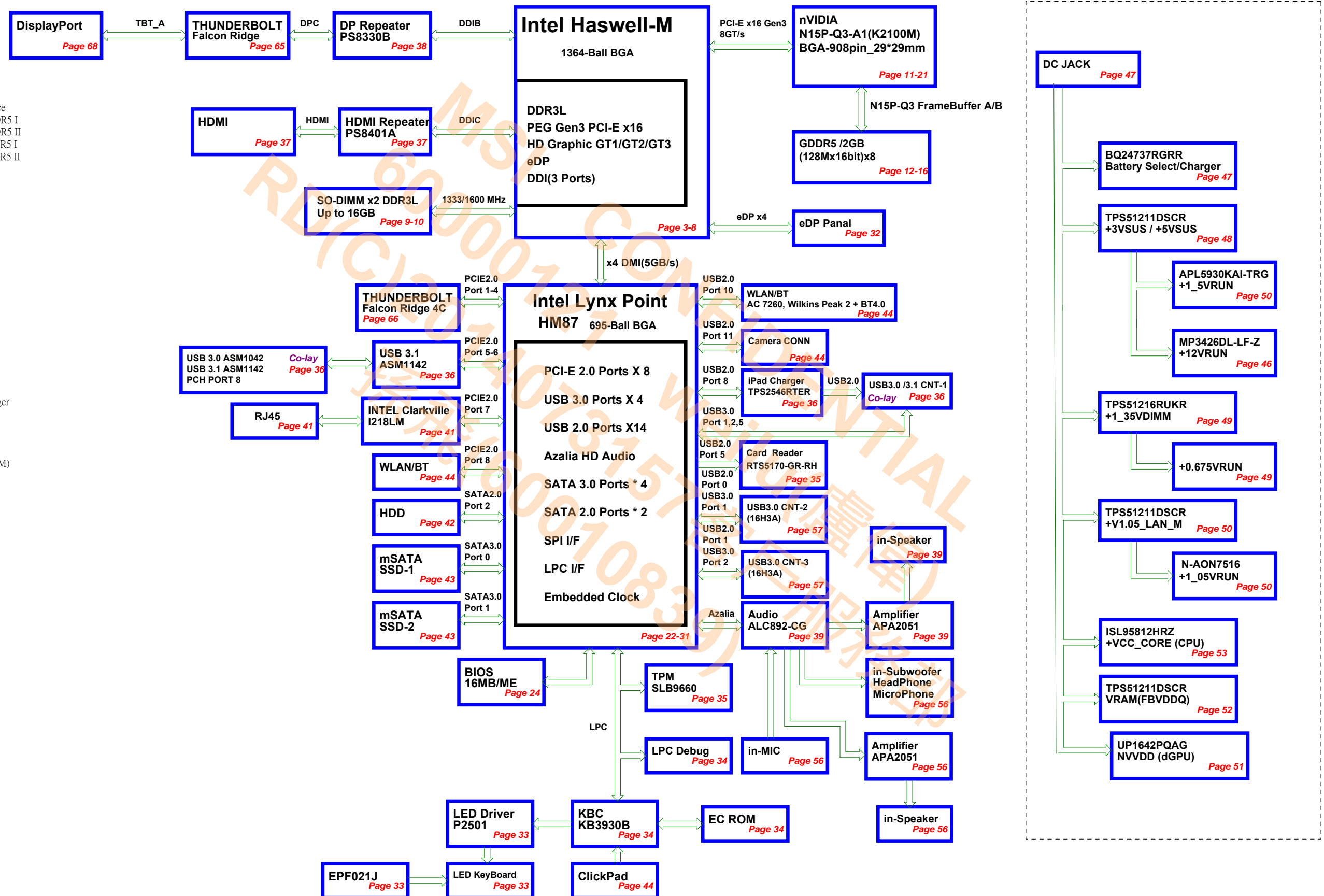


Shark Bay Mobile

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Page 04: CPU-2 (DDR3L)
Page 05: CPU-3 (Display/Reserved)
Page 06: CPU-4 (Power)
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Page 13: DGPU-3_N14P_FrameA GDDR5 I
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Page 47: Battery Select/Charger
Page 48: System Power
Page 49: +1.35VDDIMM/+0.675VRUN
Page 50: +1.05VRUN / +1.5VRUN
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Page 54: EMI/Impedence
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Page 61: Power on Block Diagram
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Page 64: TBT_FR_Misc
Page 65: TBT_FR
Page 66: FR_PCIe_TBT
Page 67: Vcc_Vss
Page 68: TBT_Power
Page 69: History



SCHEMATIC ANNOTATIONS AND BOARD INFORMATION

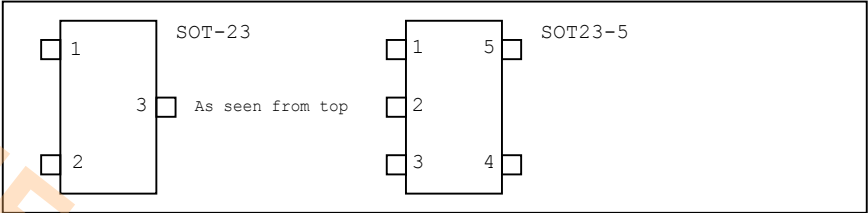
Voltage Rails

Voltage	Description	Control Signal
PWR_SRC	AC ADAPTER OR BATTERY IN	
+5VALW	5.0V always on power rail	PWR_SRC
+3VALW	3.3V always on power rail	PWR_SRC
+5VSUS	5.0V power rail	SUS_ON
+3VSUS	3.3V power rail	SUS_ON
+1_35VDIMM	1.35V DDR3L power rail (off in S4-S5)	DIMM_ON
+0_675VRUN	0.675V DDR3L Termination voltage (off in S3-S5)	PM_SLP_S3#
+5VRUN	5.0V switched power rail (off in S3-S5)	RUN_ON
+3VRUN	3.3V switched power rail (off in S3-S5 / M0)	RUN_ON
+1_5VRUN	1.5V switched power rail (off in S3-S5)	RUN_ON
+VCC_CORE	1.8V Core Voltage for Processor	EC_ALLSYSPG
+1_05VRUN	1.05V rail for Processor	RUN_ON
NVVDD	V Core Voltage for nVIDIA dGPU	NVVDD_EN
+3V3_NV	3.3V PEX power rail (off in Optimus OFF)	DGPU_PWR_EN#
FBVDDQ	1.35V FB / GDDR5 power rail (off in Optimus OFF)	FBVDDQ_ON
PEX_VDD	1.05V PLL power rail (off in Optimus OFF)	NVVDD_EN

Net Naming Conventions

Suffix
= Active Low Signal
Prefix
H = Host
M = DDR Memory
TP = Test Point (does not connect anywhere else)
FB = DGPU VRAM
VIAxxx = Like Test Point, but using VIA.

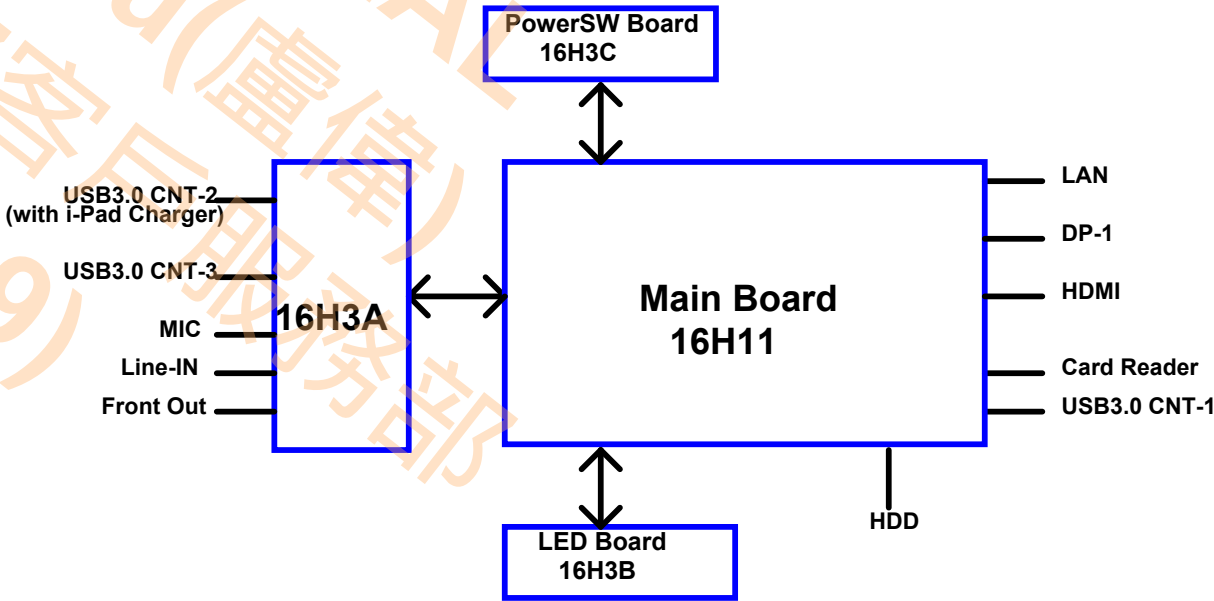
PCB Footprints



POWER STATES

STATE \ SIGNAL	SLP_S3#	SLP_S4#	SLP_S5#	+V*ALW	+*VSUS	+*VRUN	Clocks
S0(Full ON)	HIGH	HIGH	HIGH	ON	ON	ON	ON
S3(Suspend to RAM)	LOW	HIGH	HIGH	ON	ON	OFF	OFF
S4(Suspend to Disk)	LOW	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	LOW	ON	OFF	OFF	OFF

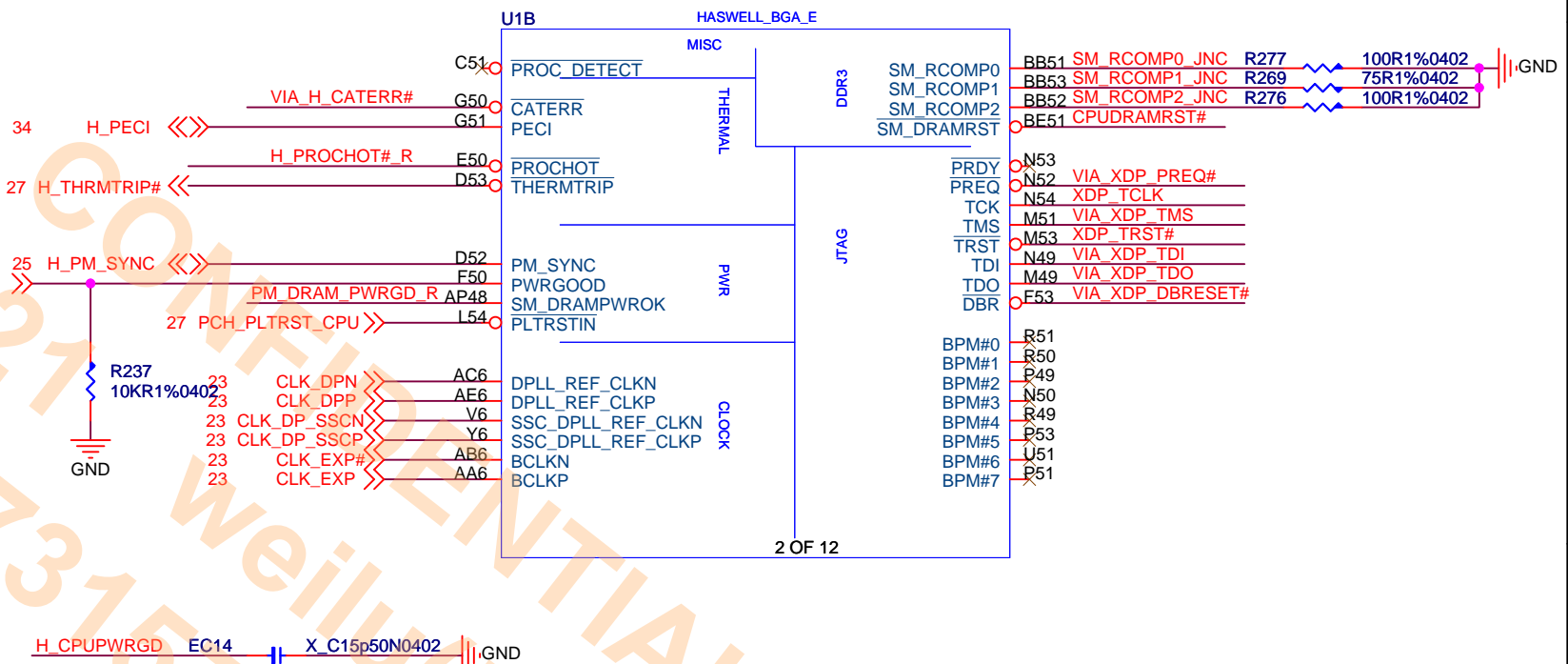
Note : WHEN AC MODE , System turn on and +V*SUS always keep high



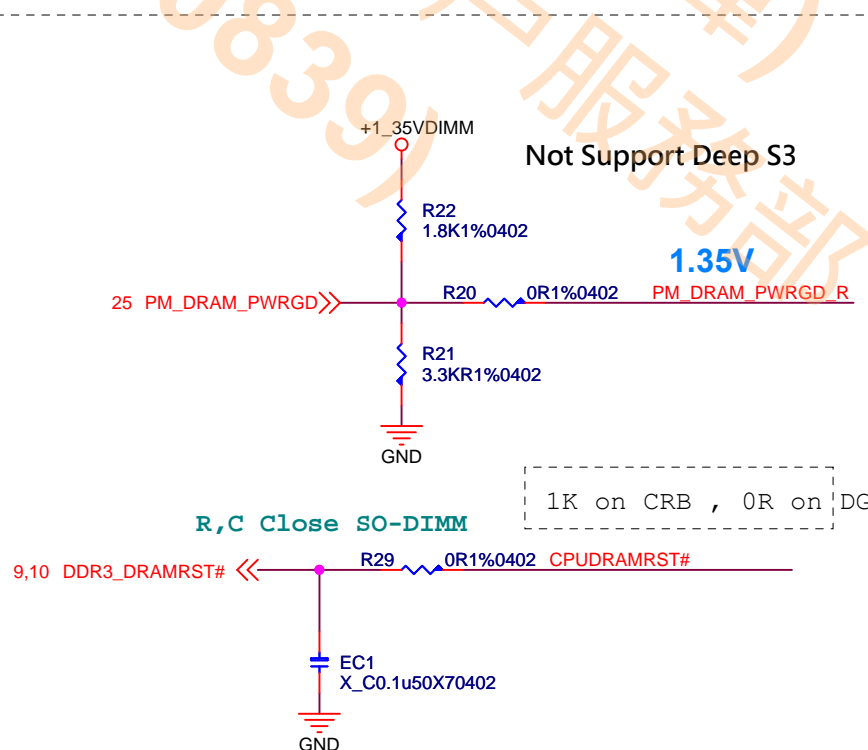
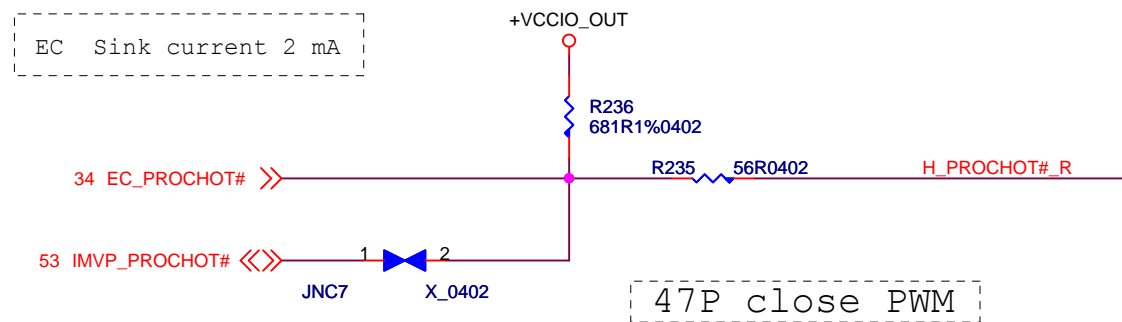
Haswell (DMI,PEG,FDI)

PEG_RCOMP
Width:12 mils
Spacing:15 mils
Length:400 mils

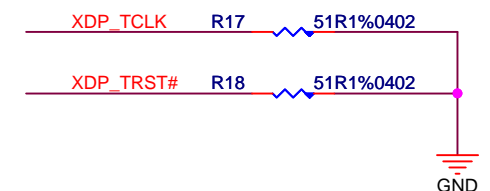
Haswell (CLK,MISC,JTAG)



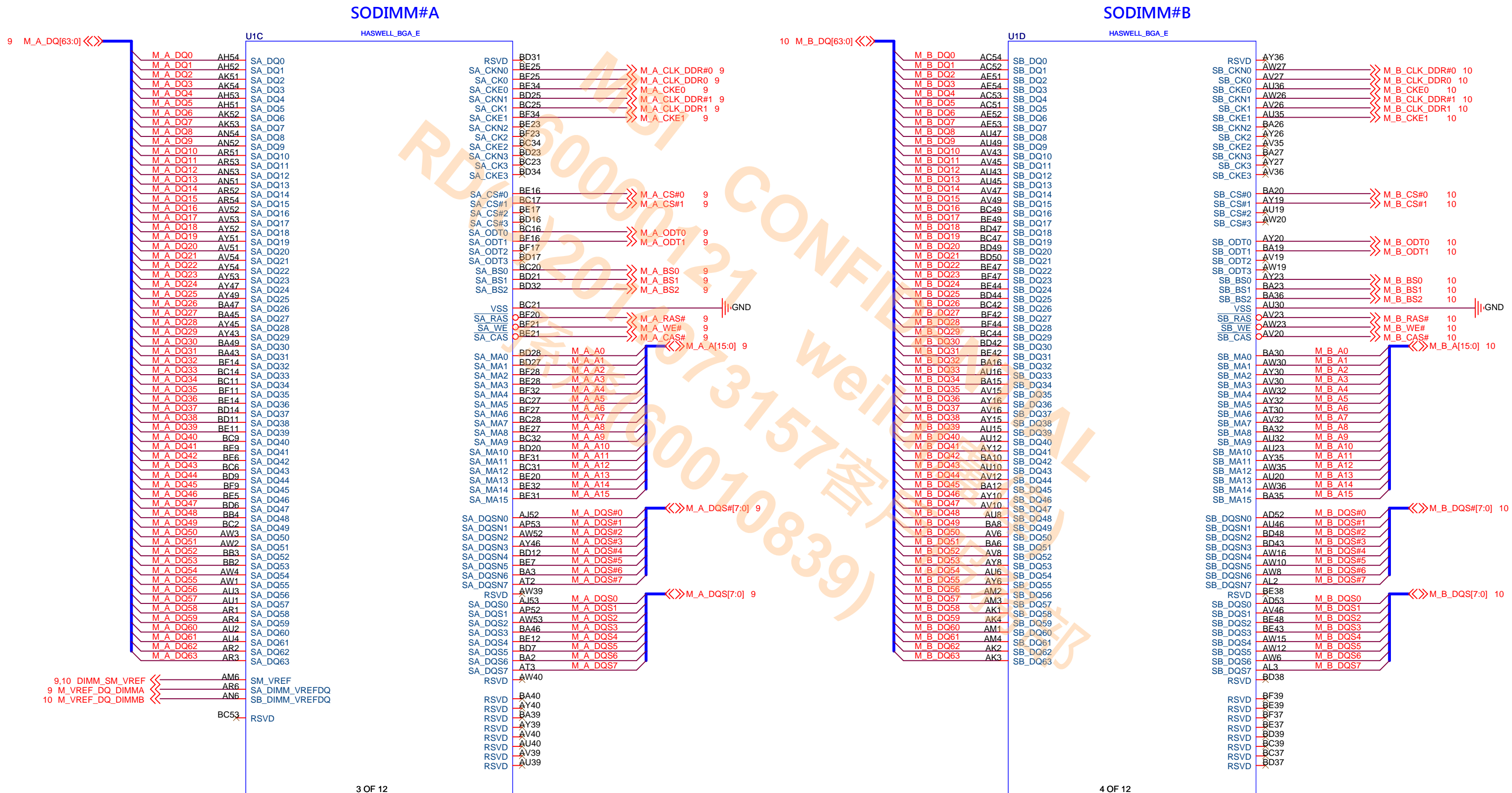
SM_RCOMP_0/1/2 : 15/20/25/15/20/25
SM_RCOMP_0/1/2 Length max: 500mil



p.11 479493_479493_SharkBay_HSW_ext_rev2.0.pdf
Processor JTAG (TDI, TDO, TMS, TRST#, TCK) signals, PREQ# and PRDY# signals have adequate internal bias resistances to support the removal of the external pull up and pull down on the board when debug is no longer needed.



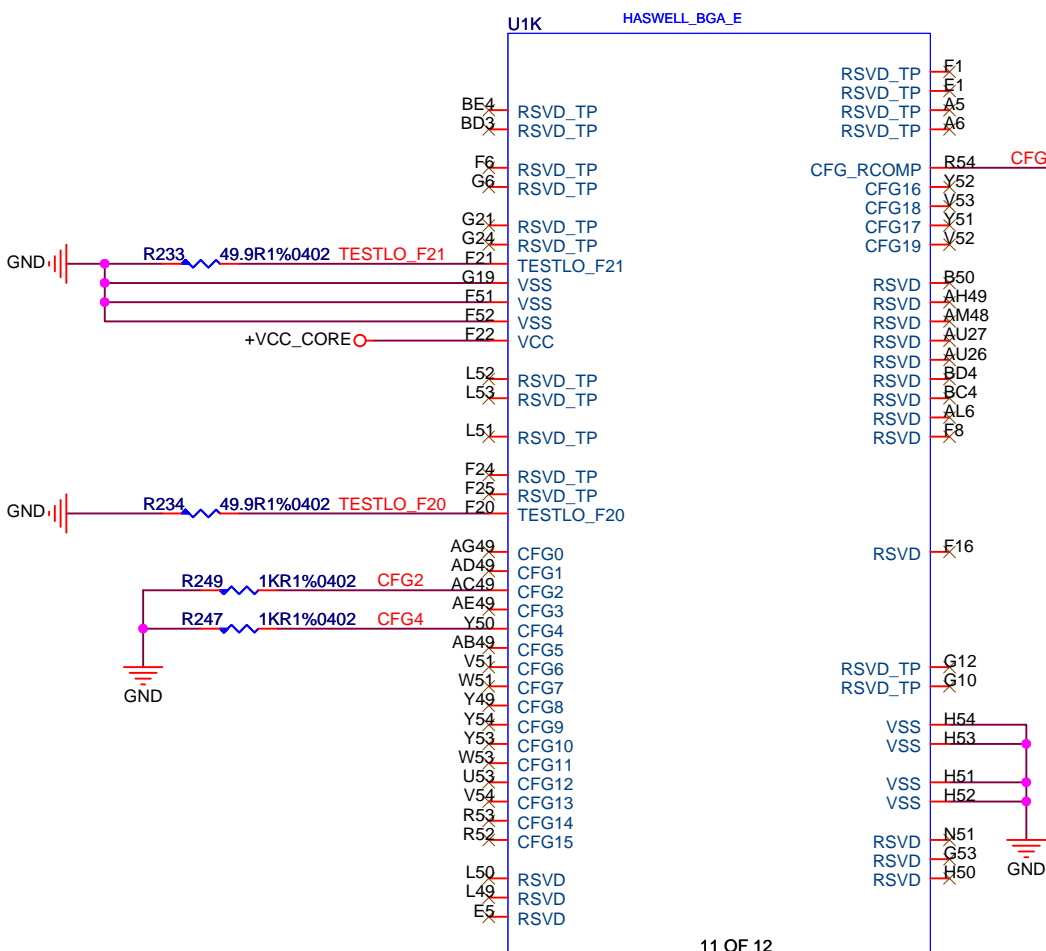
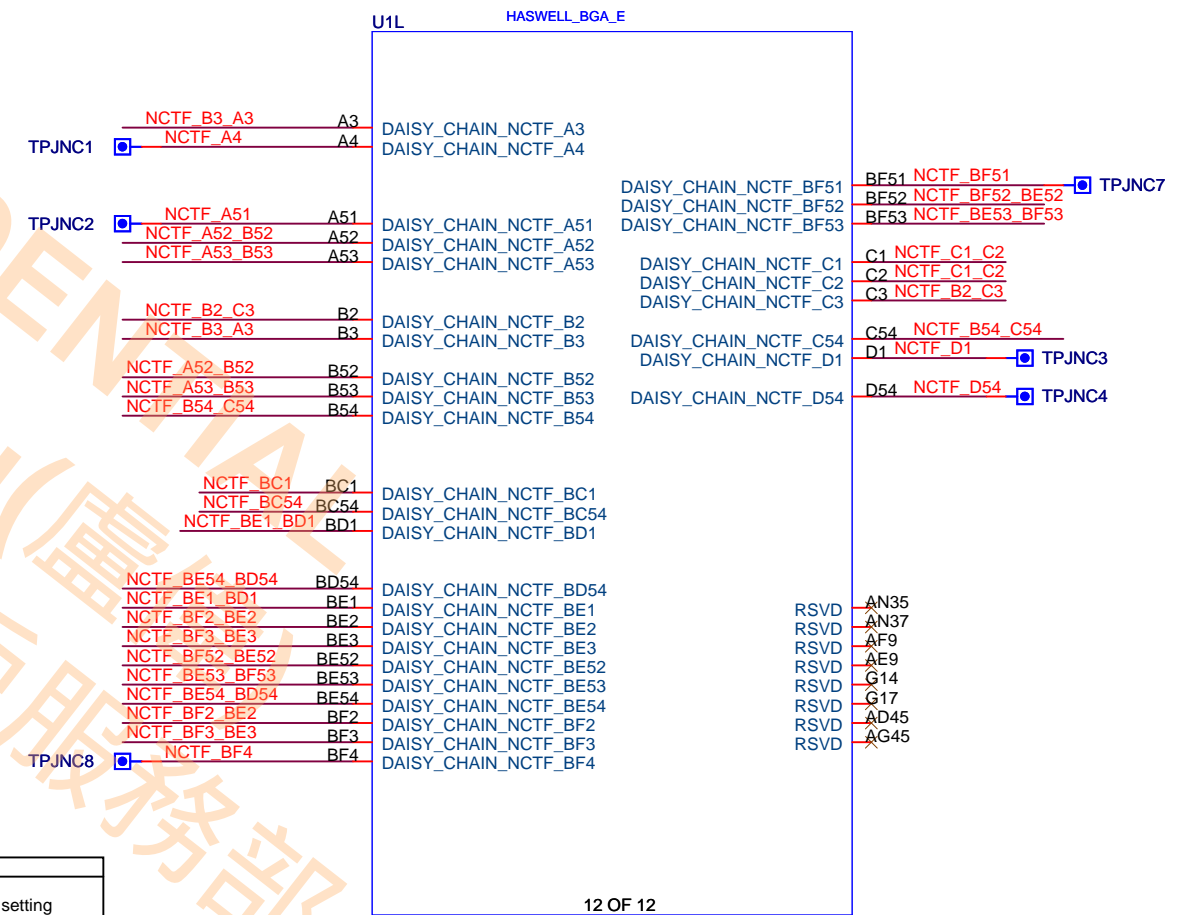
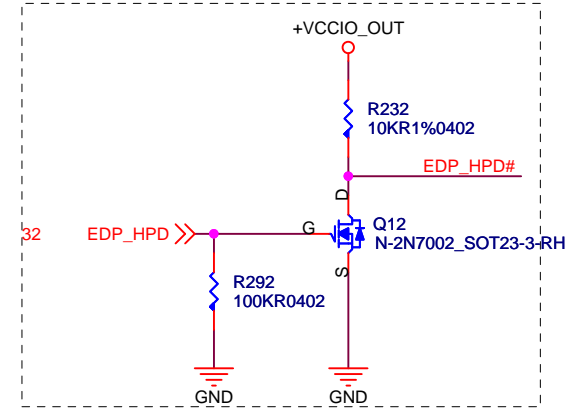
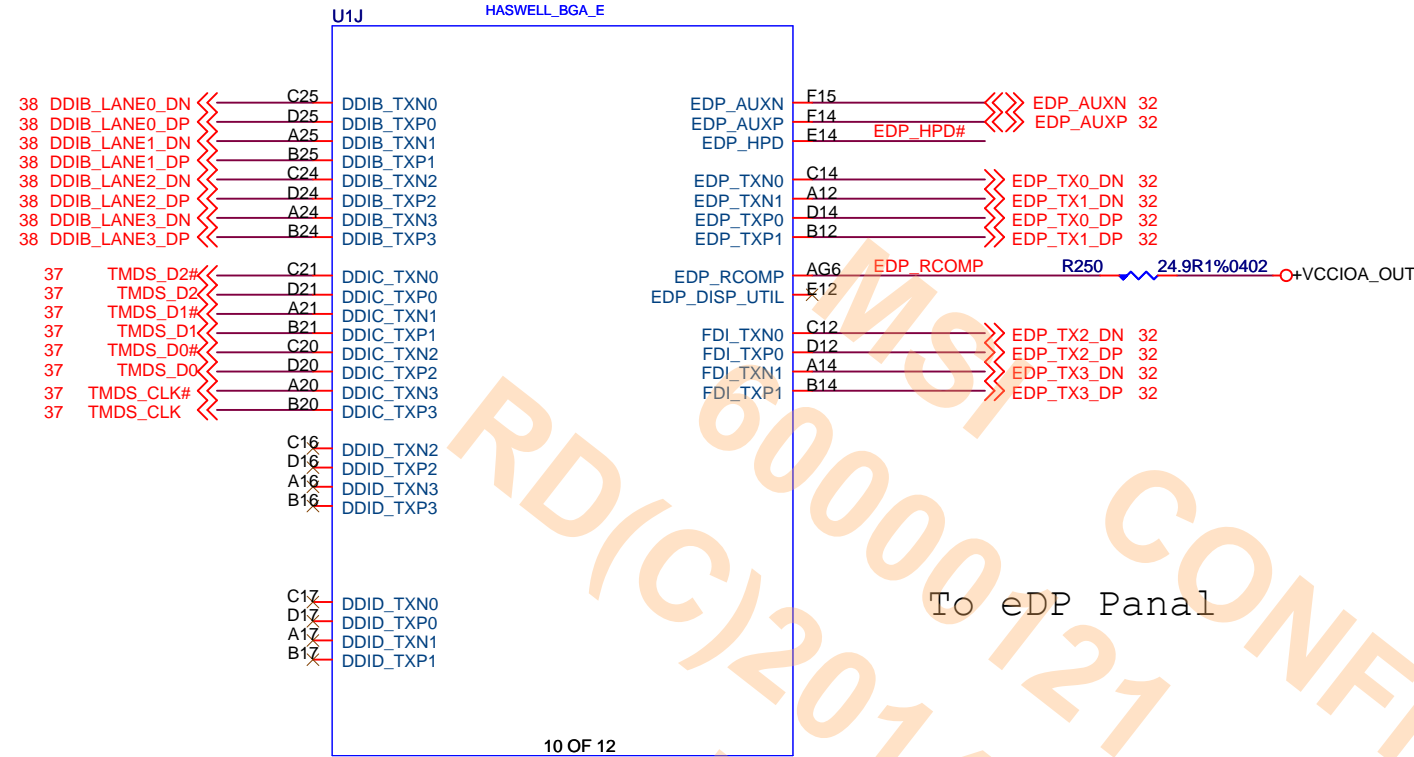
Haswell (DDR3L)



Display/Reserved

DP

HDMI



PCI Express* Static x16 Lane Numbering Reversal	
CFG2	1 = Normal operation 0 = Lane numbers reversed.

MSR Privacy Bit Feature	
CFG3	1 = Debug capability is determined by IA32_Debug_Interface_MSR (0xC80) bit[0] setting 0 = IA32_Debug_Interface_MSR (0xC80) bit[0] default setting overridden

eDP enable	
CFG4	1 = Disabled 0 = Enabled

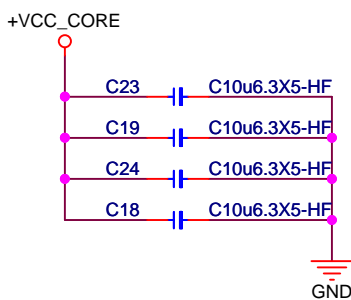
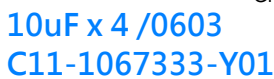
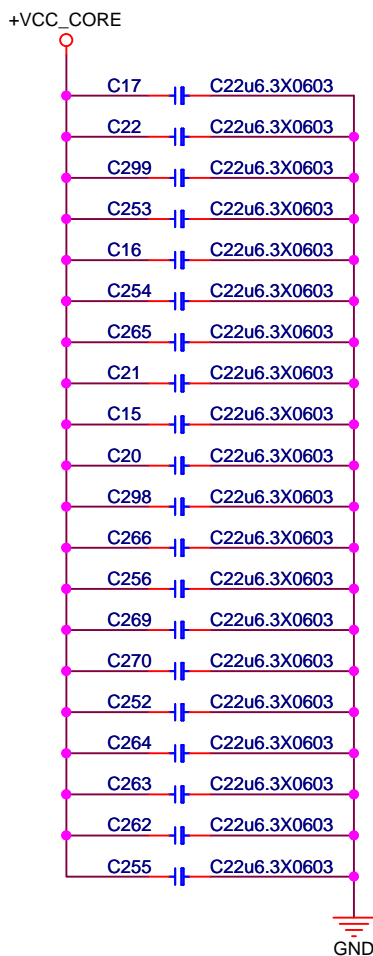
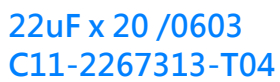
PCI Express* Bifurcation	
CFG[5:6]	00 = 1 x8, 2 x4 PCI Express 01 = reserved 10 = 2 x8 PCI Express 11 = 1 x16 PCI Express

PEG DEFER TRAINING	
CFG7	1: (Default) PEG Train immediately following xxRESETB de assertion 0: PEG Wait for BIOS for training

msi MICRO-STAR INT'L CO.,LTD.

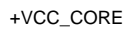
Title		
CPU-3 (Display/Reserved)		
Size	Document Number	Rev
	MS-16H3	1.0
Date:	Wednesday, June 25, 2014	Sheet 5 of 69

Haswell (POWER)

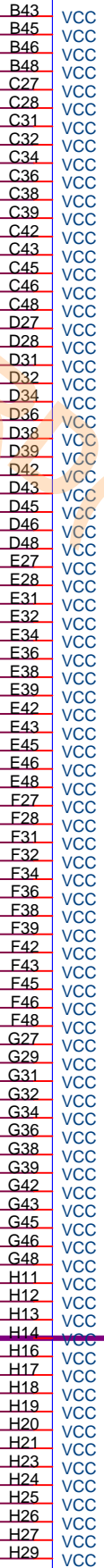


	Haswell	Boardwell
R231	No Stuff	Stuff
C284	No Stuff	Stuff
C271	No Stuff	Stuff
R12	No Stuff	Stuff
R11	No Stuff	Stuff

2014.2.20 Modify for Haswell CPU

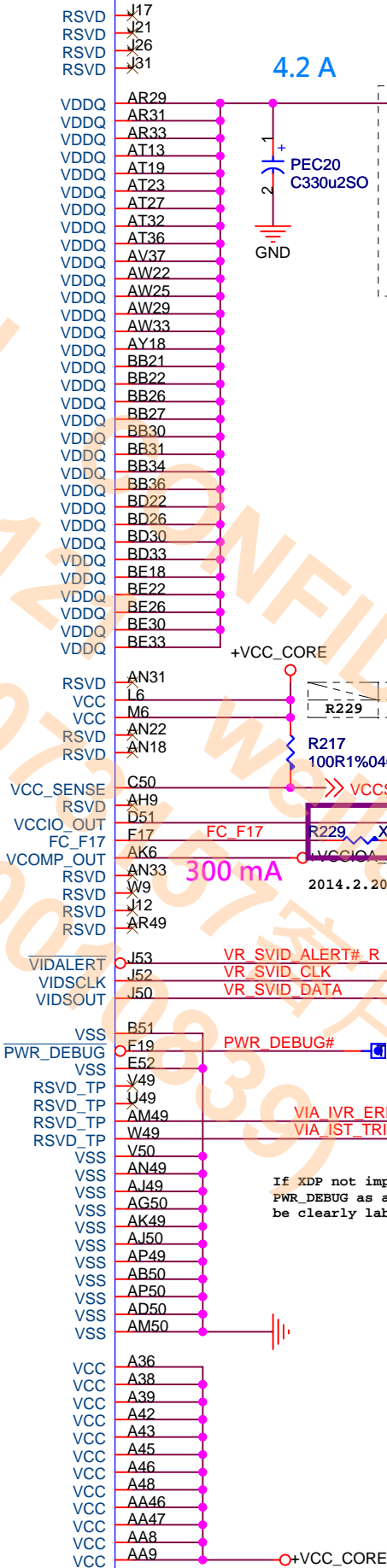


95A

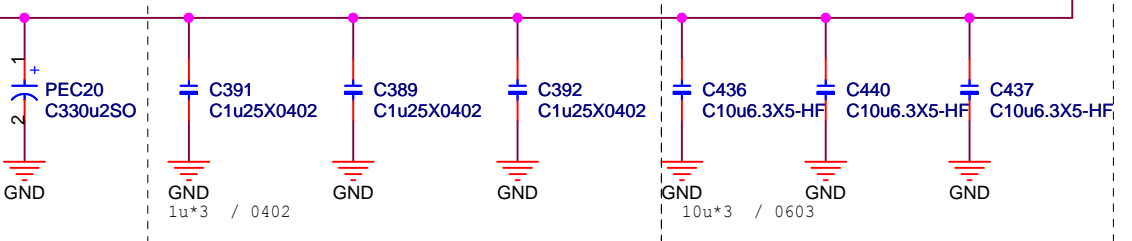


HASWELL_BGA_E

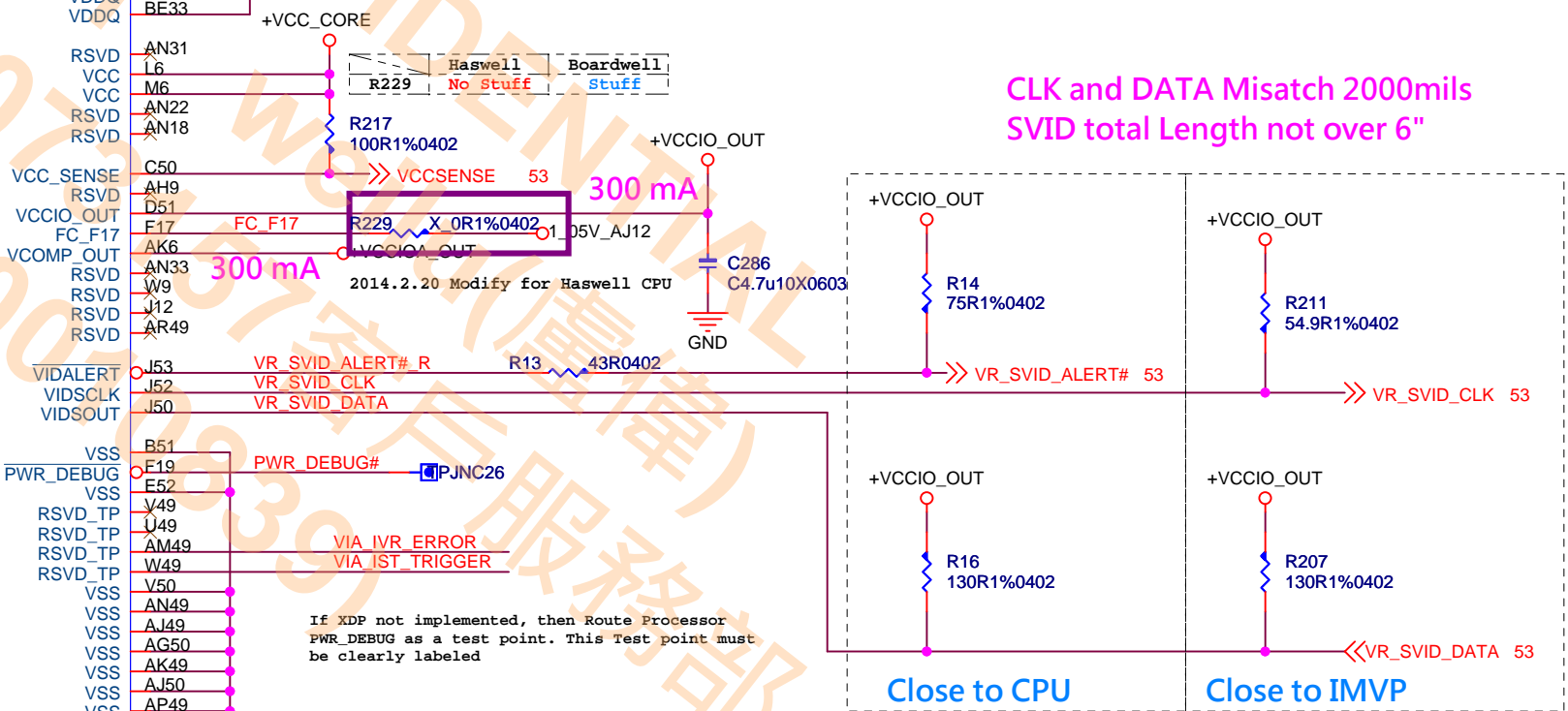
U1E



4.2 A

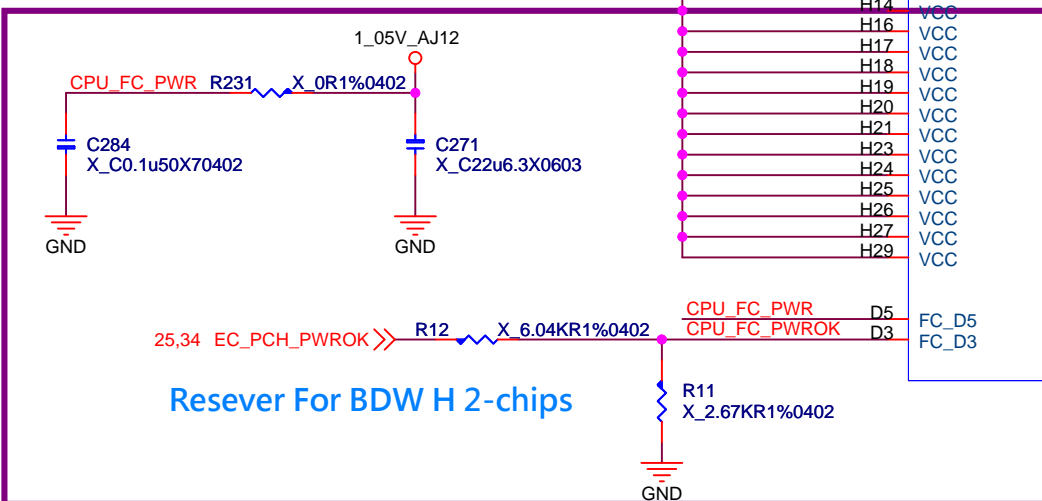


CLK and DATA Misatch 2000mils
SVID total Length not over 6"



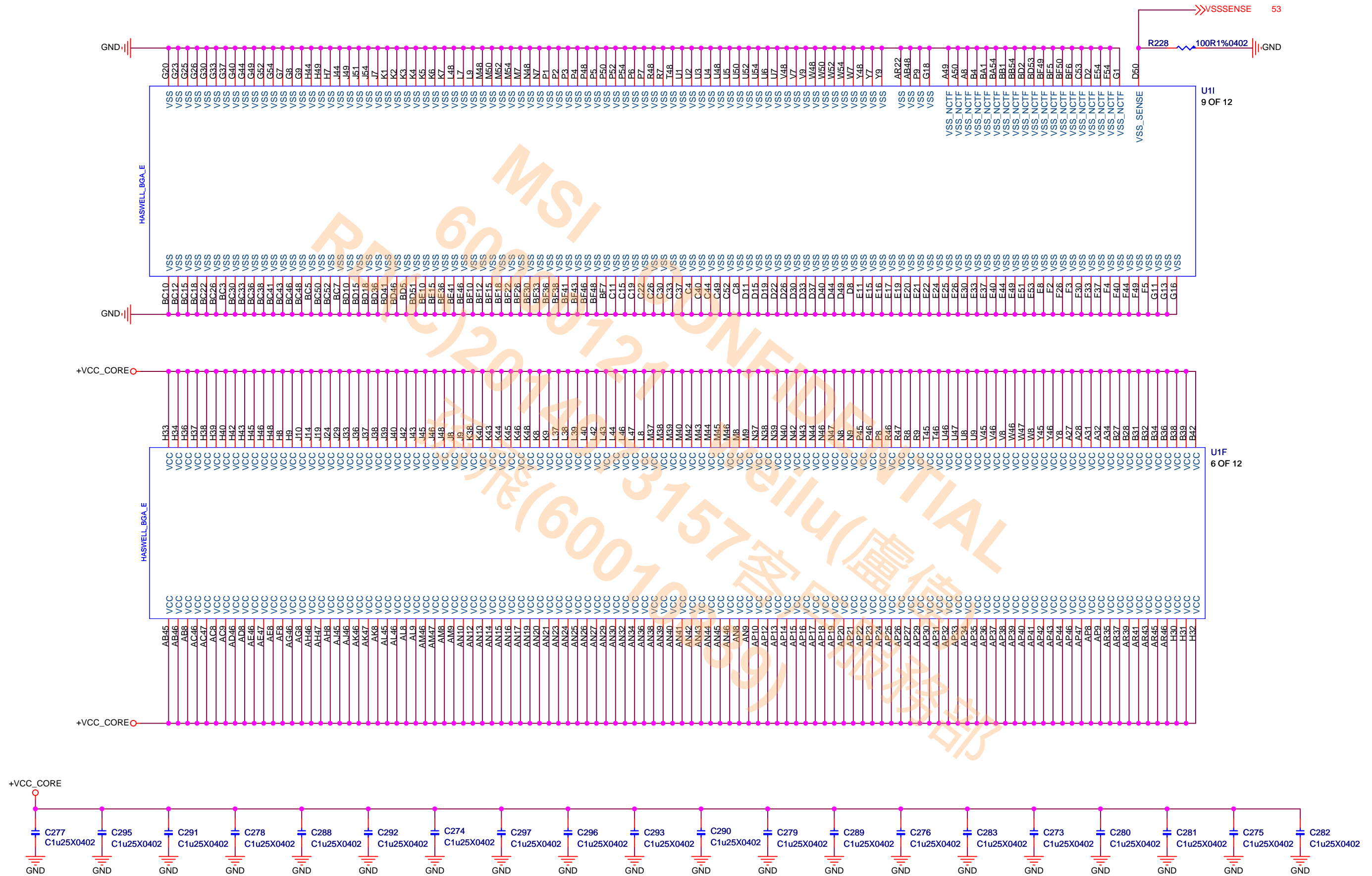
Close to CPU

Close to IMVP

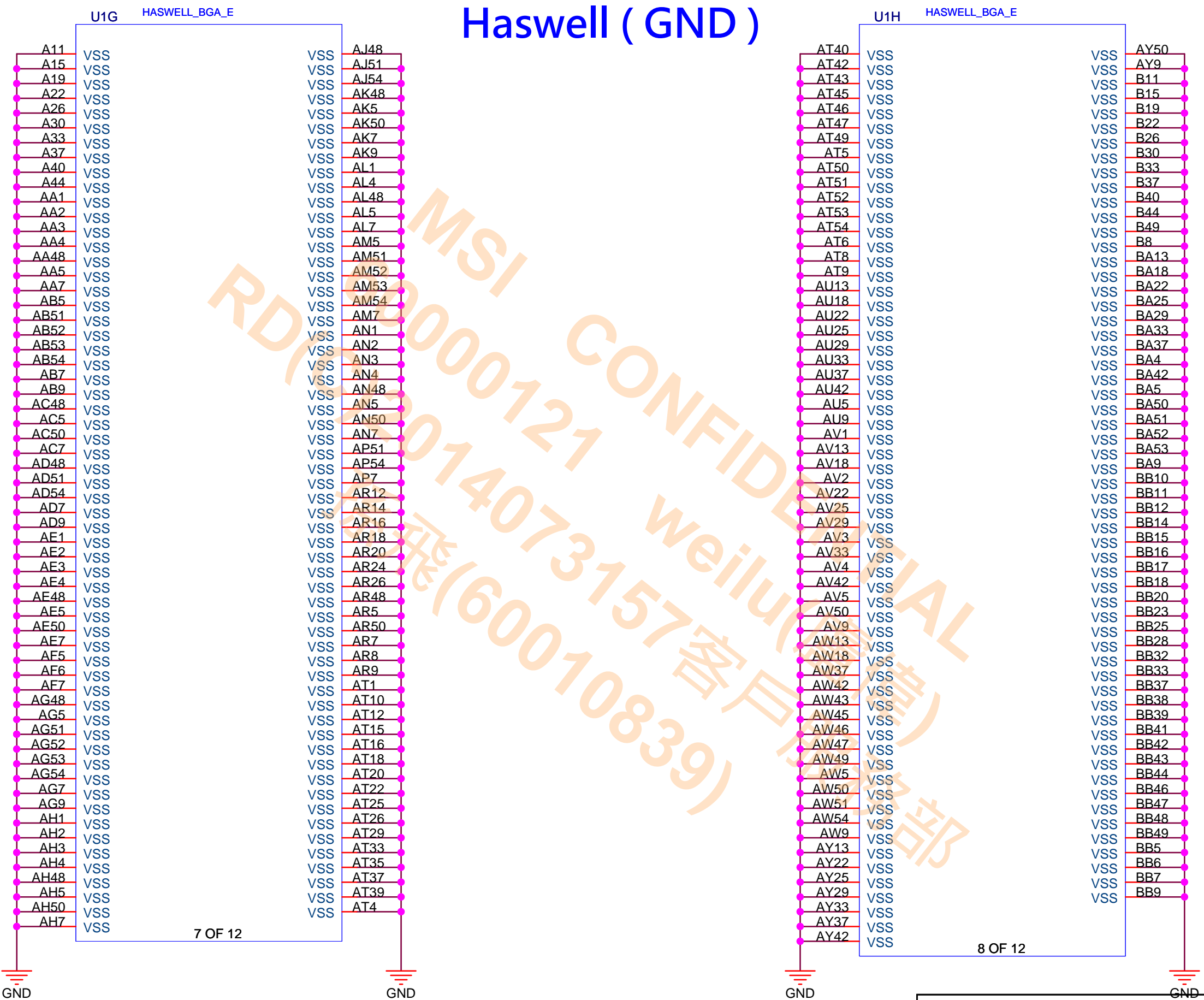


Resever For BDW H 2-chips

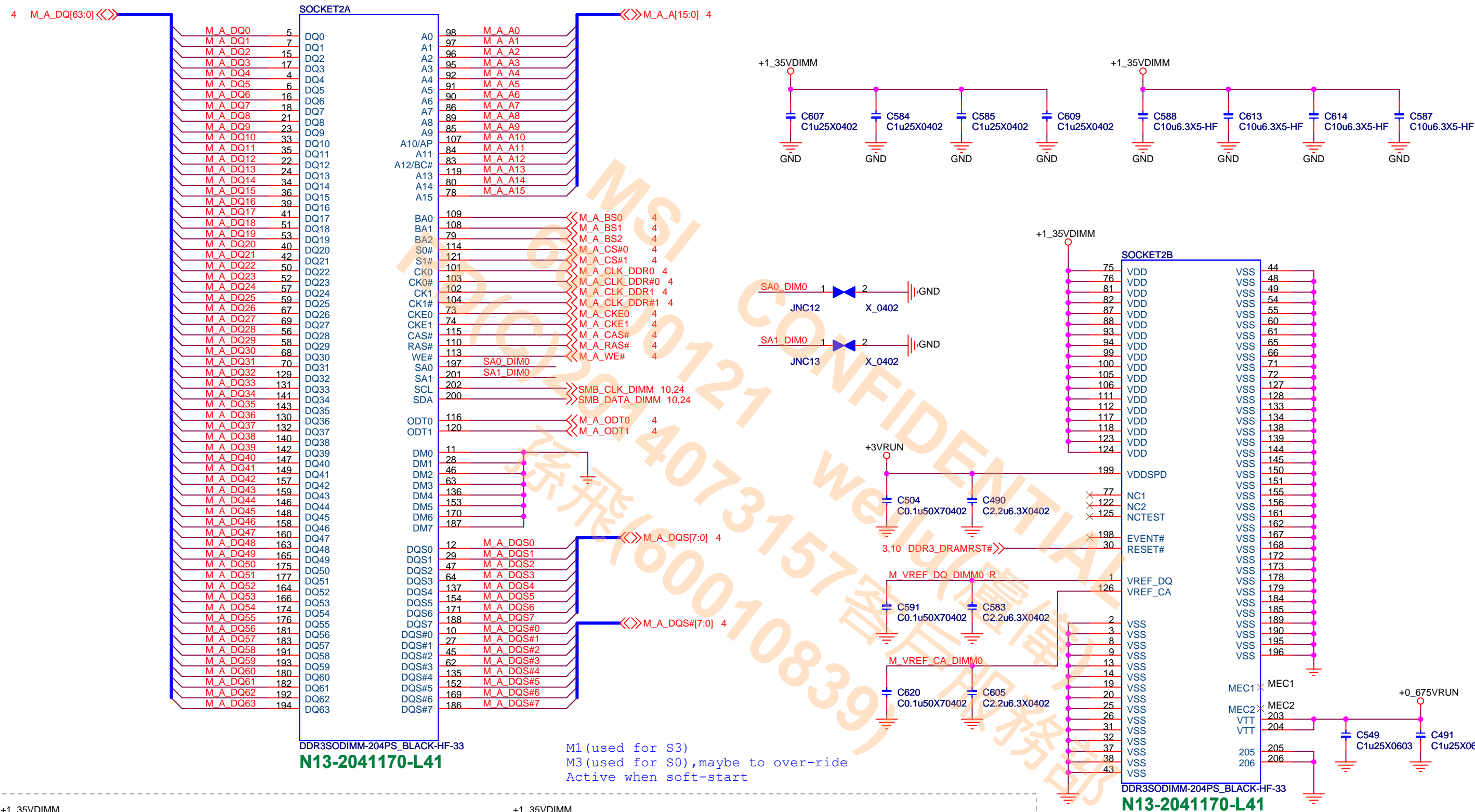
Haswell (Power & GND)



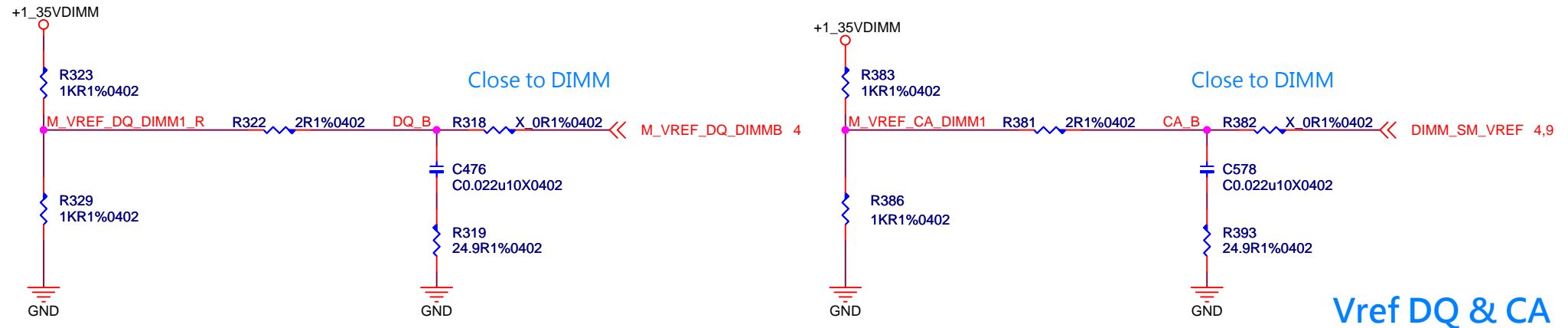
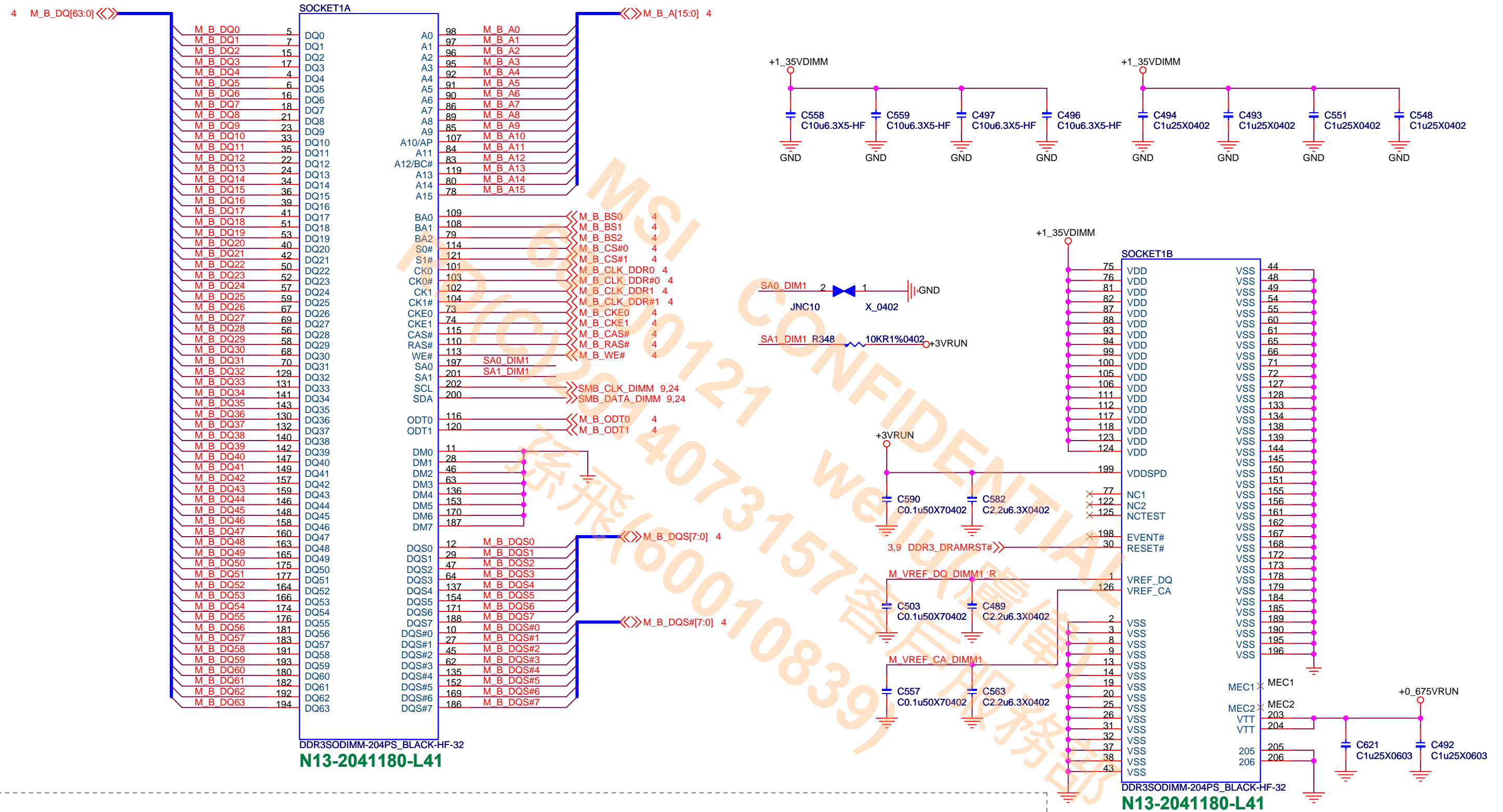
Haswell (GND)

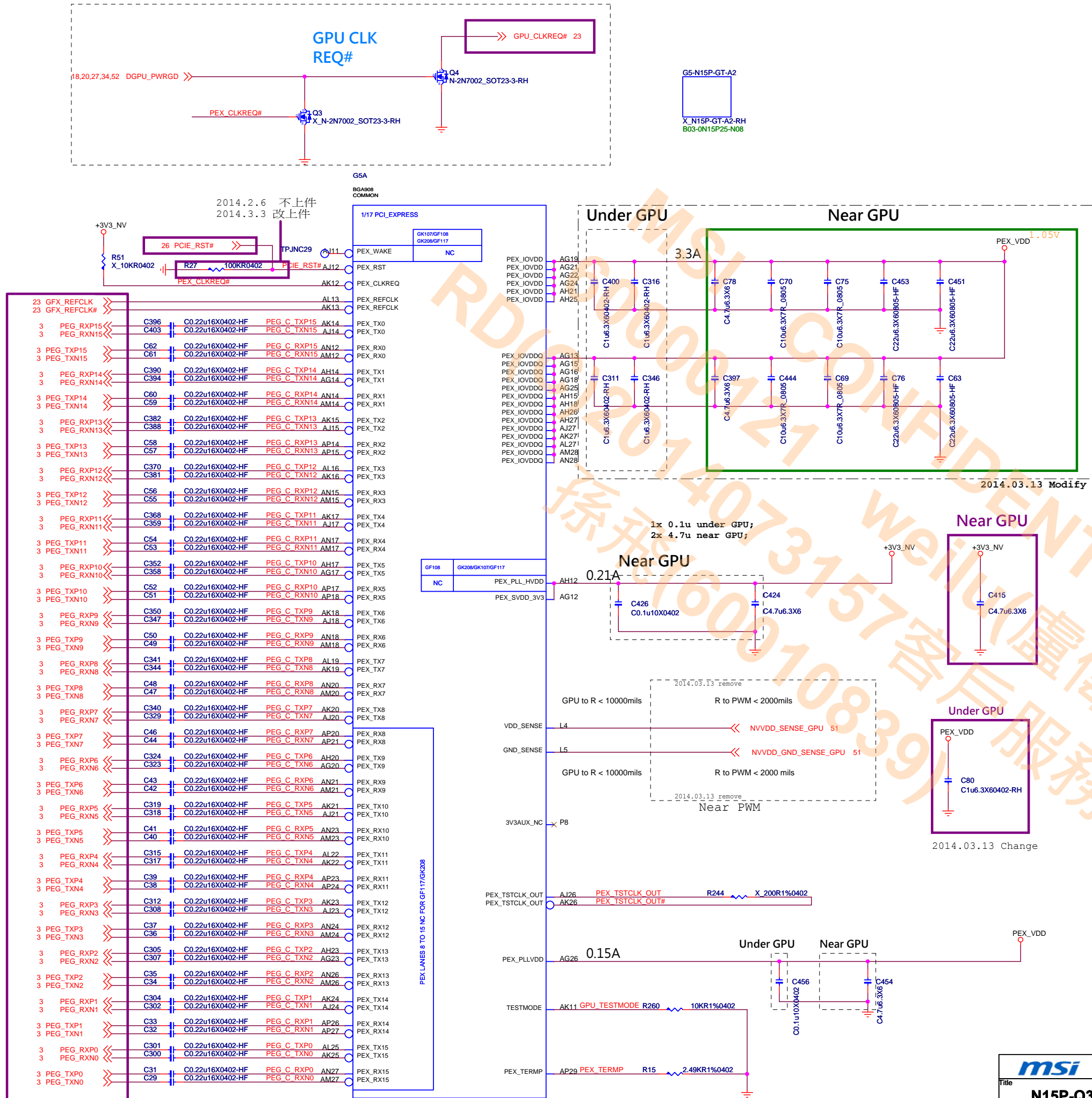


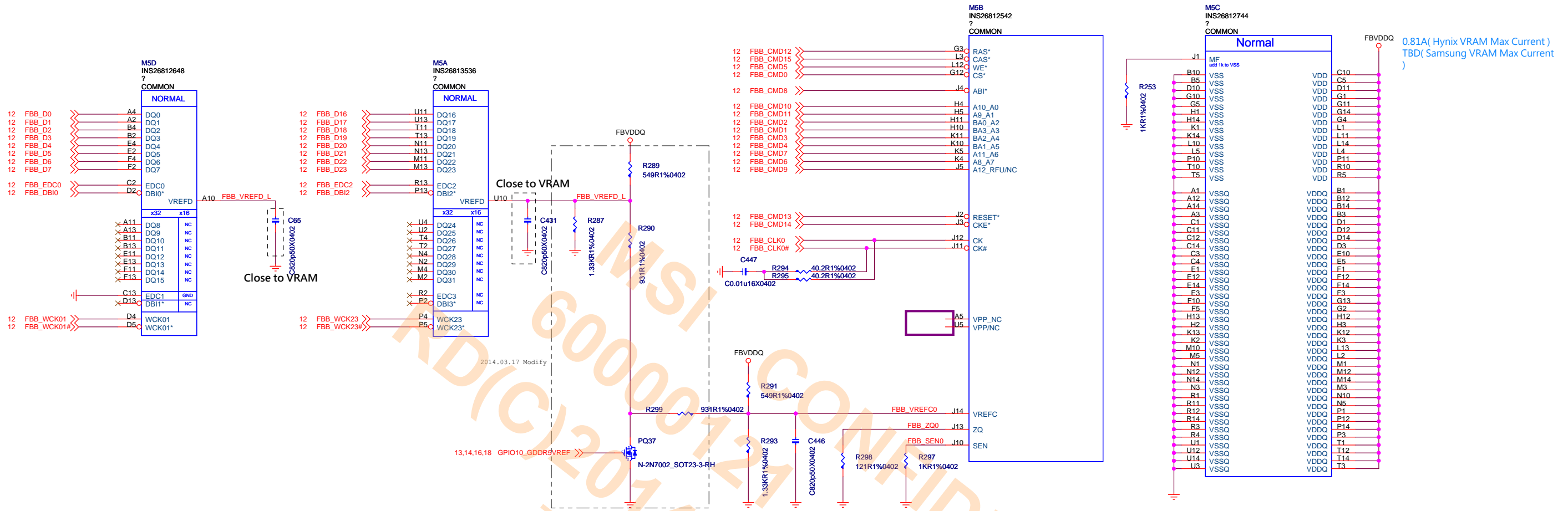
SODIMM#A



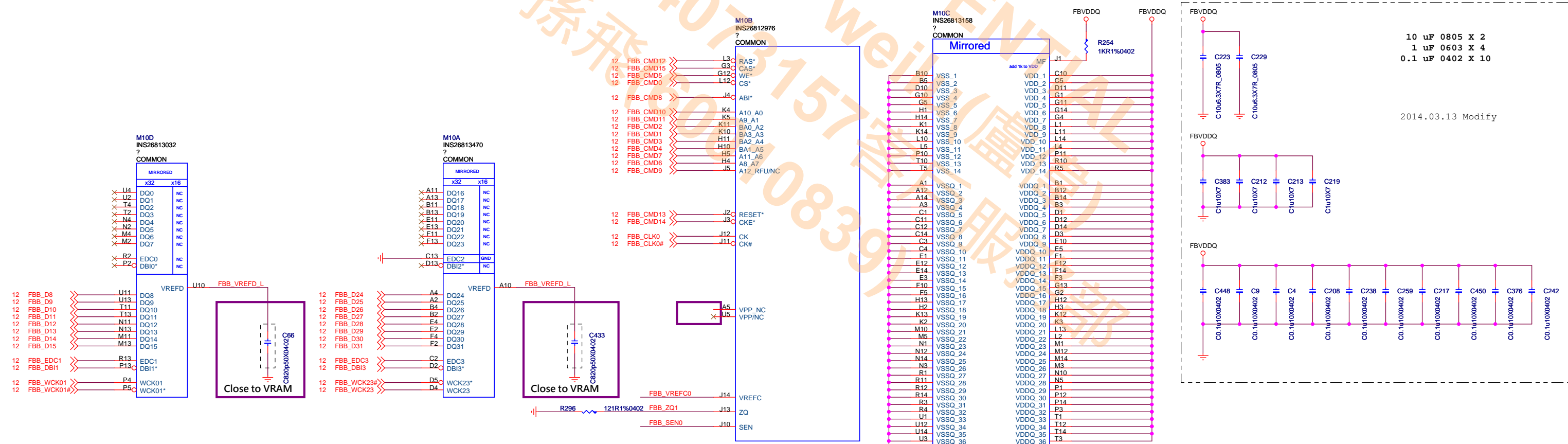
SODIMM#B







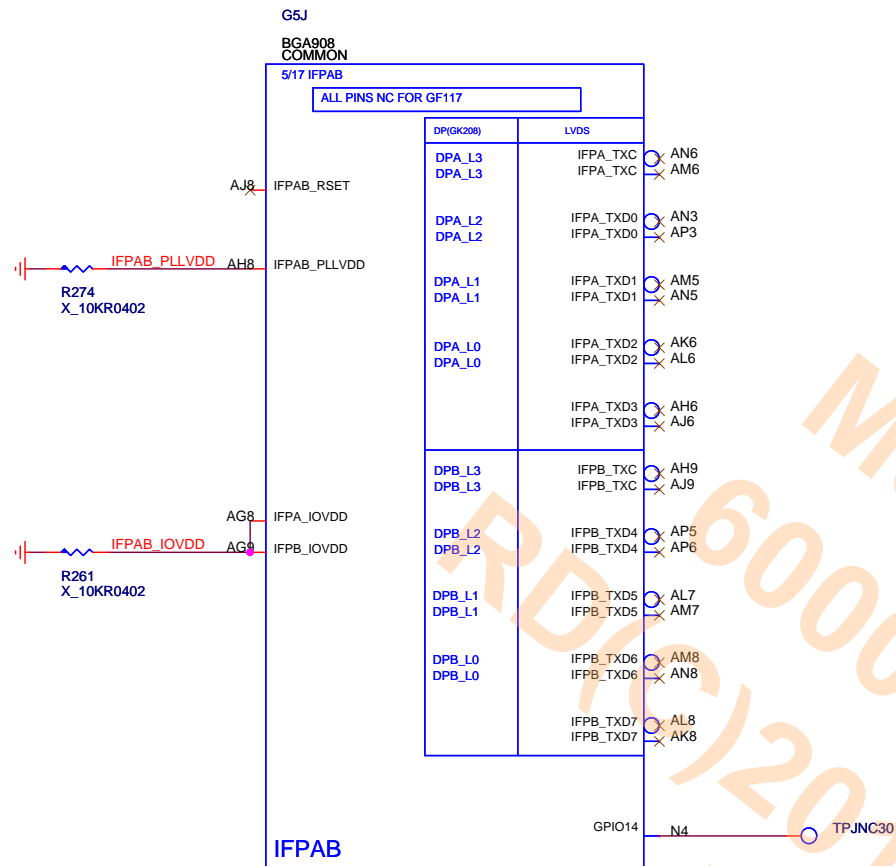
0.81A (Hynix VRAM Max Current)
TBD (Samsung VRAM Max Current)



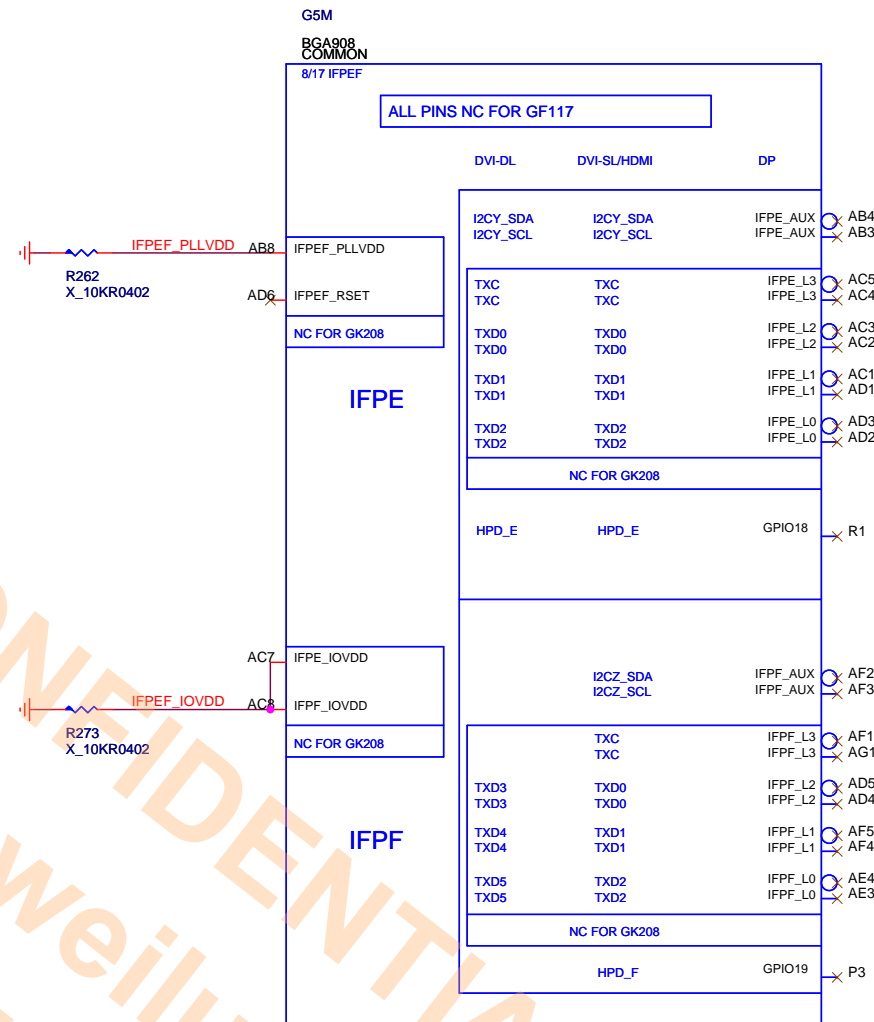
10 uF 0805 X 2
1 uF 0603 X 4
0.1 uF 0402 X 10

2014.03.13 Modify

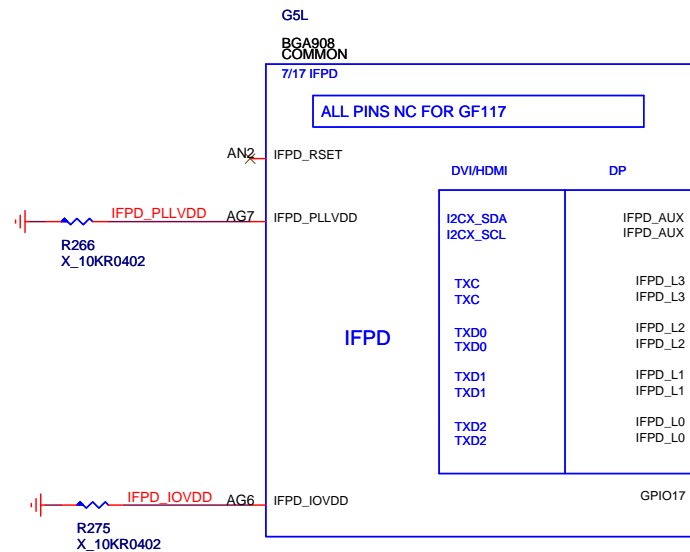
IFP A/B LVDSDual Link



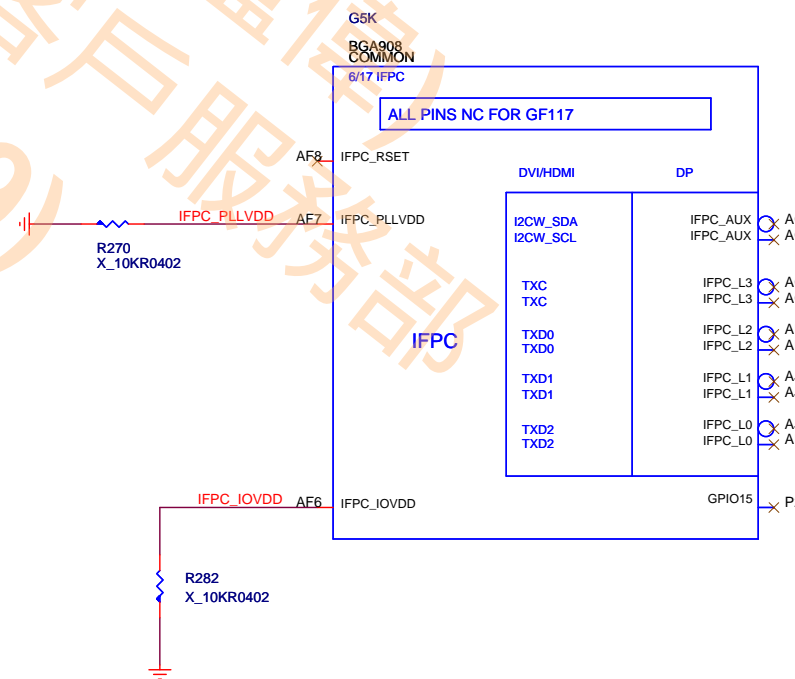
IFP E/F Dual Link TMDS DVI-I



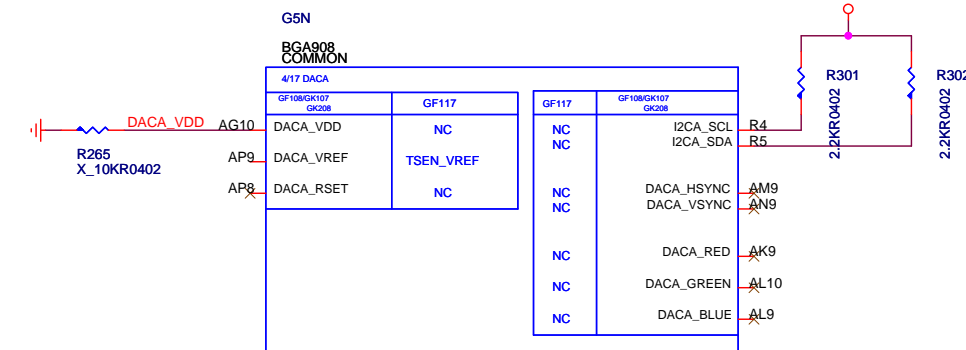
IFP D Dual Mode DP



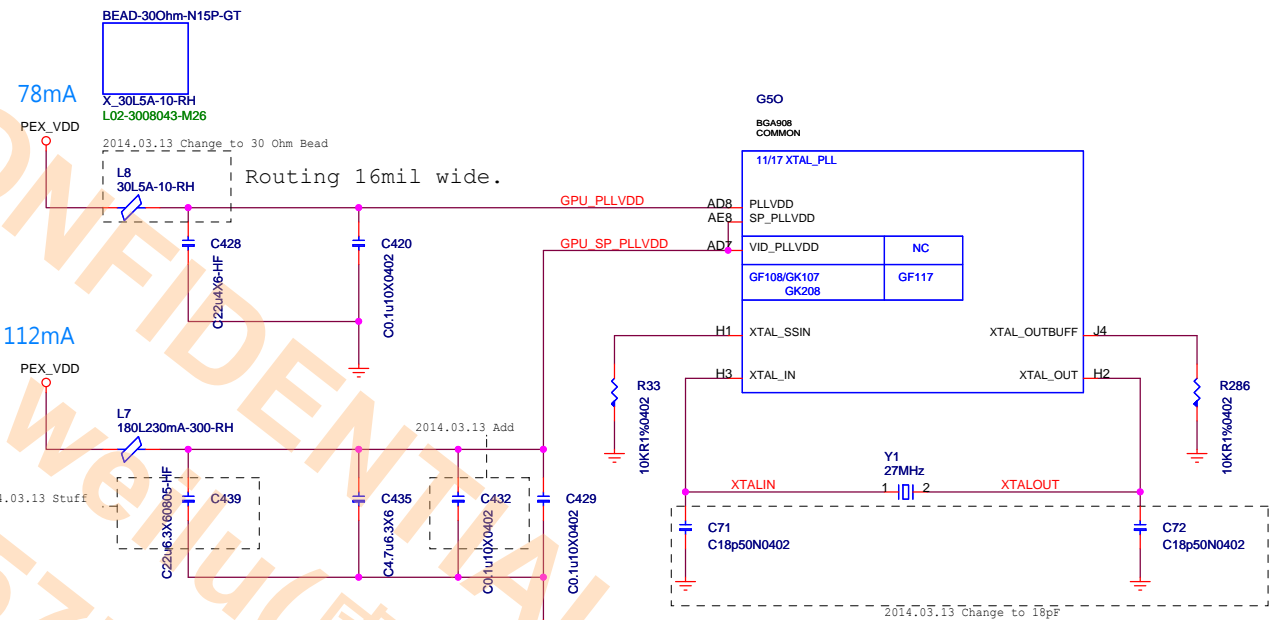
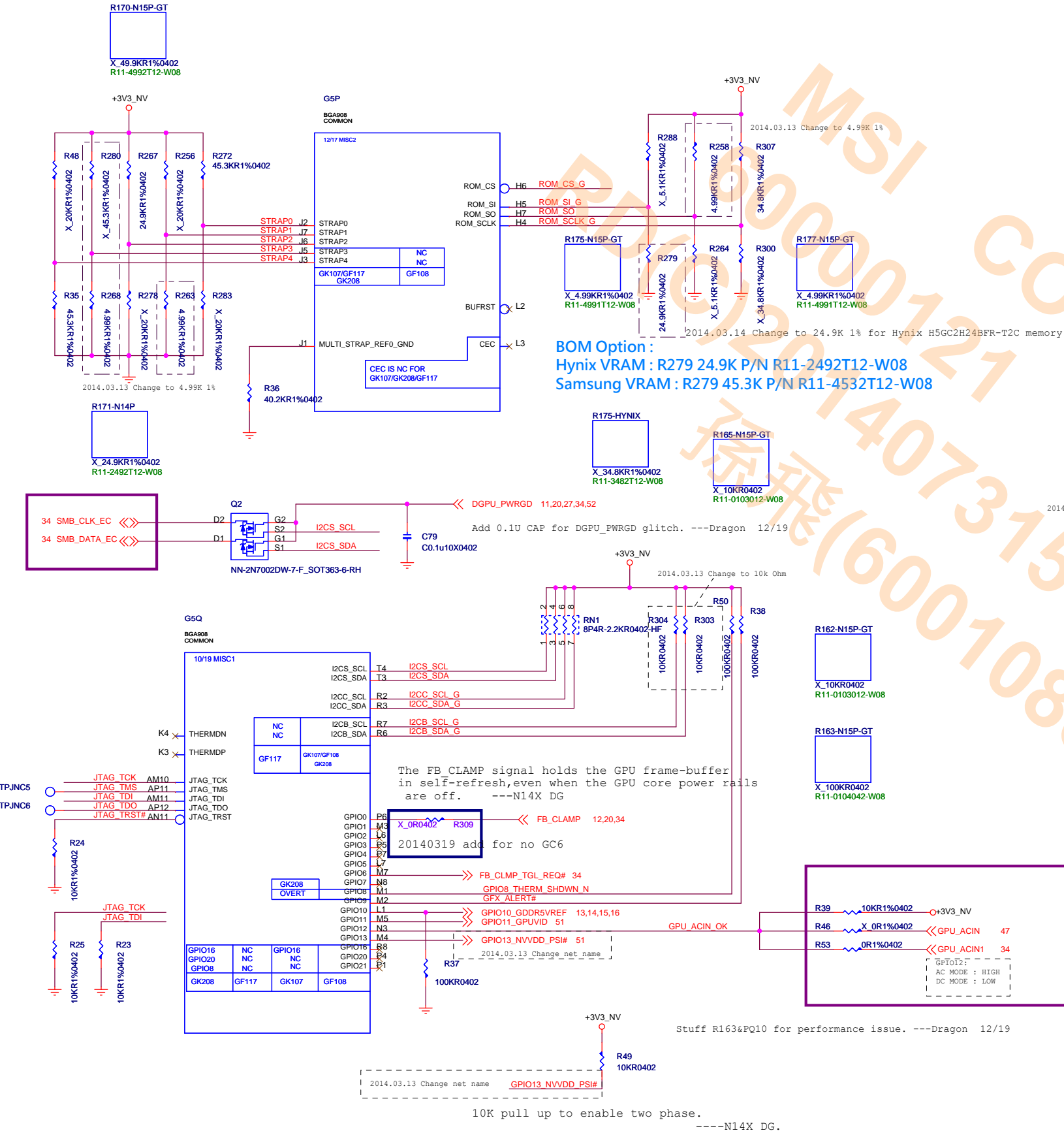
IFP C Native HDMI OR DP



DAC A VGA



Item	Location	N15P-Q3
Strap Mode	R3365	MULTISTRAP_REF_GND, 40.2K PD to GND
Device ID		0x11FC
Package		GB4-128
Memory Type		GDDR5
ROM_SI	R3175	0x4, Hynix 2G, 24.9kohm PD
	R3175	0x7, Samsung 2G, 45kohm PD
ROM_SO	R3193	0x8, 5kohm pull up
ROM_SCLK	R3179	0x1110, 35kohm PU(with ROM)
Strap0	R3170	45kohm pull up
Strap1	R3180	5kohm pull down
Strap2	R3171	DID, 0x1100, 24.9kohm PU
Strap3	R3188	0x0 for Optimus, 5kohm pull down
Strap4	R3183	0x0111, 45kohm pull down



Pin Name	Normal function	I/O	Functional Description	Recommended Default Pull-up or Pull-down
GPIO0	FB_CLAMP_MON	I	FB Clamp monitor	
GPIO1	NC	O		
GPIO2	NC	O		
GPIO3	NC	O		
GPIO4	NC	O		
GPIO5	NC	O		
GPIO6	FB_CLAMP_TGL_REQ	O	FB Clamp toggle request	
GPIO7	NC	O		
GPIO8	OVERT	I	Thermal Over Temperature	100K pull-up
GPIO9	ALERT	I/O	Active Low Thermal Alert	100K pull-up
GPIO10	MEM_VREF_CTL	O	Memory VREF Control	100K pull-down
GPIO11	PWM_VID	O	GPU Core VDD PWM control signal	
GPIO12	PWR_LEVEL	I	AC power detect	100K pull-up
GPIO13	SPI	O	Phase Shedding	10K pull-up
GPIO14	NC	I		
GPIO15	NC	I		
GPIO16	NC	O		
GPIO17	NC	I		
GPIO18	NC	I		
GPIO19	NC	I		
NC	NC			

2014.03.18 Modify

Near GPU

Near GPU

Under GPU

Near GPU

Near GPU

Under GPU

(Voltage range:0.7125~1.15V)

G5H

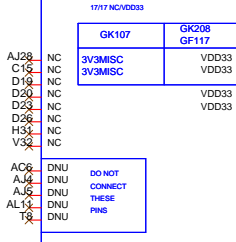
G5F

45A(at TDP)

G5E

BGAG08

COMMON



Under GPU

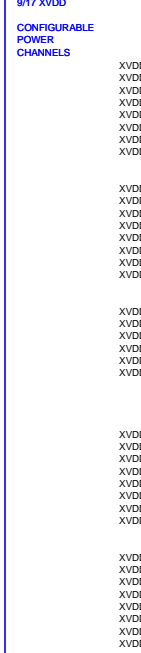
Near GPU

Design guide suggest:
4x 0.1u under GPU;
1x 1u near GPU;
1x 4.7u near GPU;

G5I

BGAG08

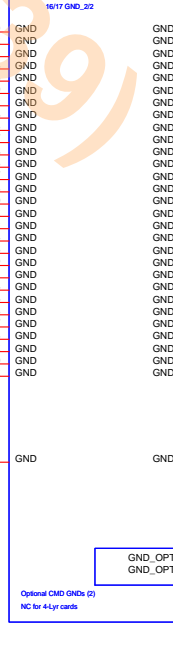
COMMON



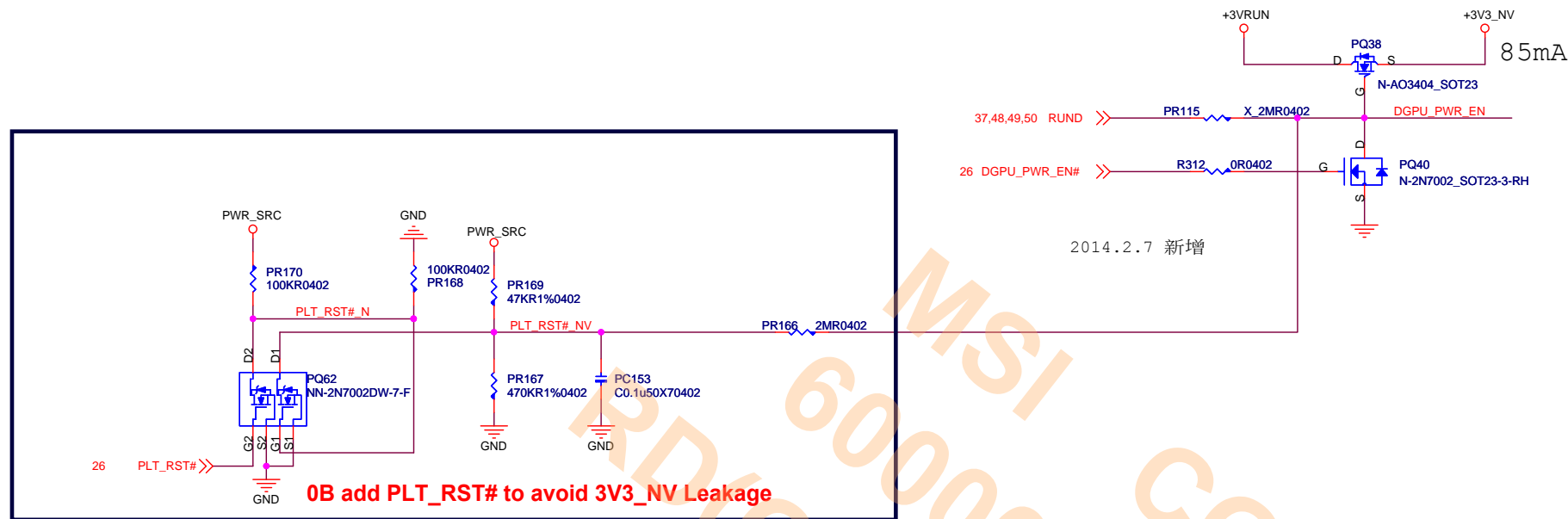
G5G

BGAG08

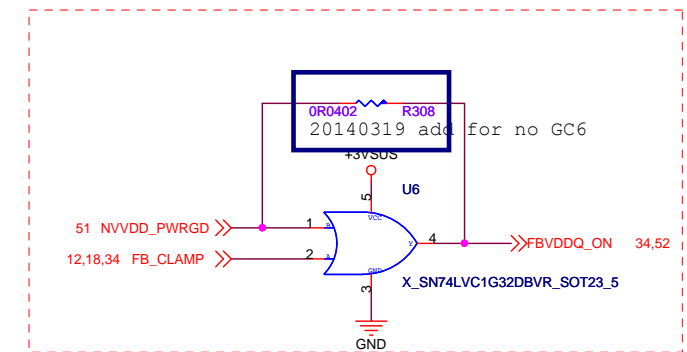
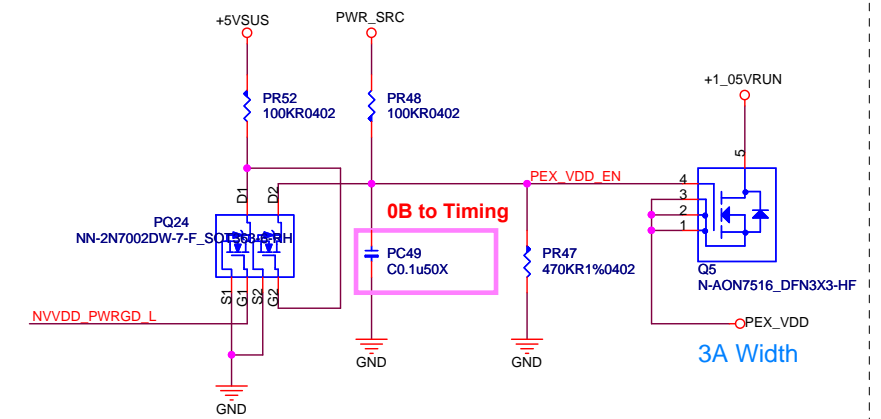
COMMON



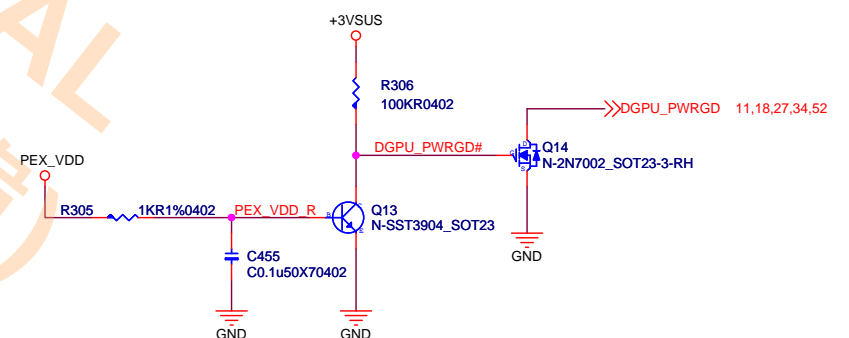
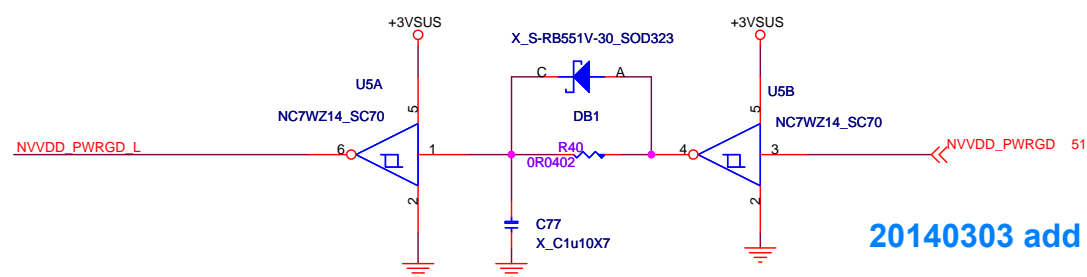
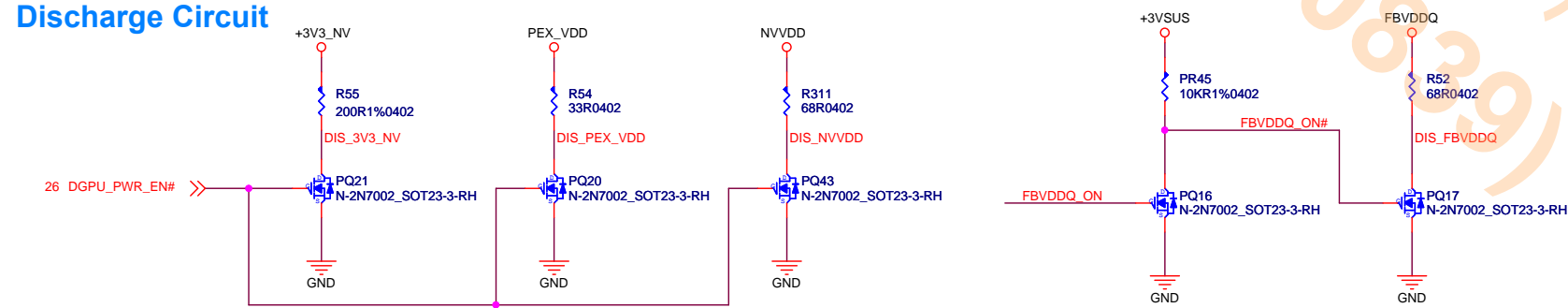
DGPU_Power Control



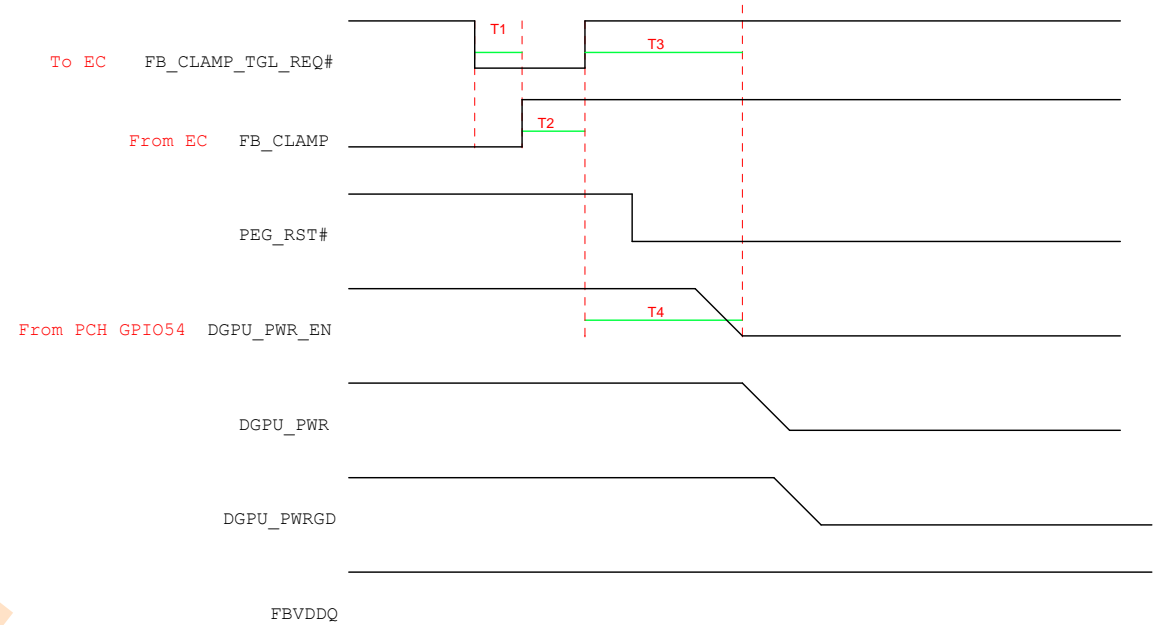
PEX_VDD



Discharge Circuit



GC6 ENTRY SEQUENCE (NOT support)



NOTES: For optimus system, VDD33 usually drops down earlier than NVVDD and FBVDDQ.

NOTES: All rails must be powered off within 10 ms from the first rail powering off.


GC6 EXIT SEQUENCE

The diagram shows the timing relationship between several signals during an FB clamp request sequence. The signals are:

- From PCH GPIO54**: A signal that transitions from low to high.
- DGPU_PWR_EN**: A signal that transitions from low to high.
- GPU_PWR**: A signal that transitions from low to high.
- FBVDDQ**: A signal that transitions from low to high.
- DGPU_PWRGD**: A signal that transitions from low to high.
- PEG_RST#**: A signal that transitions from high to low.
- To EC**: A signal that transitions from high to low.
- From EC**: A signal that transitions from high to low.

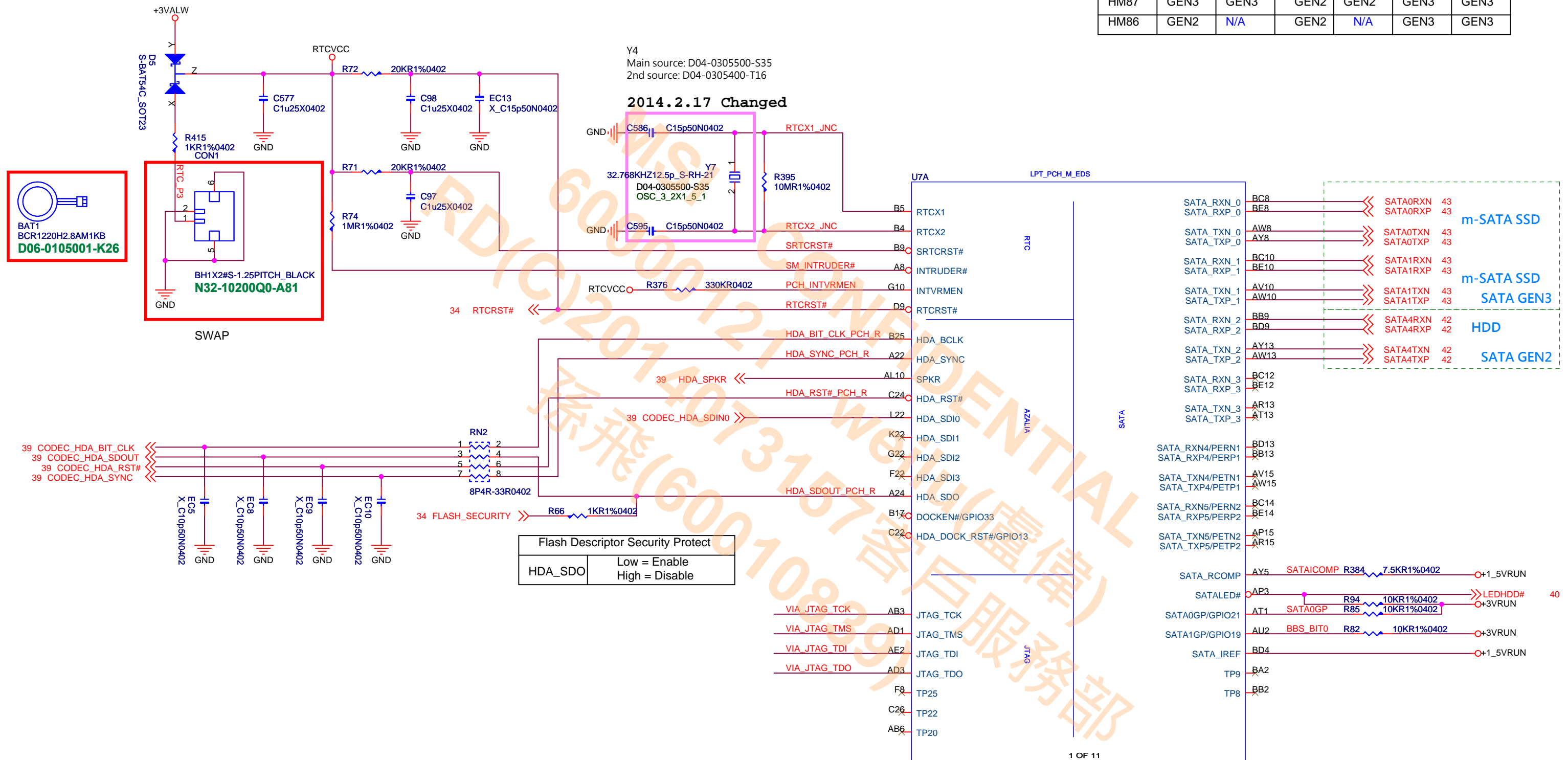
The timing sequence is as follows:

- T5**: The time from the rising edge of **DGPU_PWRGD** to the rising edge of **FBVDDQ**.
- T6**: The time from the rising edge of **FBVDDQ** to the rising edge of **FB_CLAMP**.
- T7**: The time from the rising edge of **FB_CLAMP** to the rising edge of **FBVDDQ**.
- T8**: The time from the rising edge of **FB_CLAMP** to the rising edge of **FBVDDQ**.
- T9**: The time from the rising edge of **FBVDDQ** to the rising edge of **FBVDDQ**.

		MICRO-STAR INT'L CO.,LTD.	
Title			
N15P-Q3 Power Sequence			
Size	Document Number		Rev
	MS-16H3		1.0
Date:	Wednesday, June 25, 2014	Sheet	21 of 69

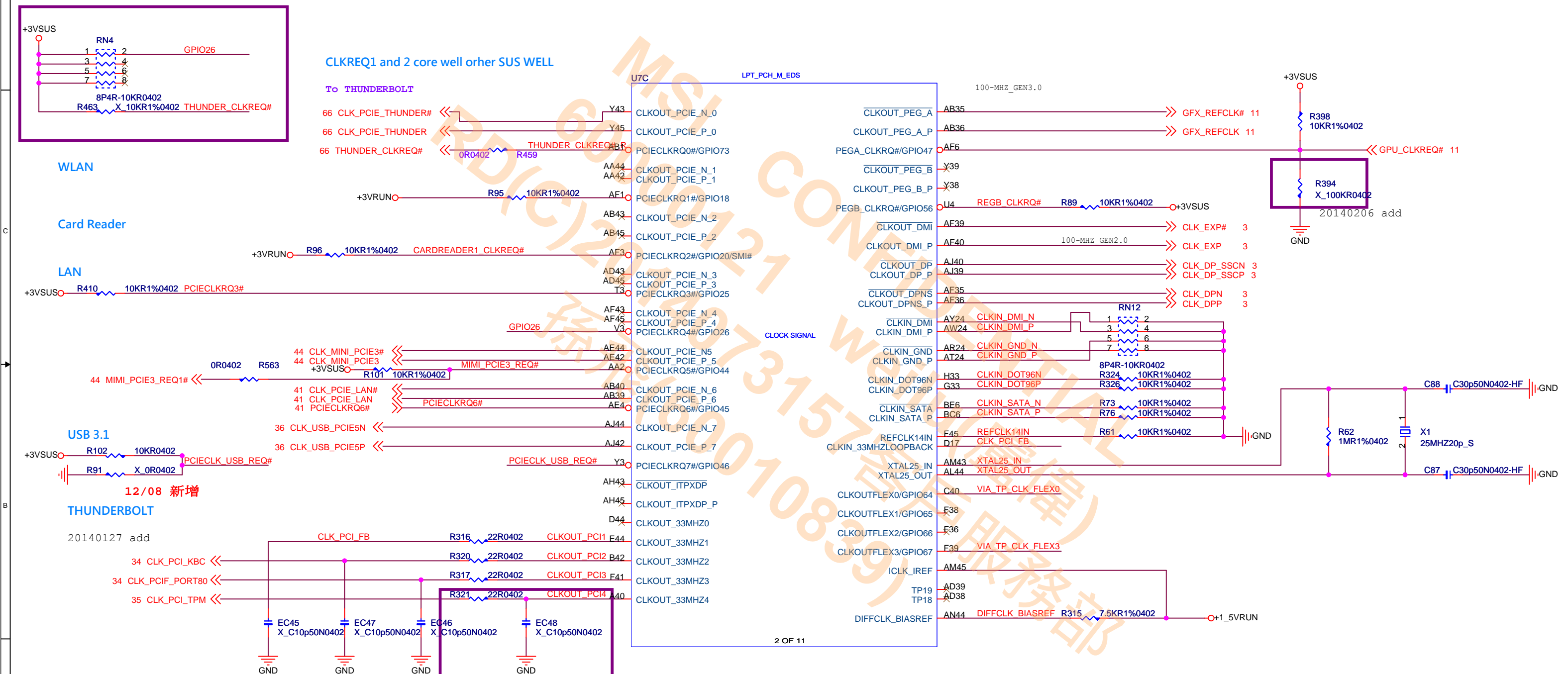
Lynx Point (HDA/JTAG/SATA)

SKU	High Speed SATA I/O Ports					
	SATA-0	SATA-1	SATA-2	SATA-3	SATA-4	SATA-5
HM87	GEN3	GEN3	GEN2	GEN2	GEN3	GEN3
HM86	GEN2	N/A	GEN2	N/A	GEN3	GEN3



Lynx Point (Clock)

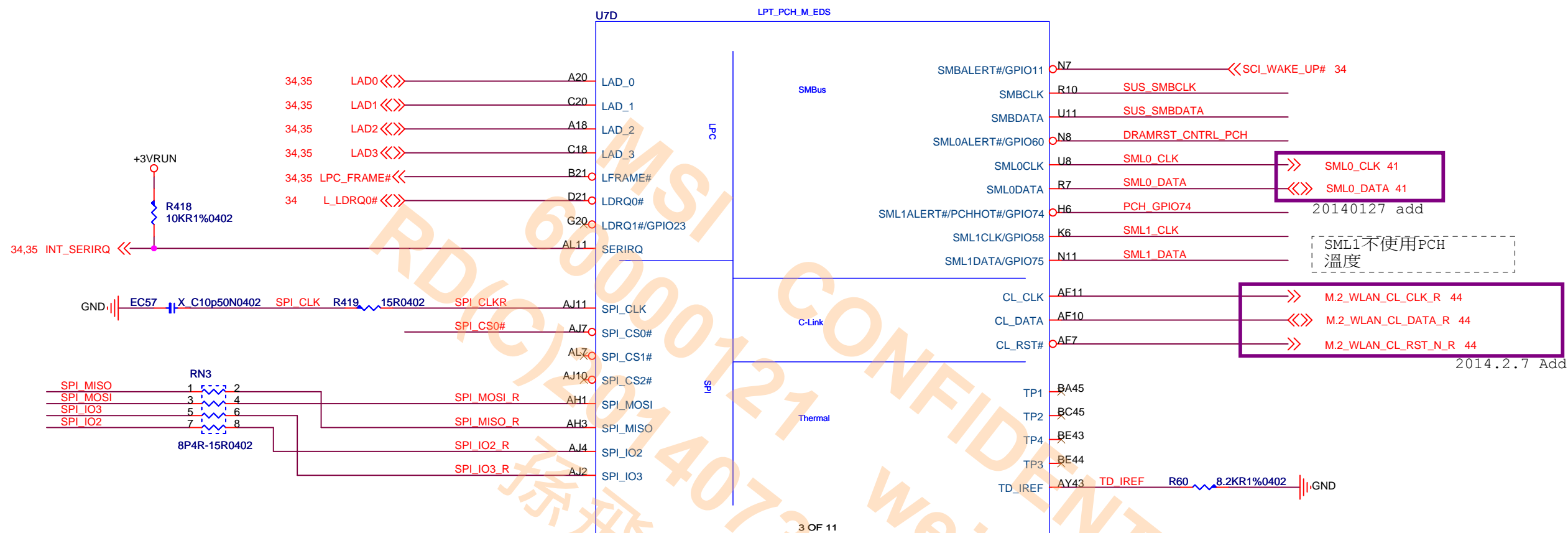
PCIe devices or addin cards that do NOT support CLKREQ# functionality should not route this signal to PCH. Intel recommends terminating PCIECLKREQ# pin on PCH with 10 k Ω \pm 10% external pull-up resistor instead of No Connect. Only PCIECLKREQ[2:1]# on PCH are core well powered. All other PCIECLKREQ# are suspend well powered.



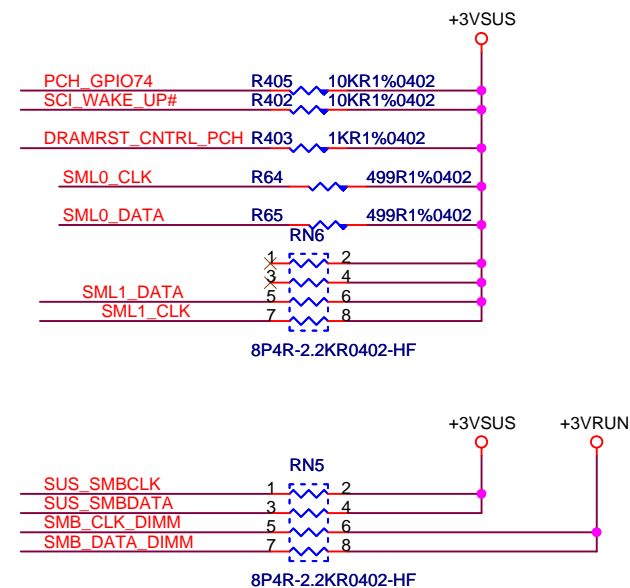
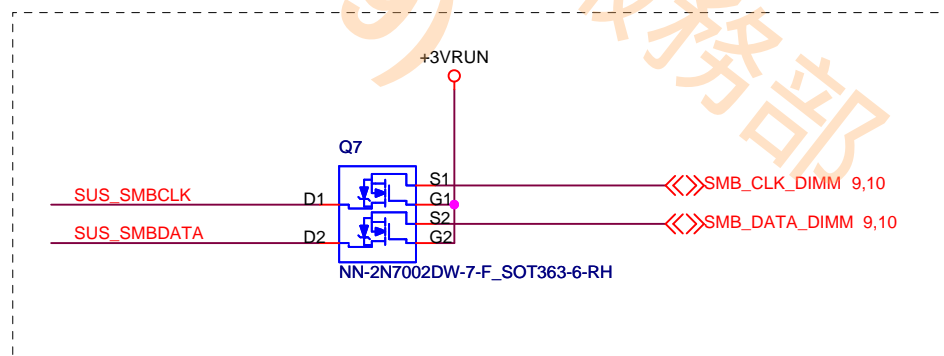
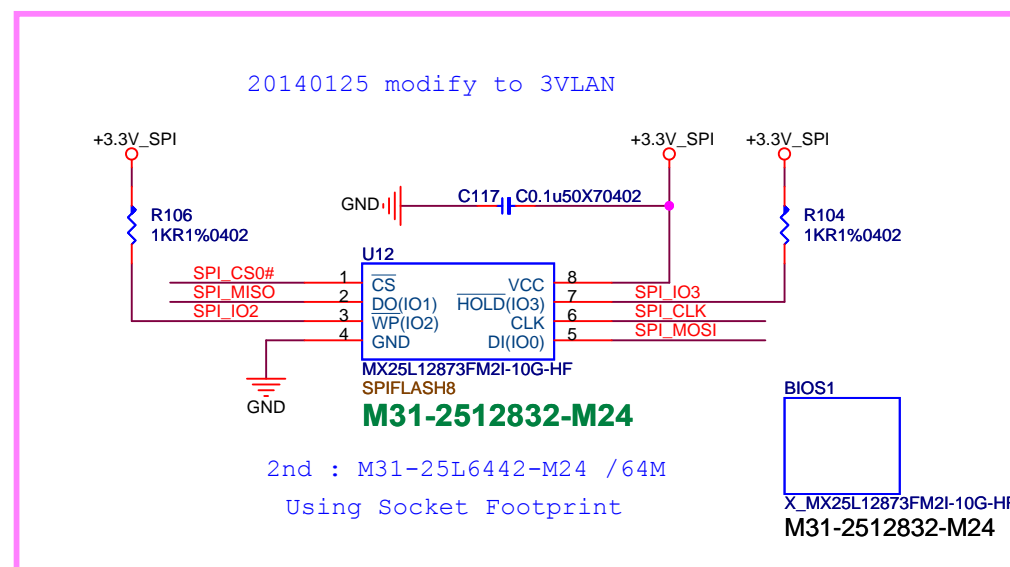
2014.2.17 Add

The CLKREQ# function can be disabled via intel management engine FW .Please refer to INTEL ME FW Bring up guide for configuring/disabling CLKREQ#

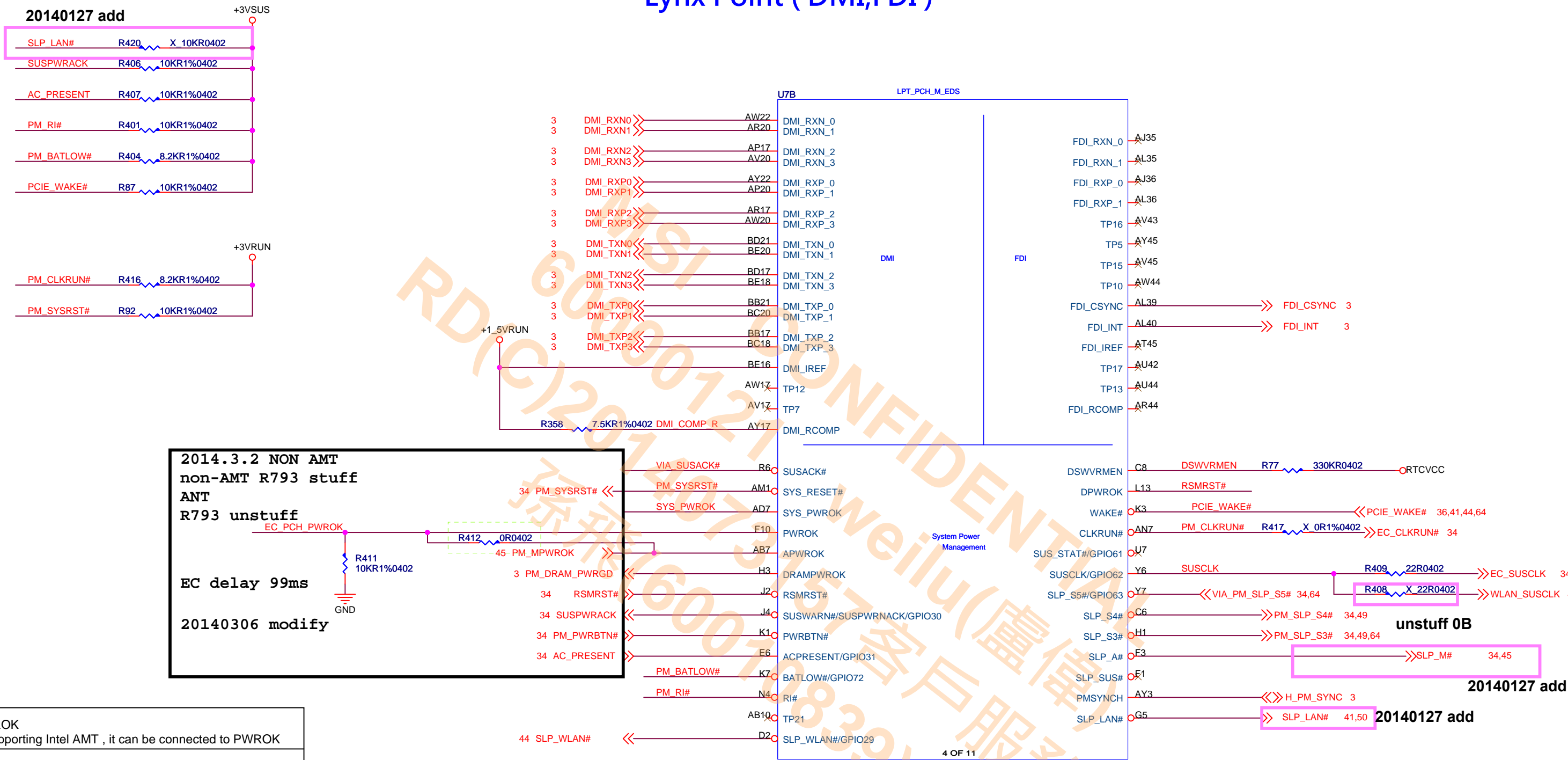
Lynx Point (LPC,SMBUS)



20140310 0A先上socket,N14-0080030-L06
顆粒,M31-25Q6402-E17
(0A Footprint共用SPIFLASH8 is Socket footprint)

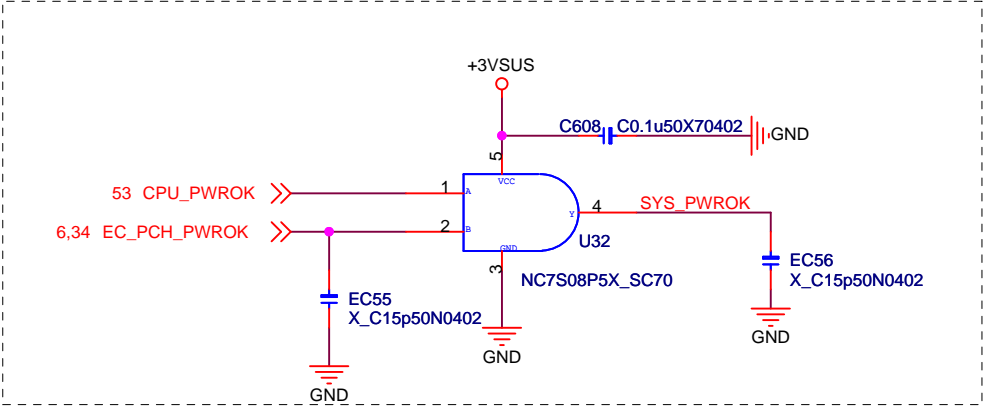


Lynx Point (DMI,FDI)

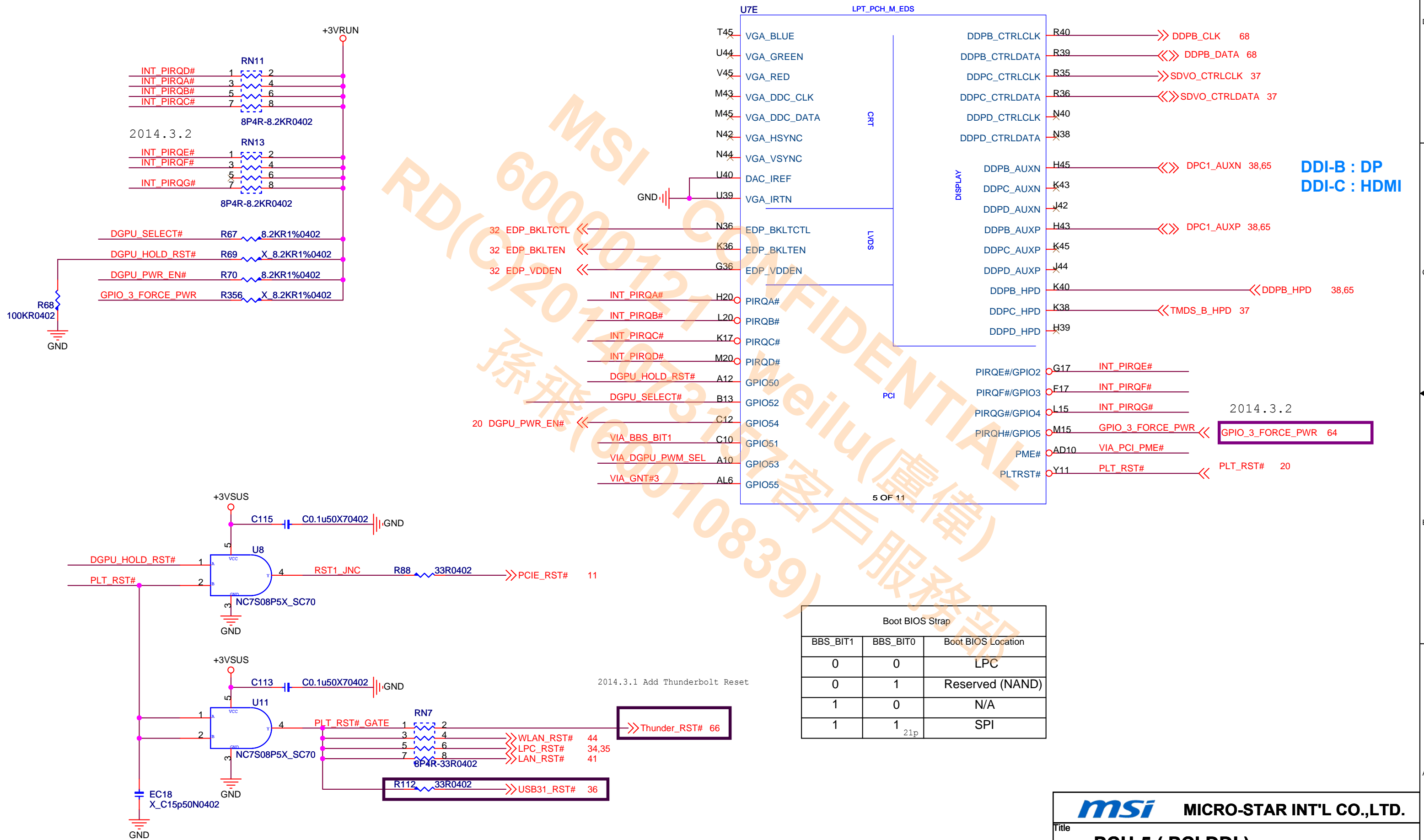


GPIO Setting : Ref 486708_LPT_EDS Section2.18

PLL ON DIE VR_ENABLE	
GPIO62	Internal pull high (Enable)
	Low: Disable



Lynx Point (PCI,DDI)



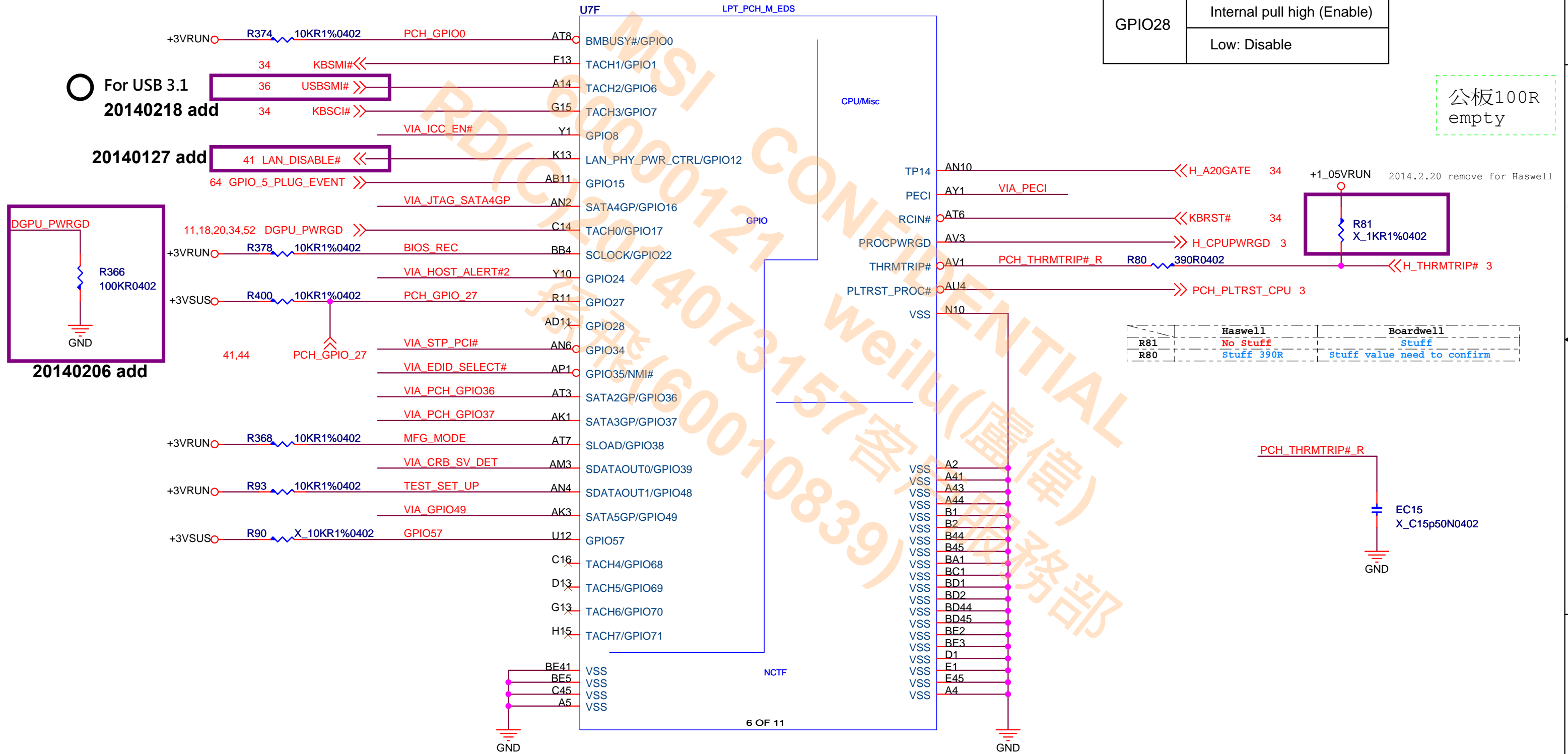
Boot BIOS Strap		
BBS_BIT1	BBS_BIT0	Boot BIOS Location
0	0	LPC
0	1	Reserved (NAND)
1	0	N/A
1	1	SPI

Lynx Point (GPIO,MISC)

GPIO Setting : Ref 486708_LPT_EDS Section2.24

PLL ON DIE VR_ENABLE	
GPIO28	Internal pull high (Enable)
	Low: Disable

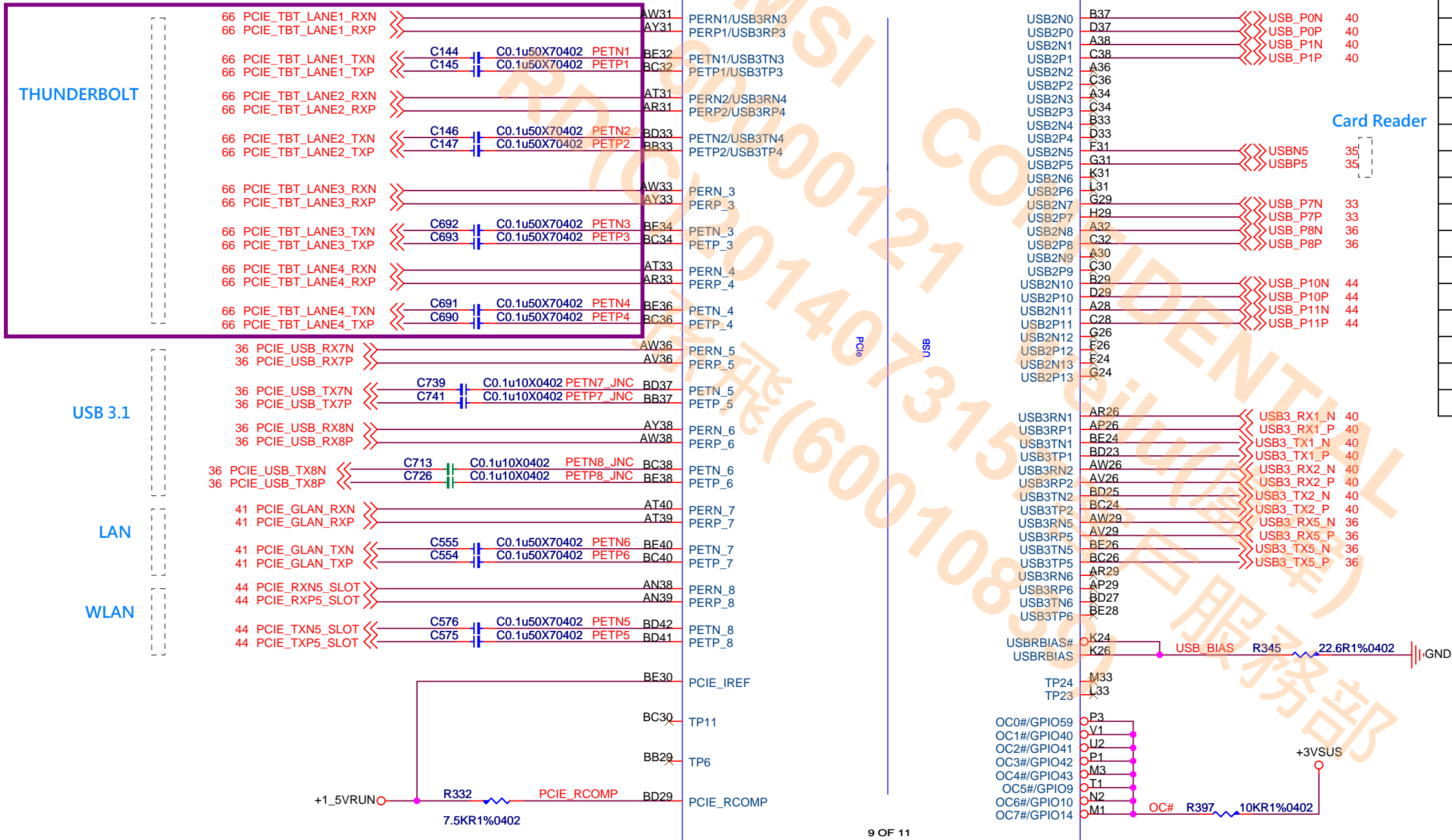
公板100R
empty



Lynx Point (PCIE,USB)

Intel Lynx Point ECHI USB(2.0) debug transport 需接Port1 or Port9

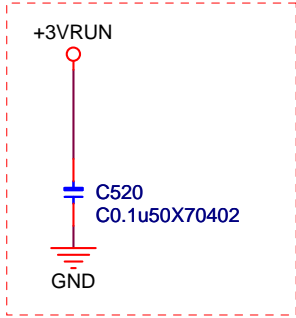
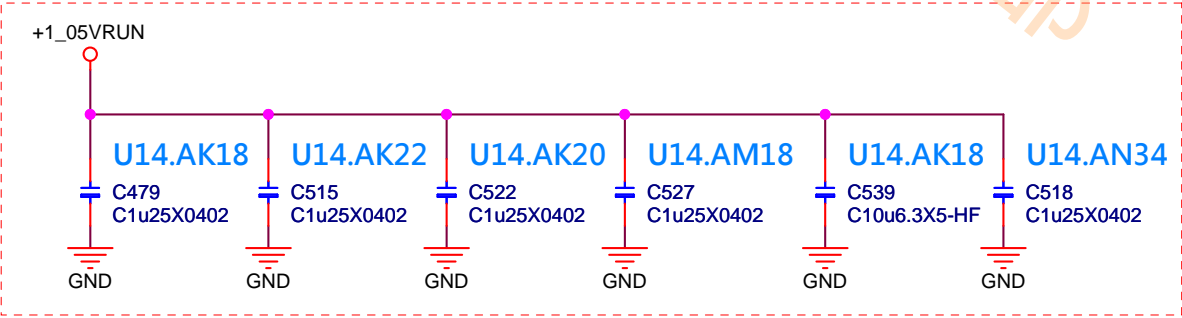
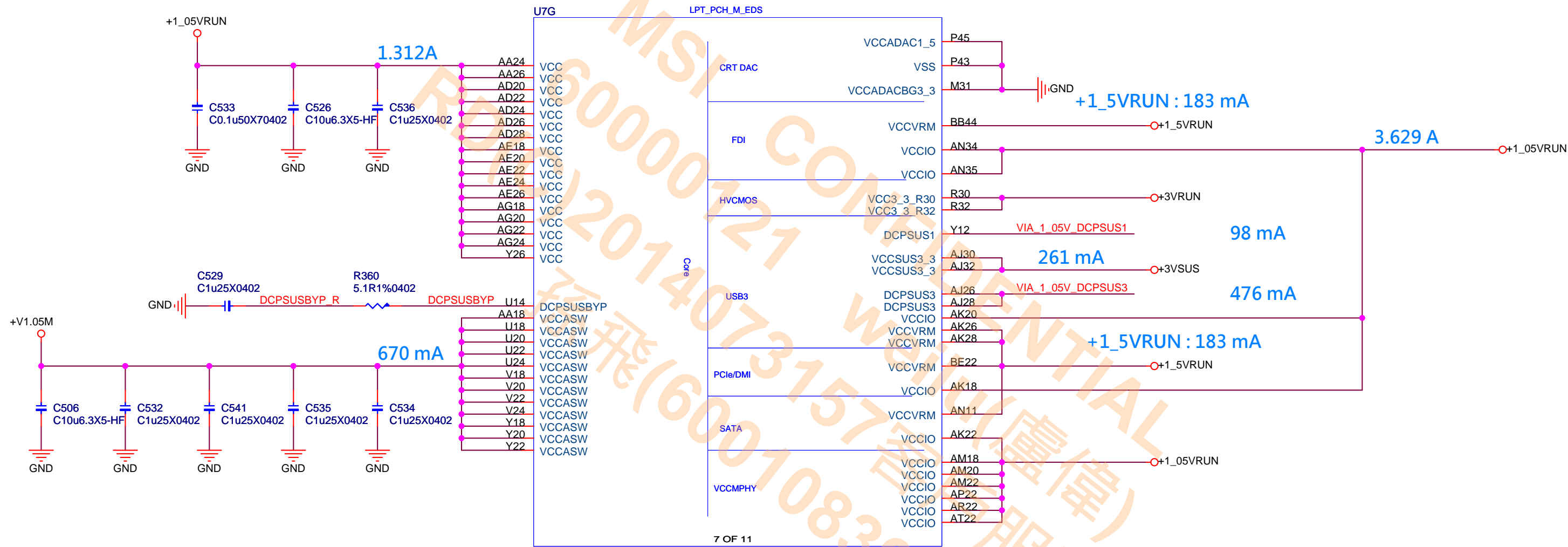
2014.2.24 Modify to four lanes TBT



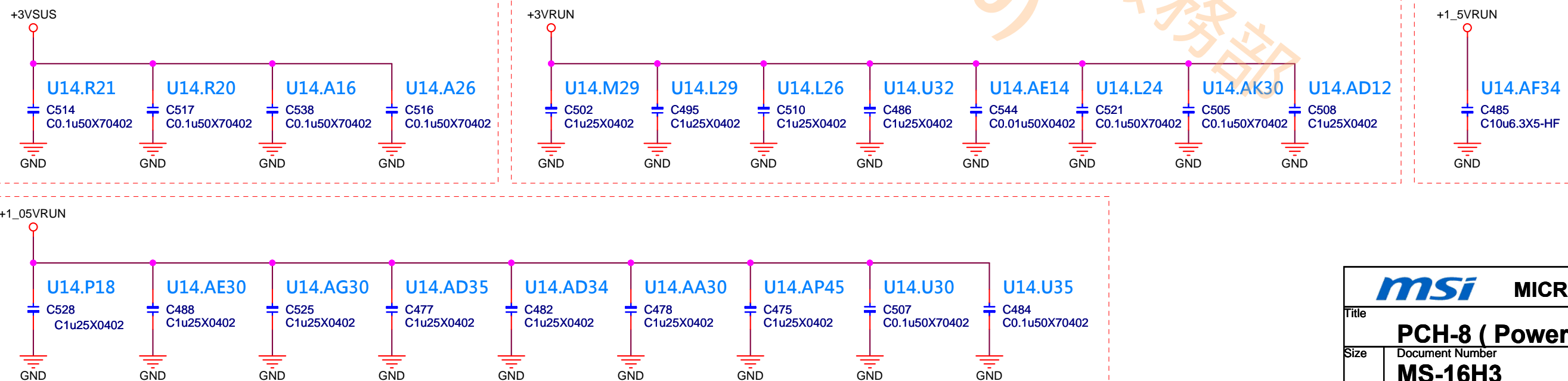
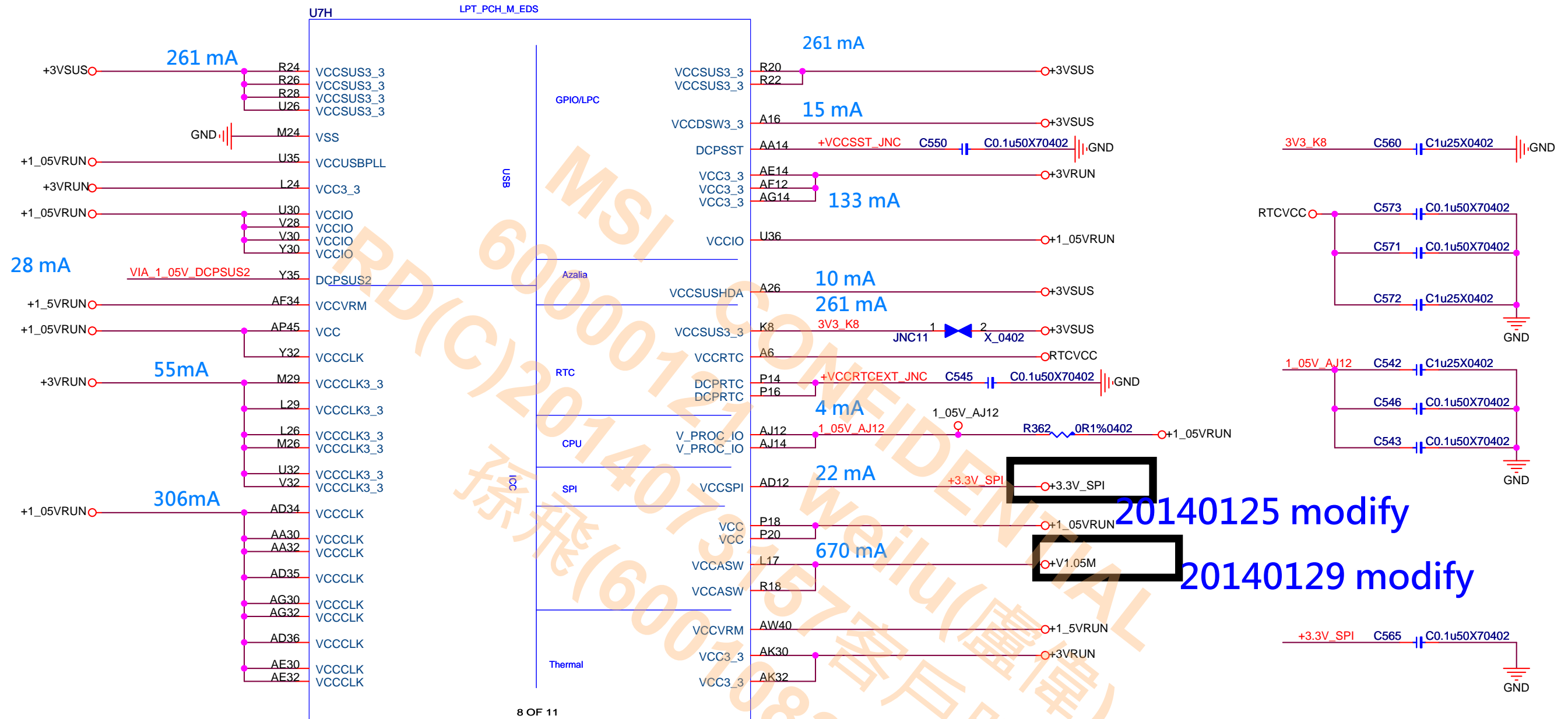
USB			
USB 2.0	USB 3.0	Device	Note
0	1	USB 3.0 Port 1	16H3A
1	2	USB 3.0 Port 2	16H3A
2			
3			NC
4			NC
5			NC
6			NC
7		EPF021	3 色KBC
8	3	USB 3.0 Port 5	16H31
9	4	USB 3.0 Port 6	no use
10		WLAN	
11		WebCam	
12		SECOND DISPLAY	
13			NC

HM86 沒USB3.0 PORT 5,6

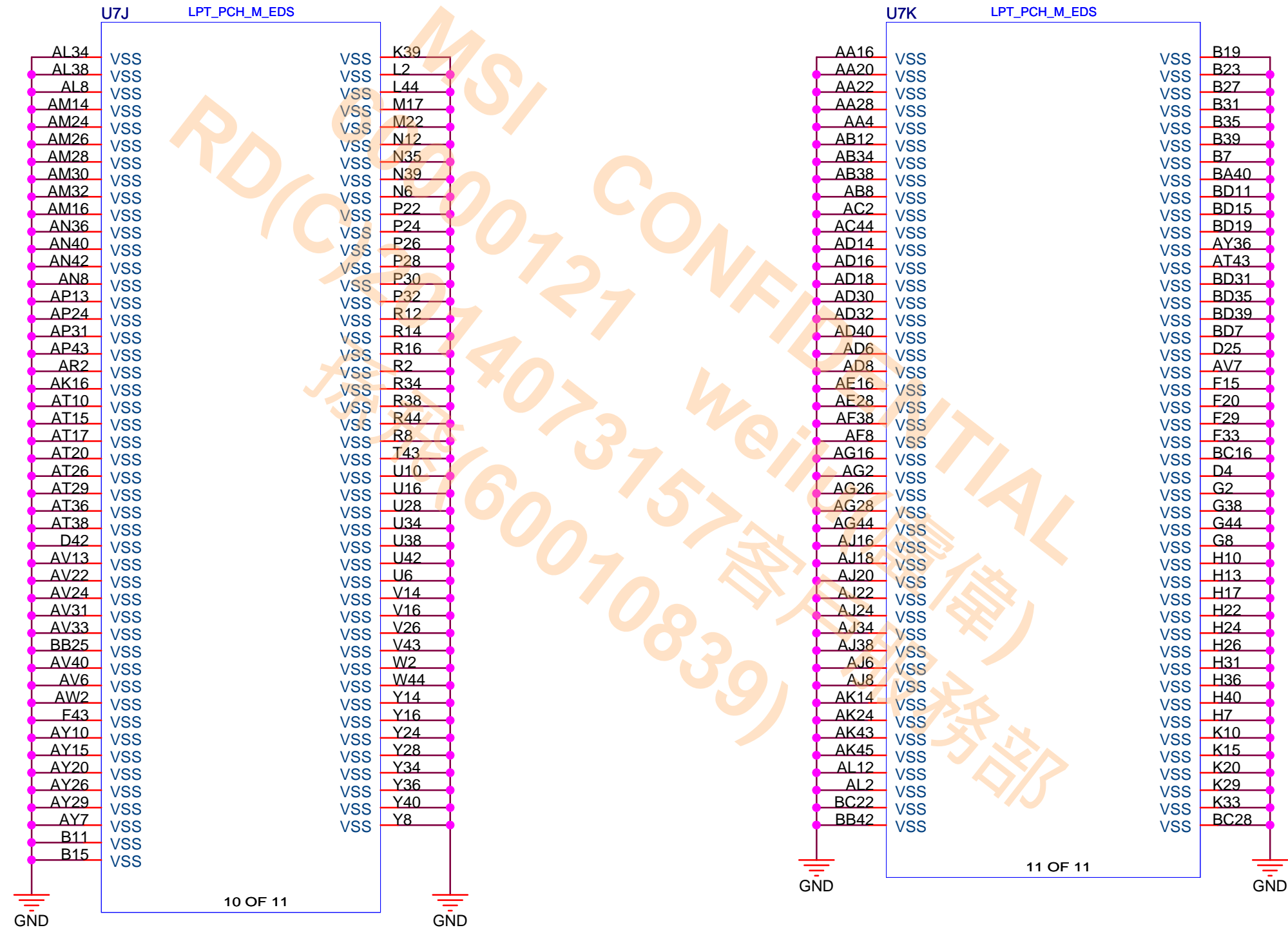
Lynx Point (Power)



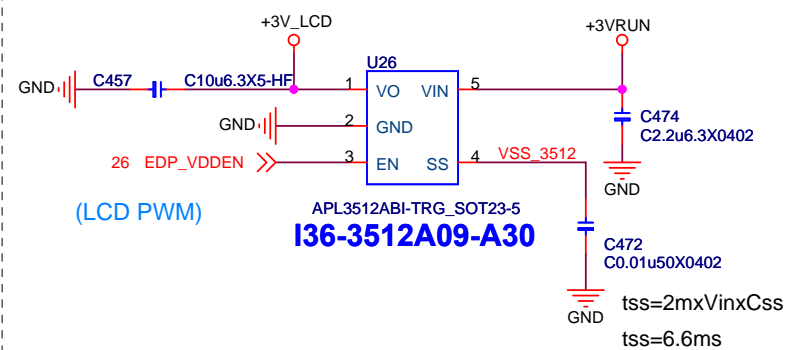
Lynx Point (Power)



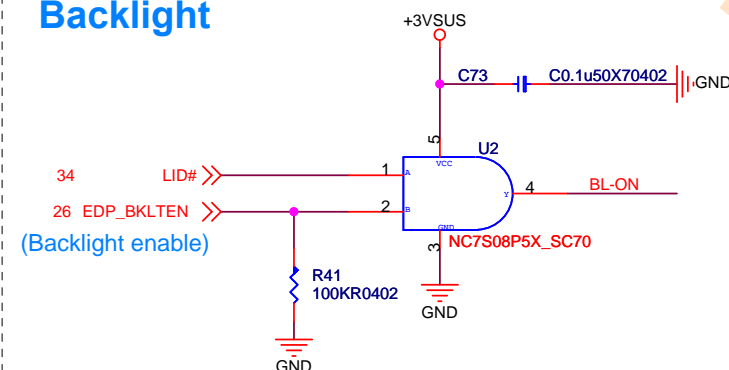
Lynx Point (GND)



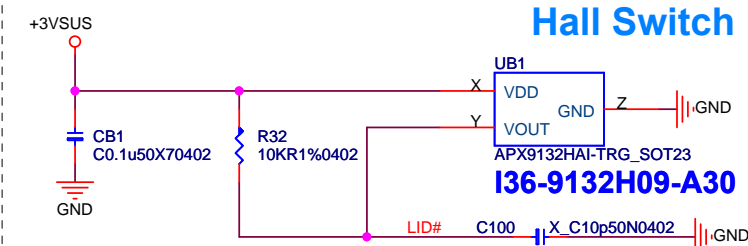
Pannel Device Logic Power



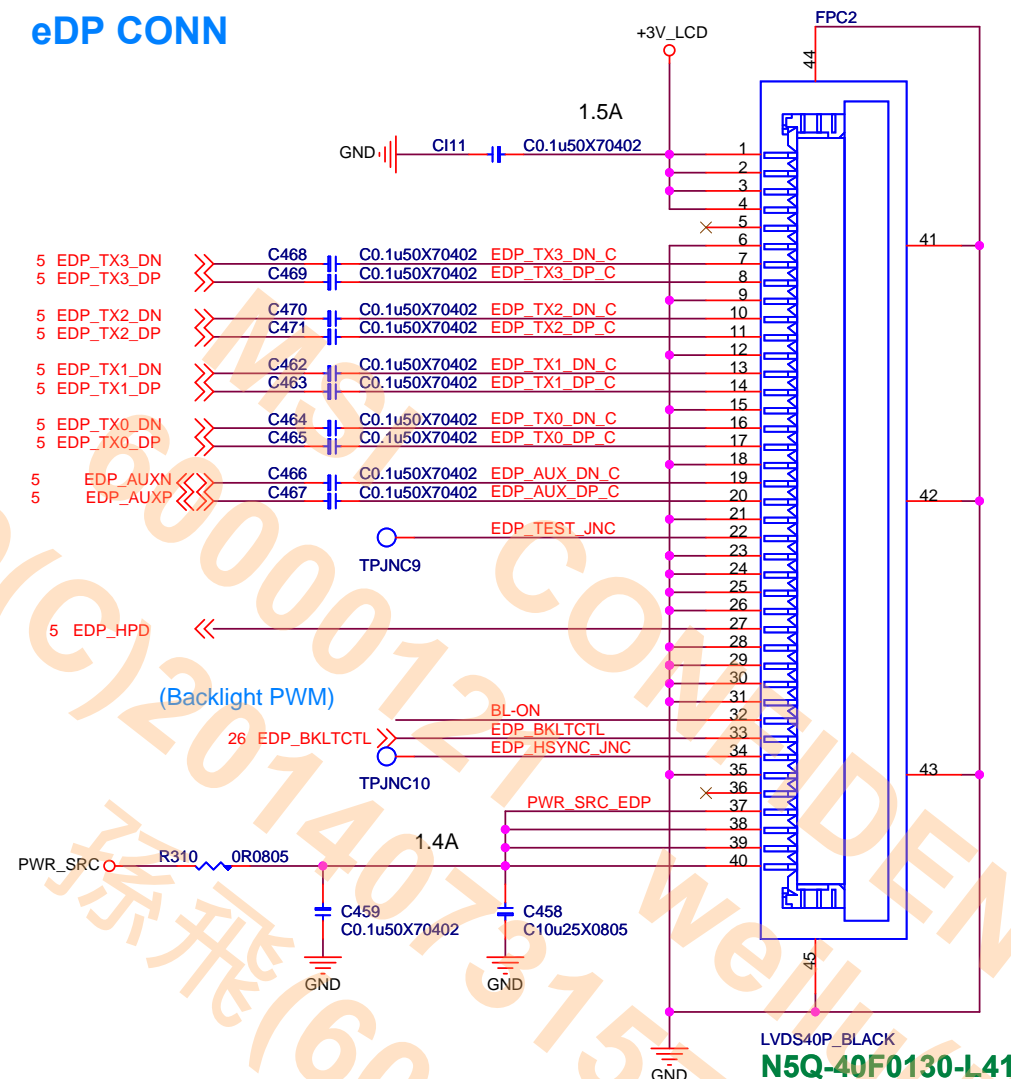
Backlight



Hall Switch



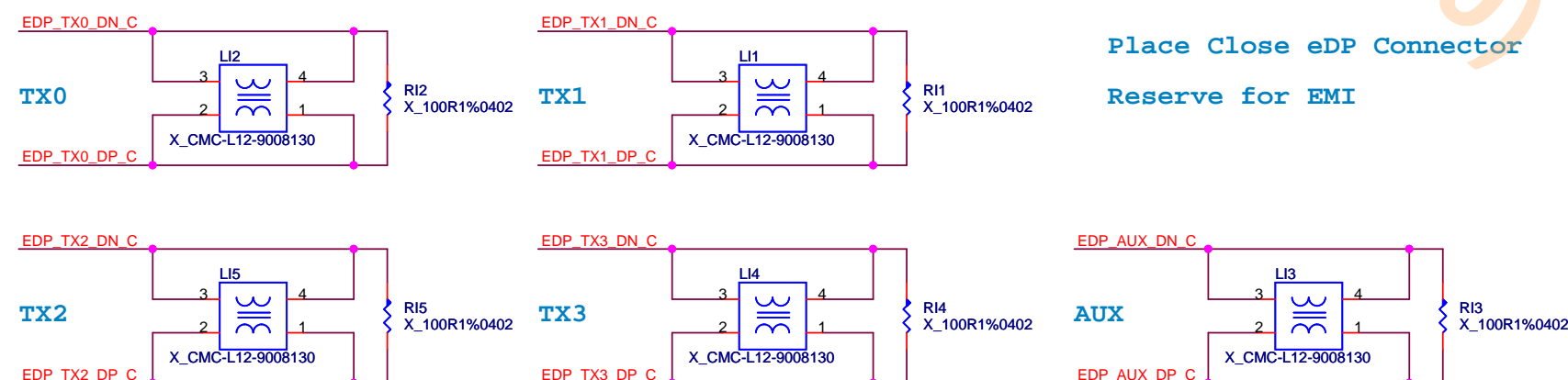
eDP CONN



LCD Module Pin Define

Pin No	Symbol	Description
1	WP	EEPROM Write Protect(Keep open)
2	H_GND	High Speed Ground(0V)
3	eDP_Rx_3N	Complement Signal Link Lane 3
4	eDP_Rx_3P	True Signal Link Lane 3
5	H_GND	High Speed Ground(0V)
6	eDP_Rx_2N	Complement Signal Link Lane 2
7	eDP_Rx_2P	True Signal Link Lane 2
8	H_GND	H_GND
9	eDP_Rx_1N	Complement Signal Link Lane 1
10	eDP_Rx_1P	True Signal Link Lane 1
11	H_GND	H_GND
12	eDP_Rx_0N	Complement Signal Link Lane 0
13	eDP_Rx_0P	True Signal Link Lane 0
14	H_GND	H_GND
15	eDP_AUX_CH_P	True Signal Aux Channel
16	eDP_AUX_CH_N	Complement Signal Aux Channel
17	H_GND	H_GND
18	LCD_VCC	LCD logic and driver power
19	LCD_VCC	LCD logic and driver power
20	LCD_VCC	LCD logic and driver power
21	LCD_VCC	LCD logic and driver power
22	TEST	LCD Test Port
23	LCD_GND	LCD logic and driver ground(0V)
24	LCD_GND	LCD logic and driver ground(0V)
25	LCD_GND	LCD logic and driver ground(0V)
26	LCD_GND	LCD logic and driver ground(0V)
27	eDP_HPDP	HPD signal pin
28	BL_GND	Backlight ground(0V)
29	BL_GND	Backlight ground(0V)
30	BL_GND	Backlight ground(0V)
31	BL_GND	Backlight ground(0V)
32	BL_ENABLE	Backlight enable
33	BL_PWM_DIM	System PWM signal input
34	SDA	I2C-bus Data
35	SCL	I2C-bus Clock
36	BL_PWR	Backlight power (5~21V)
37	BL_PWR	Backlight power (5~21V)
38	BL_PWR	Backlight power (5~21V)
39	BL_PWR	Backlight power (5~21V)
40	HSYNC	HSYNC output from Tcon

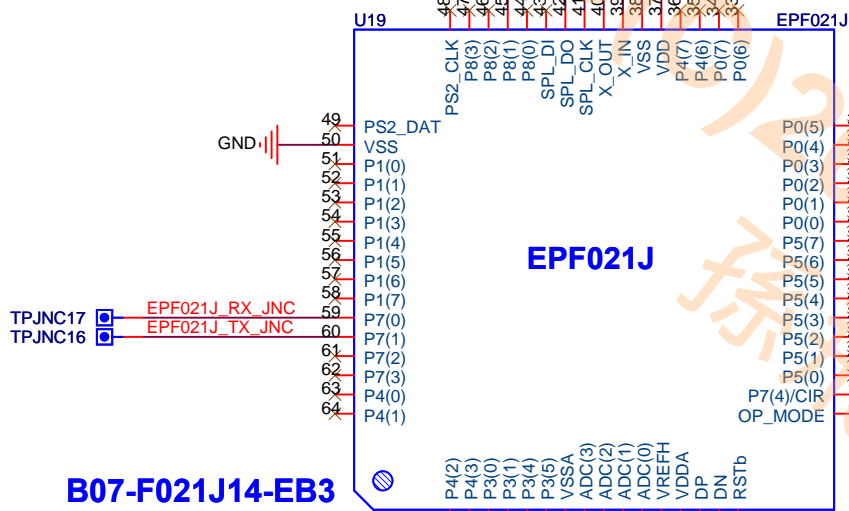
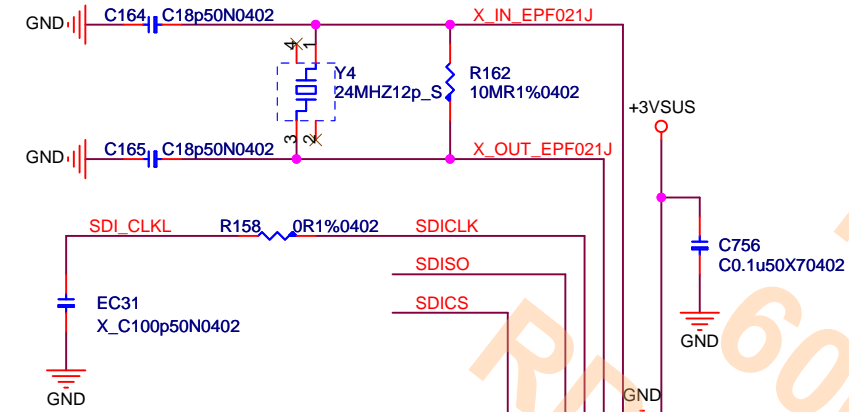
Place Close eDP Connector
Reserve for EMI



msi MICRO-STAR INT'L CO.,LTD.

Title	eDP switch & Conn/CAM/Lid		
Size	Document Number	Rev	1.0
Custom	MS-16H3		
Date:	Wednesday, June 25, 2014	Sheet	32 of 69

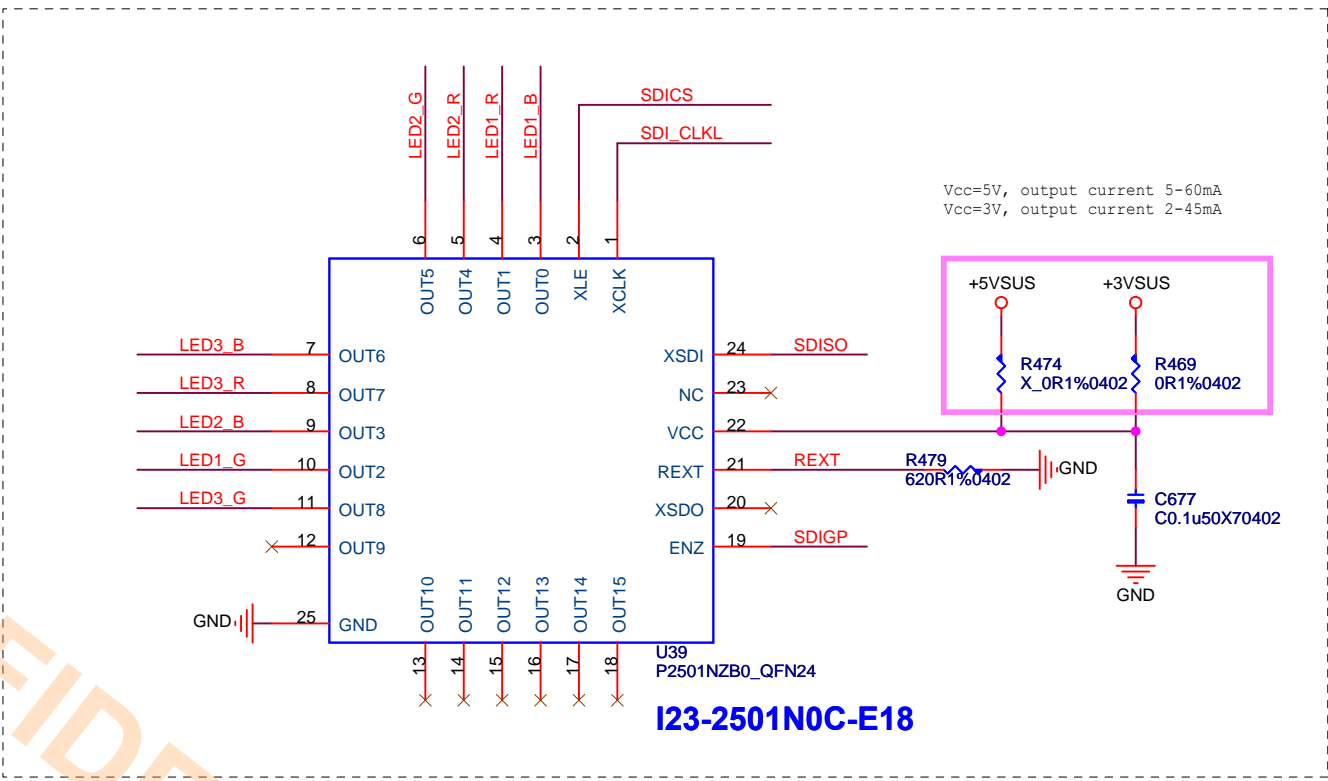
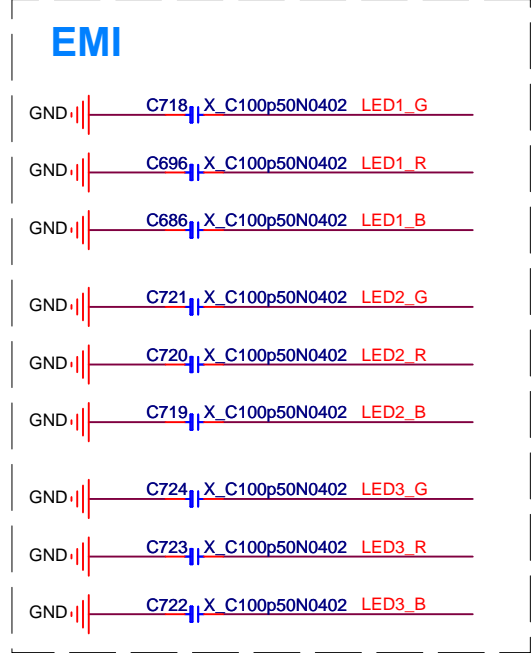
LED 8051 Controller



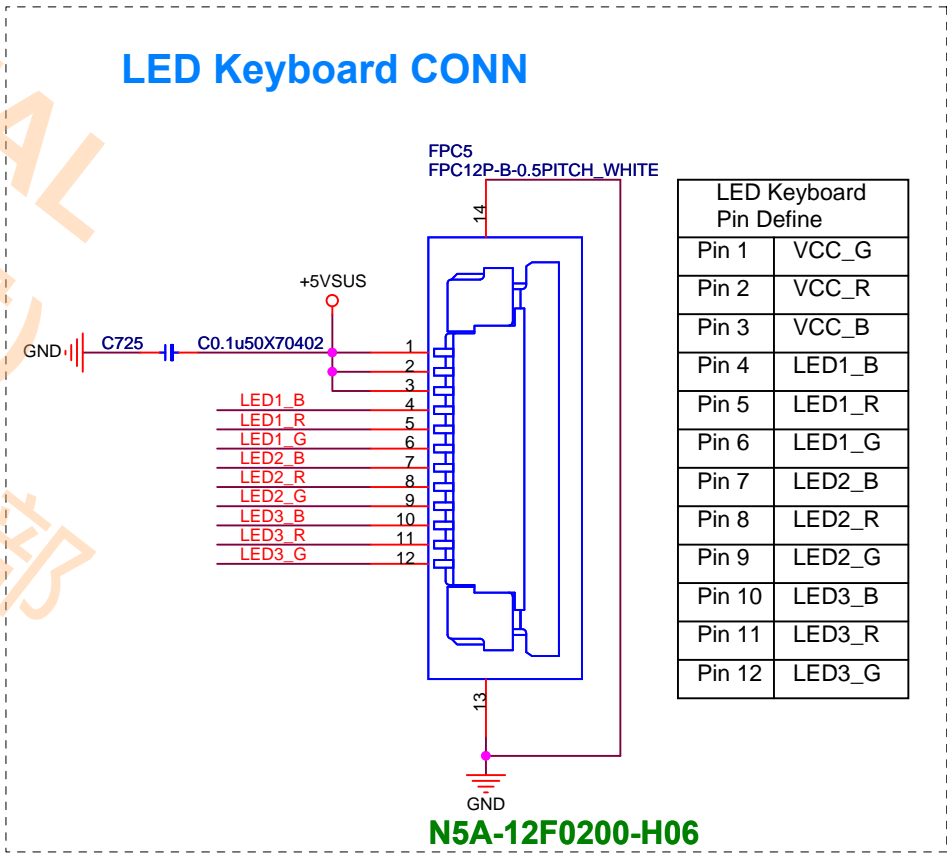
B07-F021J14-EB3

34,47 BATCLK_M
34,47 BATDATA_M

Pin12 & Pin13 have diff branch



I23-2501N0C-E18

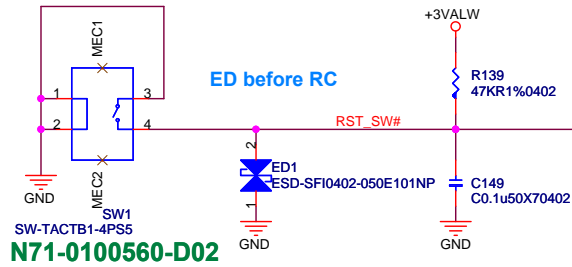


LED Keyboard Pin Define	
Pin 1	VCC_G
Pin 2	VCC_R
Pin 3	VCC_B
Pin 4	LED1_B
Pin 5	LED1_R
Pin 6	LED1_G
Pin 7	LED2_B
Pin 8	LED2_R
Pin 9	LED2_G
Pin 10	LED3_B
Pin 11	LED3_R
Pin 12	LED3_G

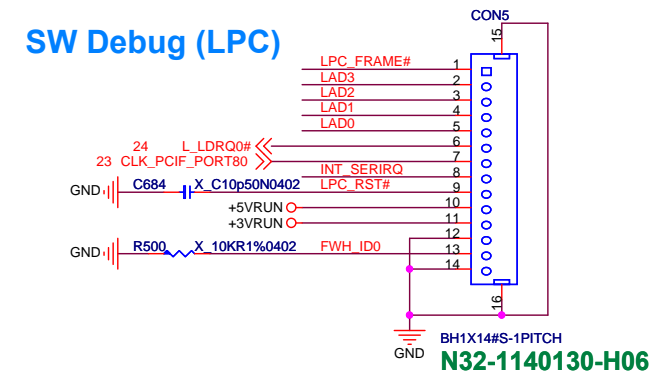
N5A-12F0200-H06

KBC(KB3930QFB1)

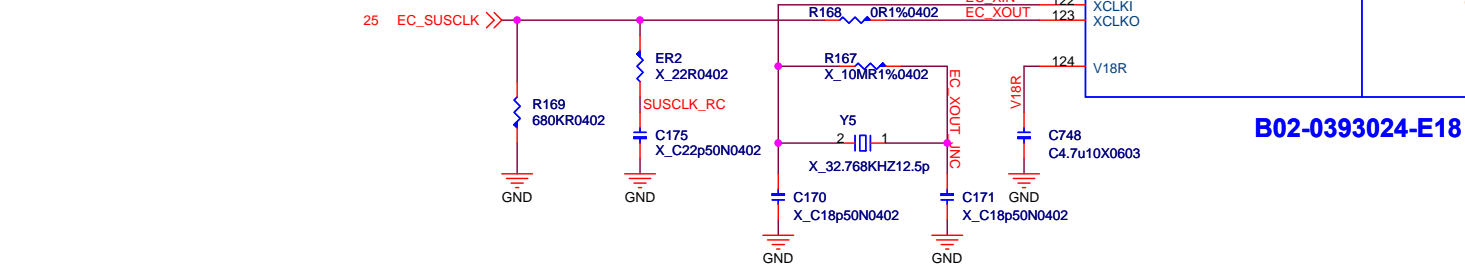
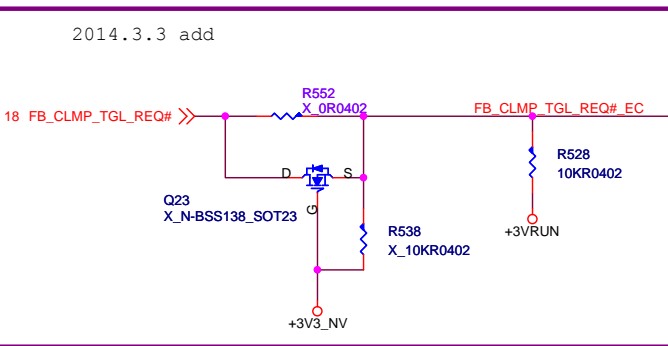
Hardware Reset



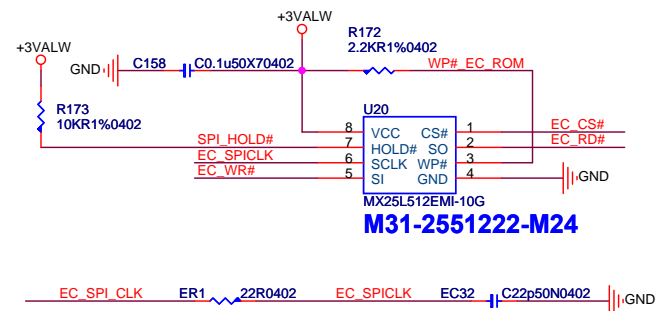
SW Debug (LPC)



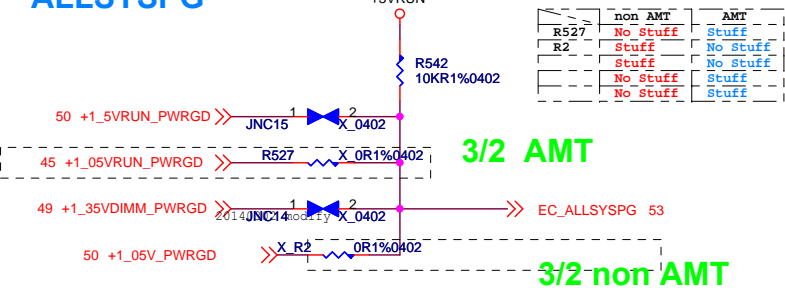
2014.3.3 add



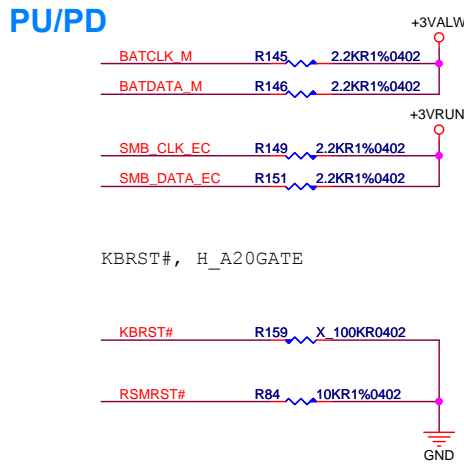
ROM



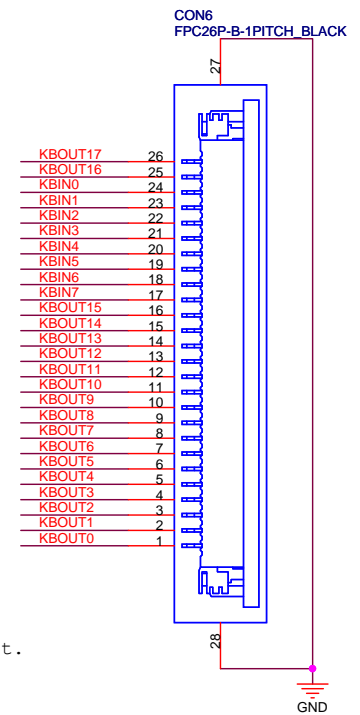
ALLSYSPG



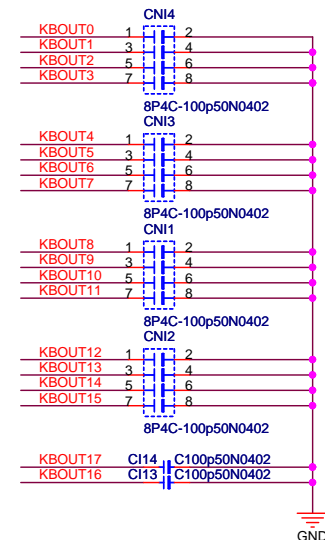
PU/PD



Keyboard conn

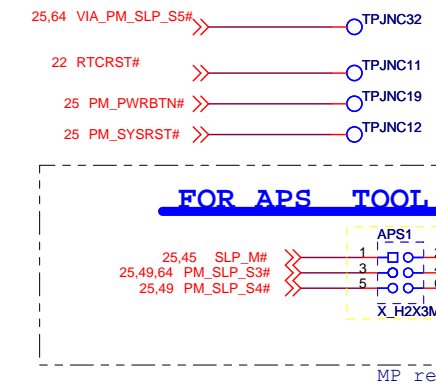


N5A-26F0340-H06

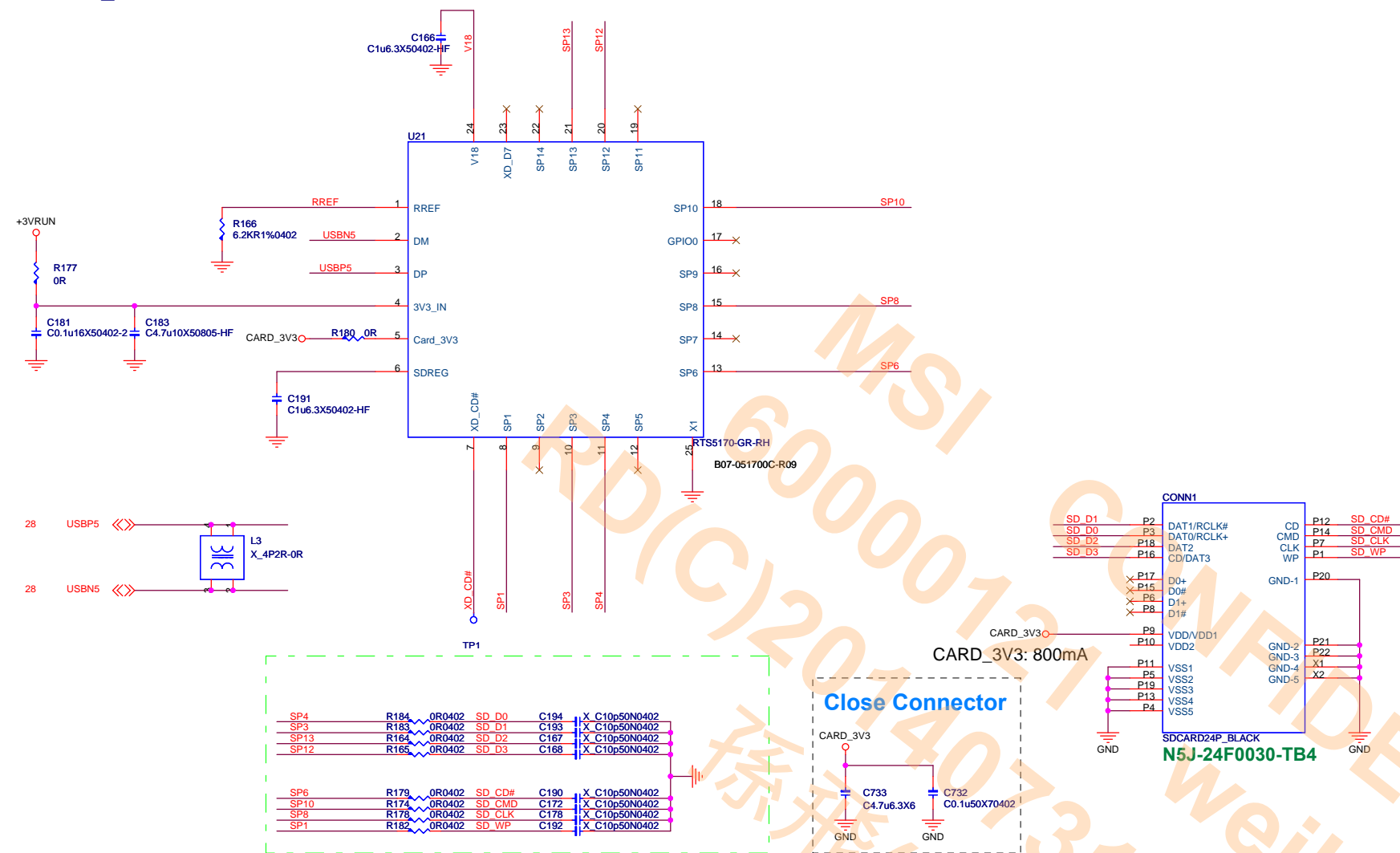


FLASH/ME DEBUG MODE STRAP

20140311 add



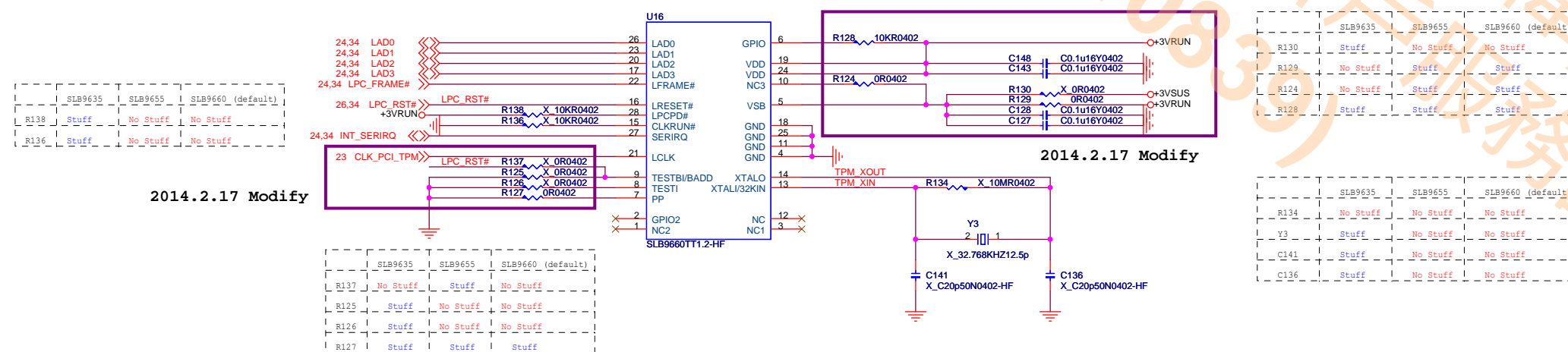
CARD READER_RTS5170



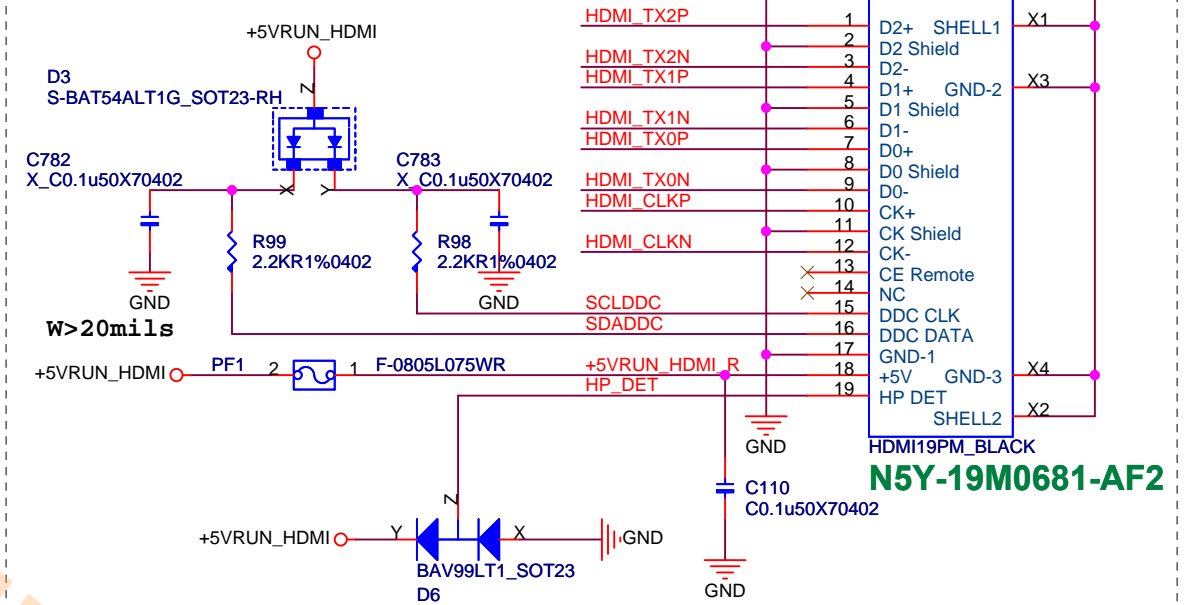
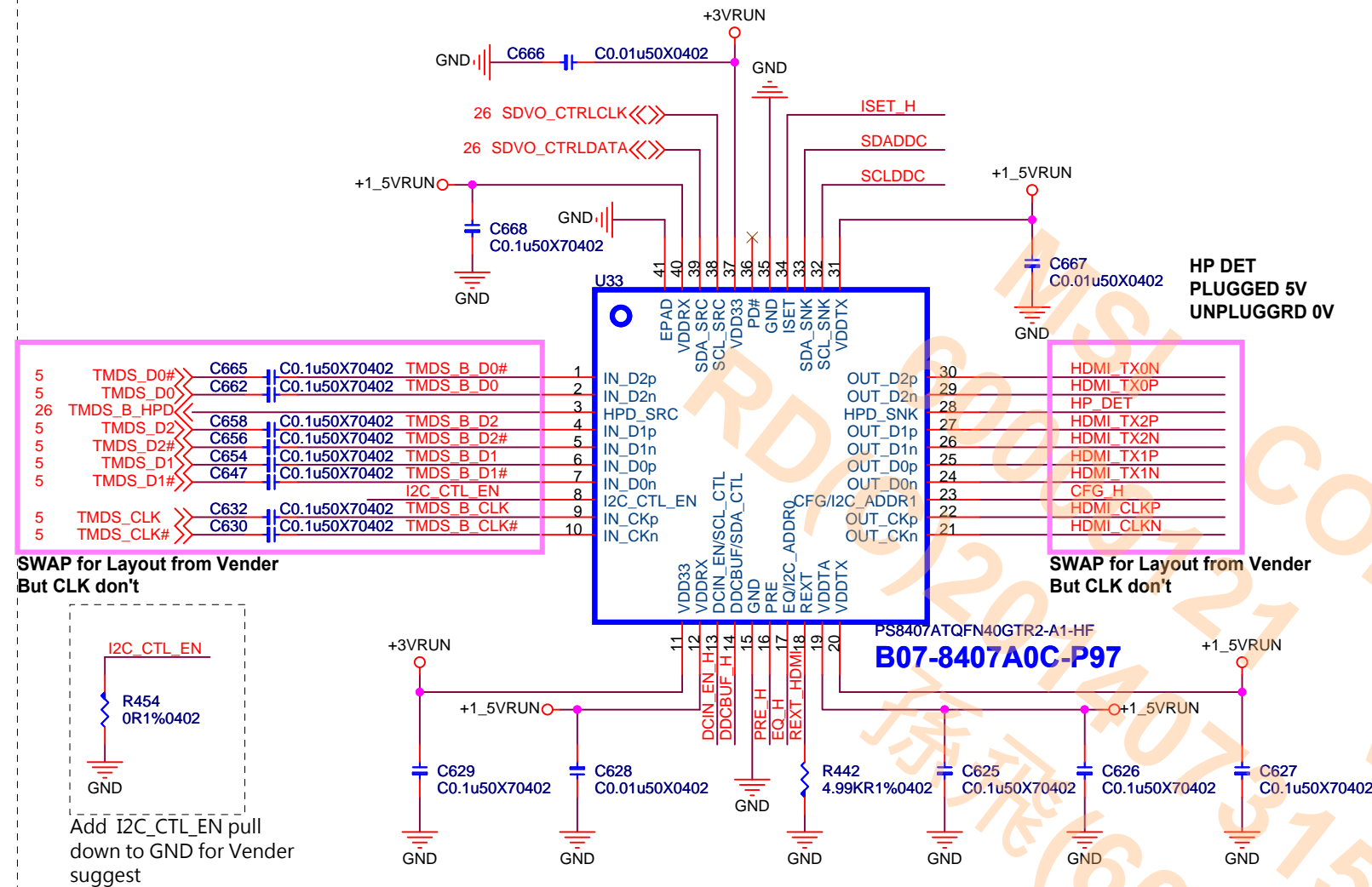
For EMI and Close to RTS5170

Pin#	Name	I/O Type	Description
1	RREF	I	Connect external resistor (6.2K \pm 1%) to reference ground
2	DM	I/O	USB D- signal
3	DP	I/O	USB D+ signal
4	3V3_IN	I	3.3V power input
5	CARD_3V3	O	3.3V power for all cards
6	SDREG	O	Internal regulator for SD card. An external capacitor should be connected
7	XD_CD#	I	xD Card Detect (xD_CD#)
8	SP1	I/O	xD Ready Signal (xD_RDY), SD Write Protect (SD_WP) and MS Clock (MS_CLK)
9	SP2	I/O	xD RE# and MS Card Detect (MS_INS#)
10	SP3	I/O	xD CE# and SD Data 1 (SD_DAT1)
11	SP4	I/O	xD_CLE, SD Data 0 (SD_DAT0) and MS Data 7 (MS_D7)
12	SP5	I/O	xD_ALE, SD Data 7 (SD_DAT7) and MS Data 3 (MS_D3)
13	SP6	I/O	xD_WE# and SD Card Detect (SD_CD#)
14	SP7	I/O	xD Write Protect (xD_WP), SD_Data 6 (SD_DAT6) and MS Data 6 (MS_D6)
15	SP8	I/O	xD Data 0 (xD_D0), SD Clock (SD_CLK) and MS Data 2 (MS_D2)
16	SP9	I/O	xD Data 1 (xD_D1), SD Data 5 (SD_D5) and MS Data 0 (MS_D0)
17	GPIO0	I/O	General purpose input/output with interrupt ability
18	SP10	I/O	xD Data 2 (xD_D2) and SD command signal (SD_CMD)
19	SP11	I/O	xD Data 3 (xD_D3), SD Data 4 (SD_DAT4) and MS Data 4 (MS_D4)
20	SP12	I/O	xD Data 4 (xD_D4), SD Data 3 (SD_DAT3) and MS Data 1 (MS_D1)
21	SP13	I/O	xD Data 5 (xD_D5), SD Data 2 (SD_DAT2) and MS Data 5 (MS_D5)
22	SP14	I/O	xD Data 6 (xD_D6) and MS BS
23	XD_D7	I/O	xD Data 7 (xD_D7)
24	V18	O	Regulated supply voltage (1.8V \pm 10%) from internal 3.3V to 1.8V regulator; supplies internal digital circuits. An external capacitance should be connected

TPM

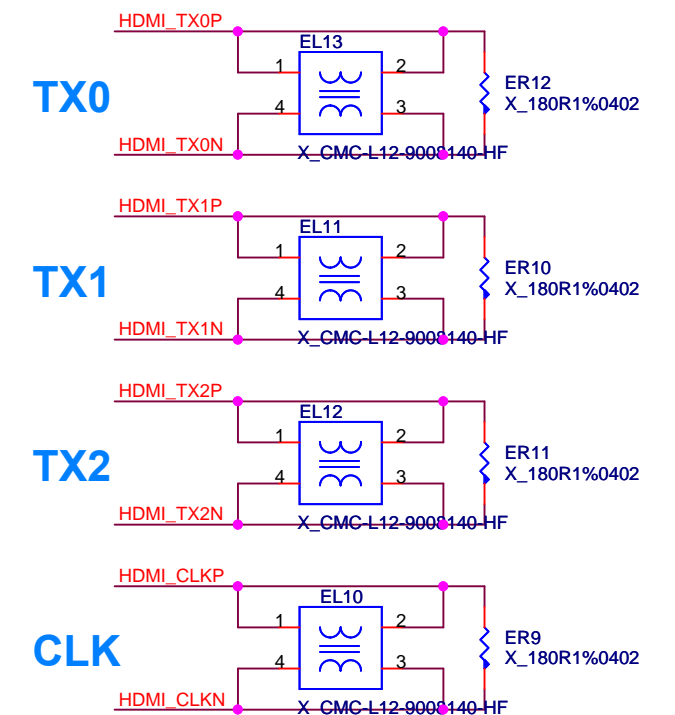


HDMI Repeater



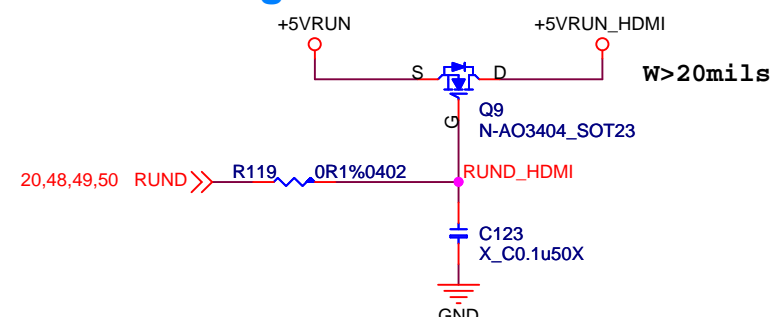
An HDMI Source shall have +5V Power signal over-current protection of no more than 0.5A.

HPD_SNK Internal PD 150kohm

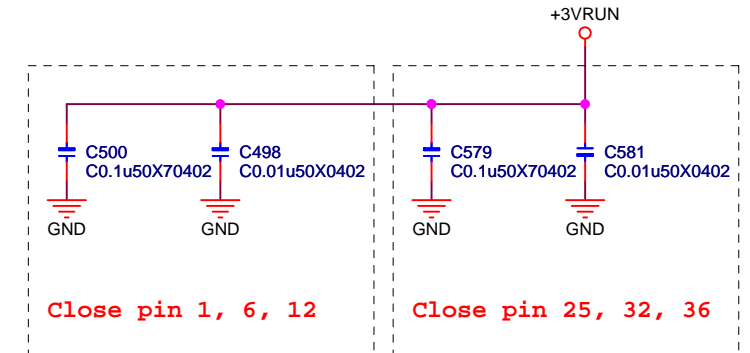
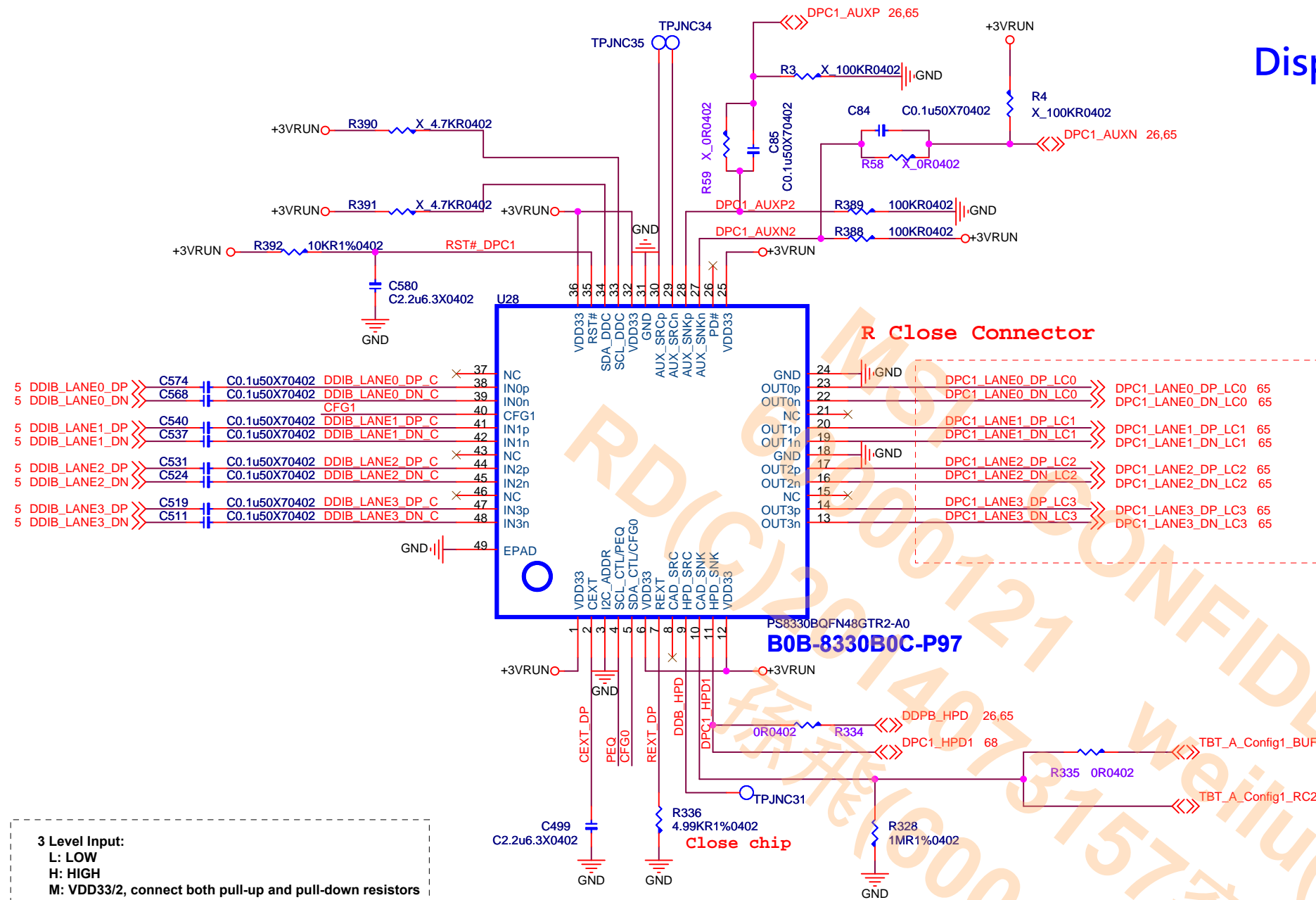


ADDR1 (CFG)	ADDR0 (EQ)	I2C control bus address (Internal pull down at ~150kΩ, 3.3V I/O)
0	0	0x4C / 4D (default)
0	1	0x5C / 5D
1	0	0xCC / CD
1	1	0xEC / ED

Avoid HDMI Leakage



Display Port



CAD_SNK Have internal Pull down 1Mohm.
HPD_SNK Have internal Pull down 150kohm.
No problem with Leakage from DP device
The DP_PWR and RETURN pins of the
box-to-box connectors must support the
maximum current rating of 500mA.

Configuration pin for automatic EQ and AUX interception; Internal pull down at ~150k Ohm, 3.3V I/O.

- L: default, automatic EQ enable & AUX interception enable
- H: automatic EQ disable & AUX interception enable
- M: automatic EQ disable & AUX interception disable, no pre-emphasis, 600mVpp swing

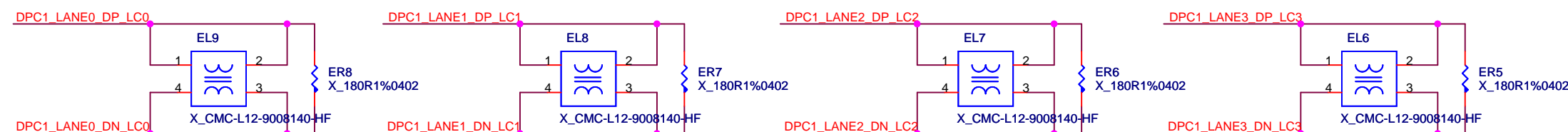
Configuration pin for auto test and input offset cancellation, 3.3V IO, internal pull up at ~150K Ohm

- H: default, auto test disable & input offset cancellation enable
- L: auto test enable & input offset cancellation enable
- M: auto test disable & input offset cancellation disable

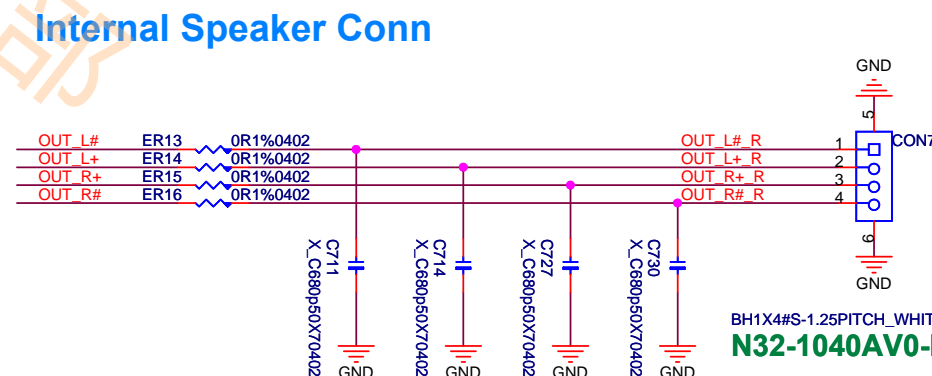
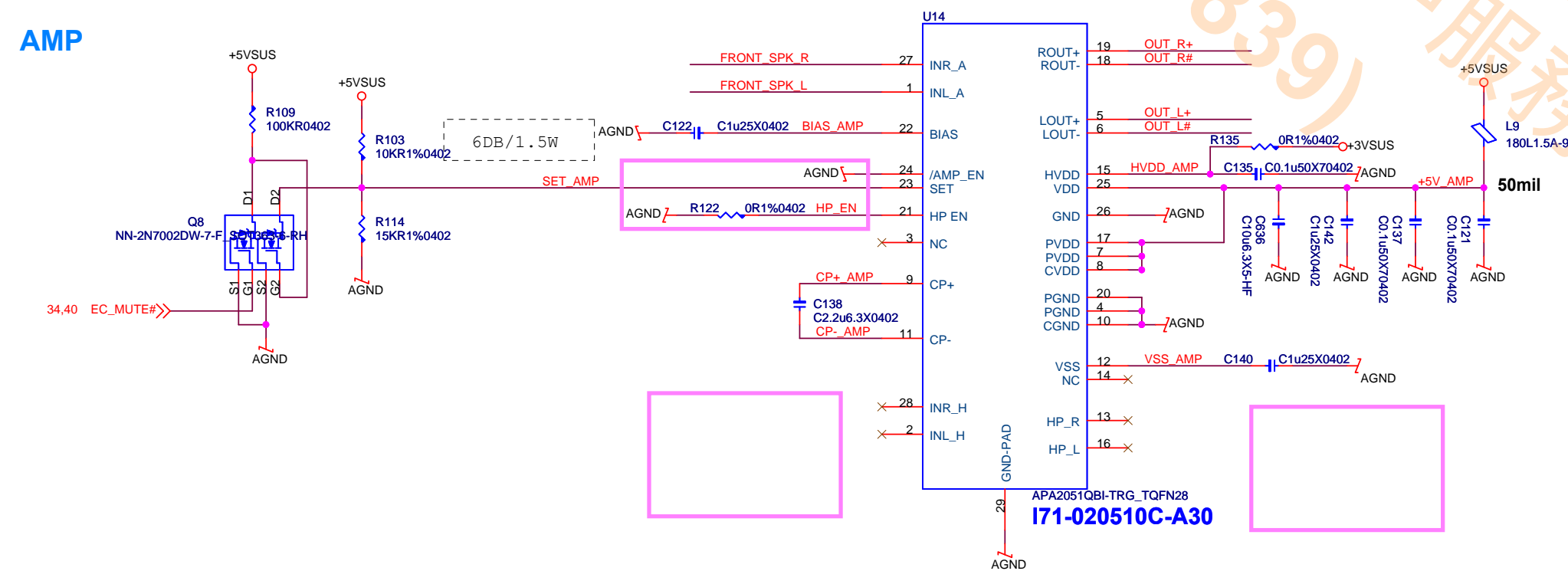
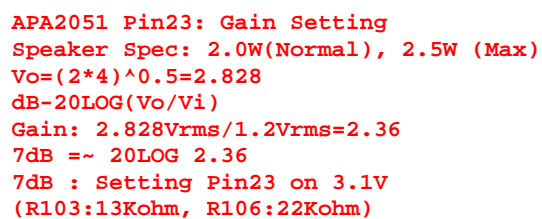
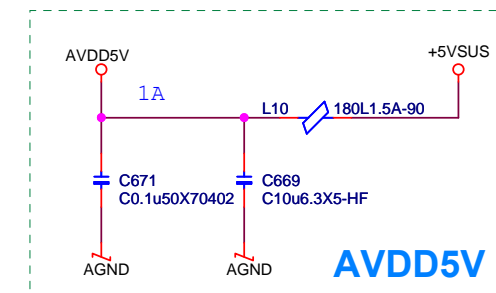
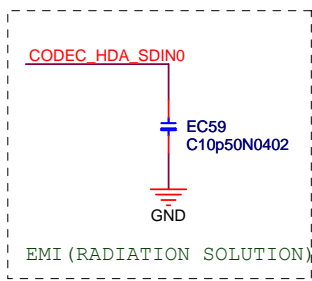
Programmable input equalization levels; Internal pull down at ~150k Ohm, 3.3V I/O.
 L: default, LEQ, compensate channel loss up to 12dB @ HBR2
 H: LEQ, compensate channel loss up to 15dB @ HBR2
 M: HLEQ, compensate channel loss up to 5dB @ HBR2

EMI Close Connector

LANE0

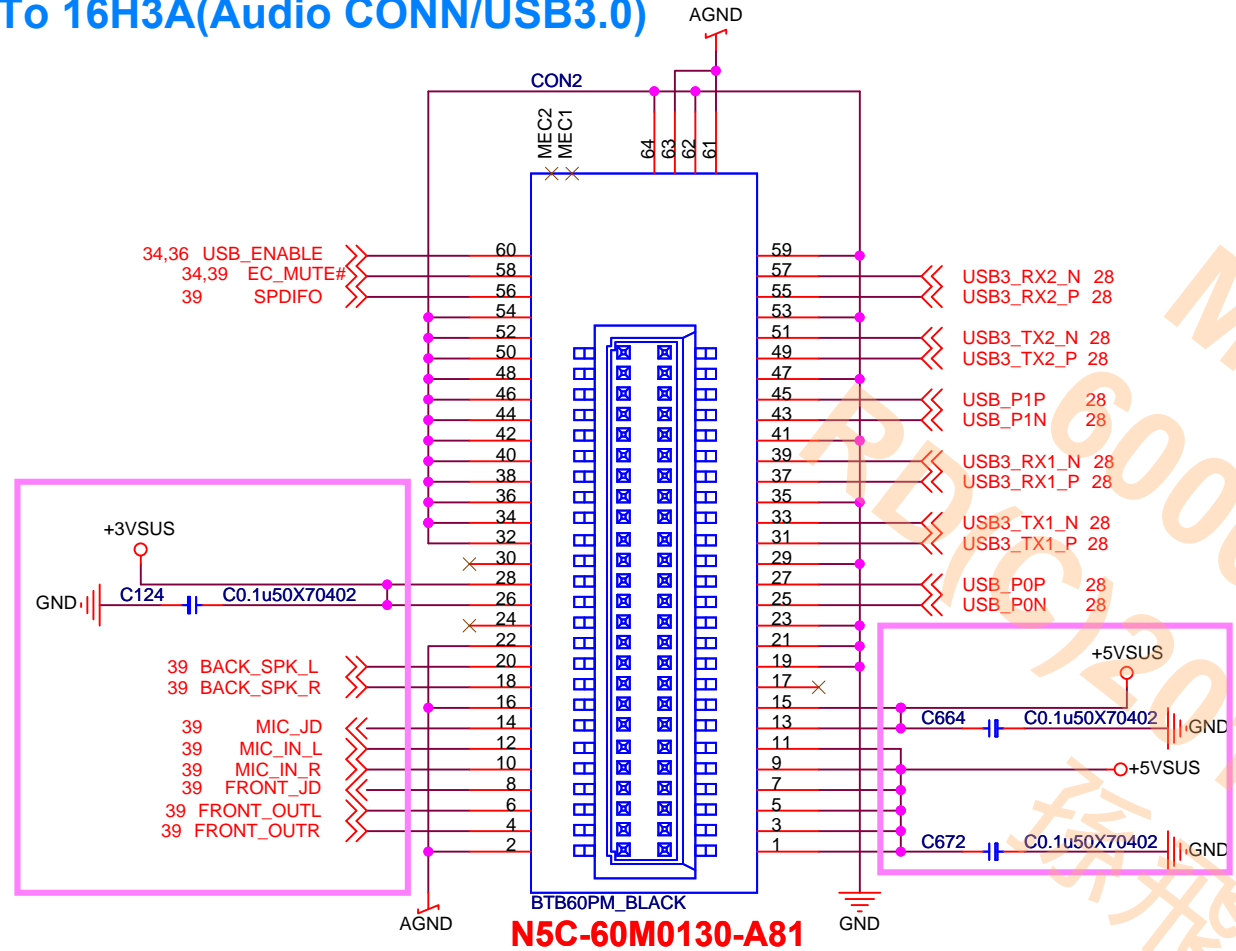


Audio CODEC/Audio AMP

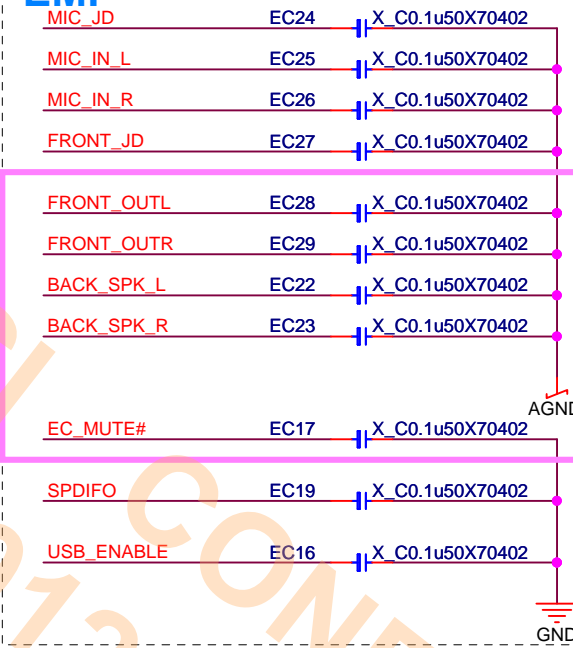


CPU FAN/BTB CONN

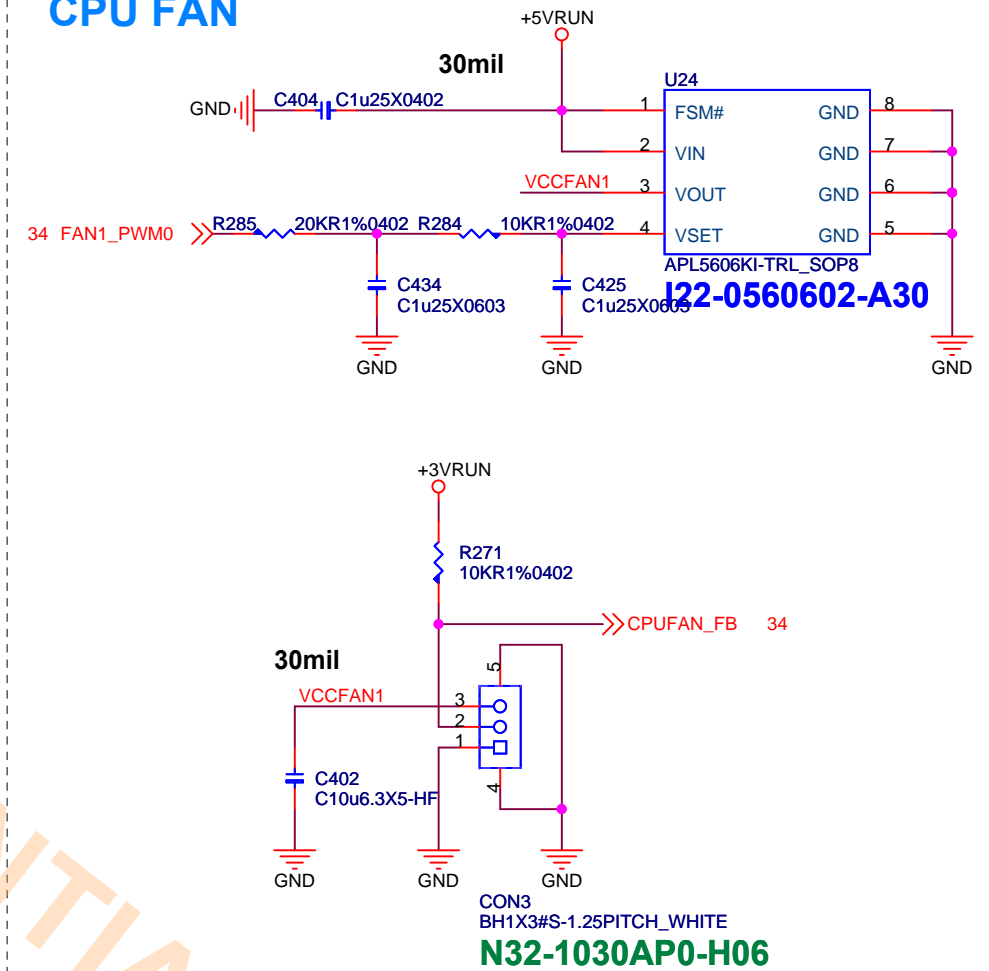
To 16H3A(Audio CONN/USB3.0)



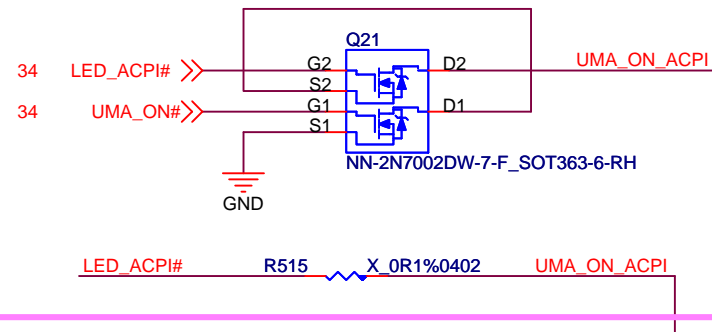
EMI



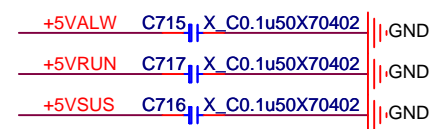
CPU FAN



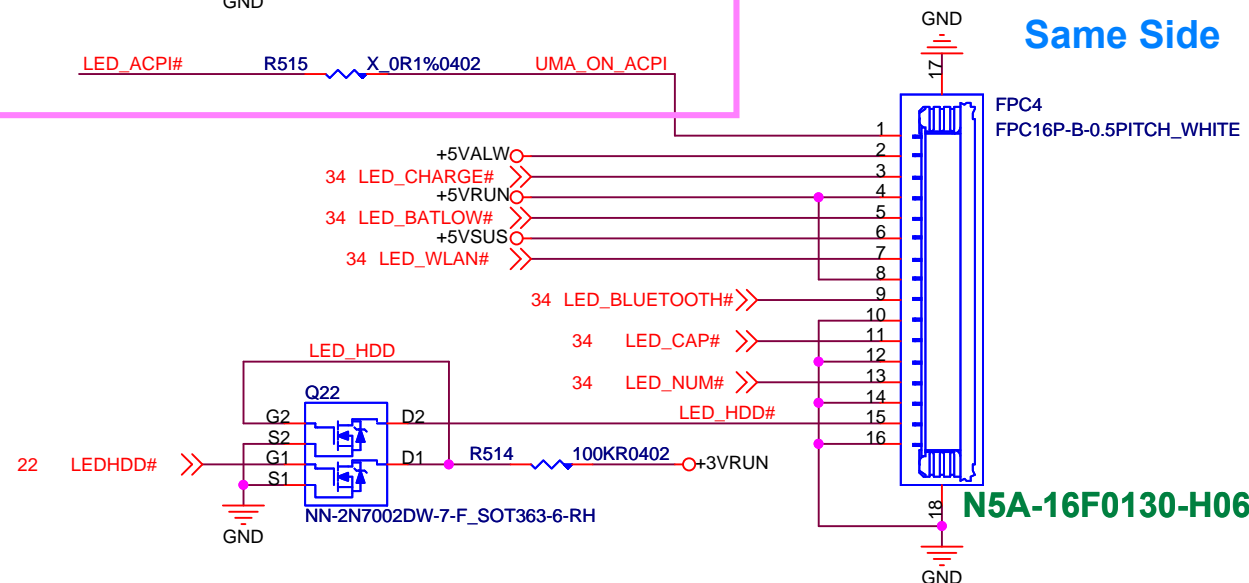
S3 Breath S0 No active



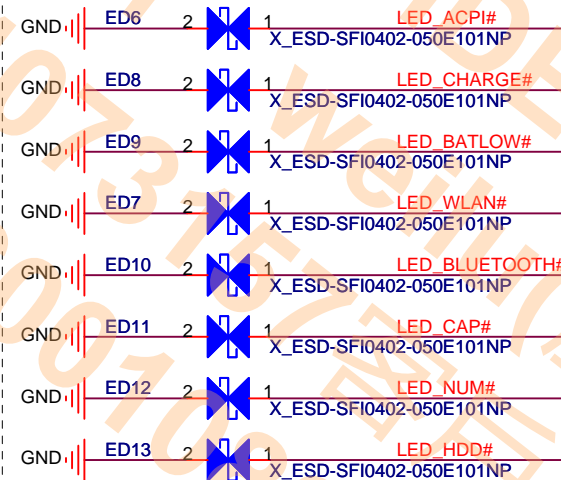
To 16H3B(LED Board)



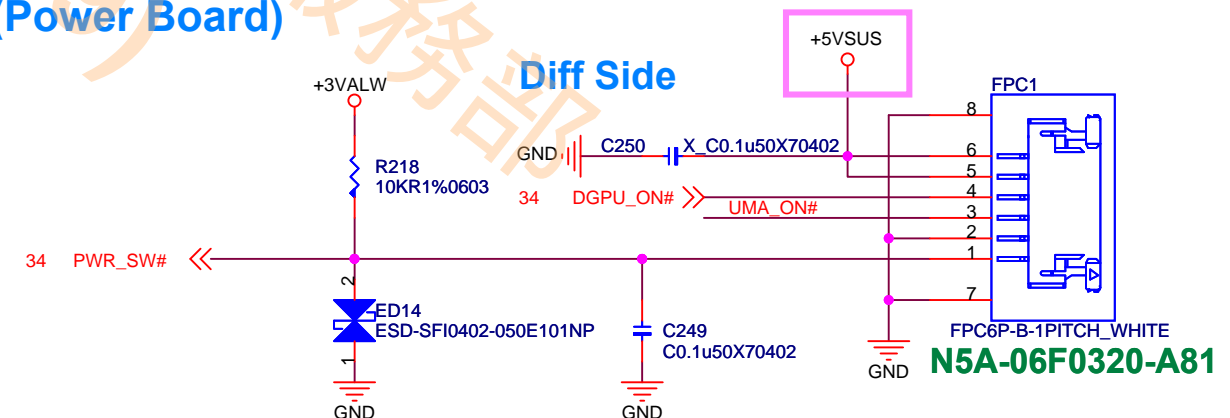
Same Side



EMI



To 16H3C (Power Board)



msi

MICRO-STAR INT'L CO.,LTD.

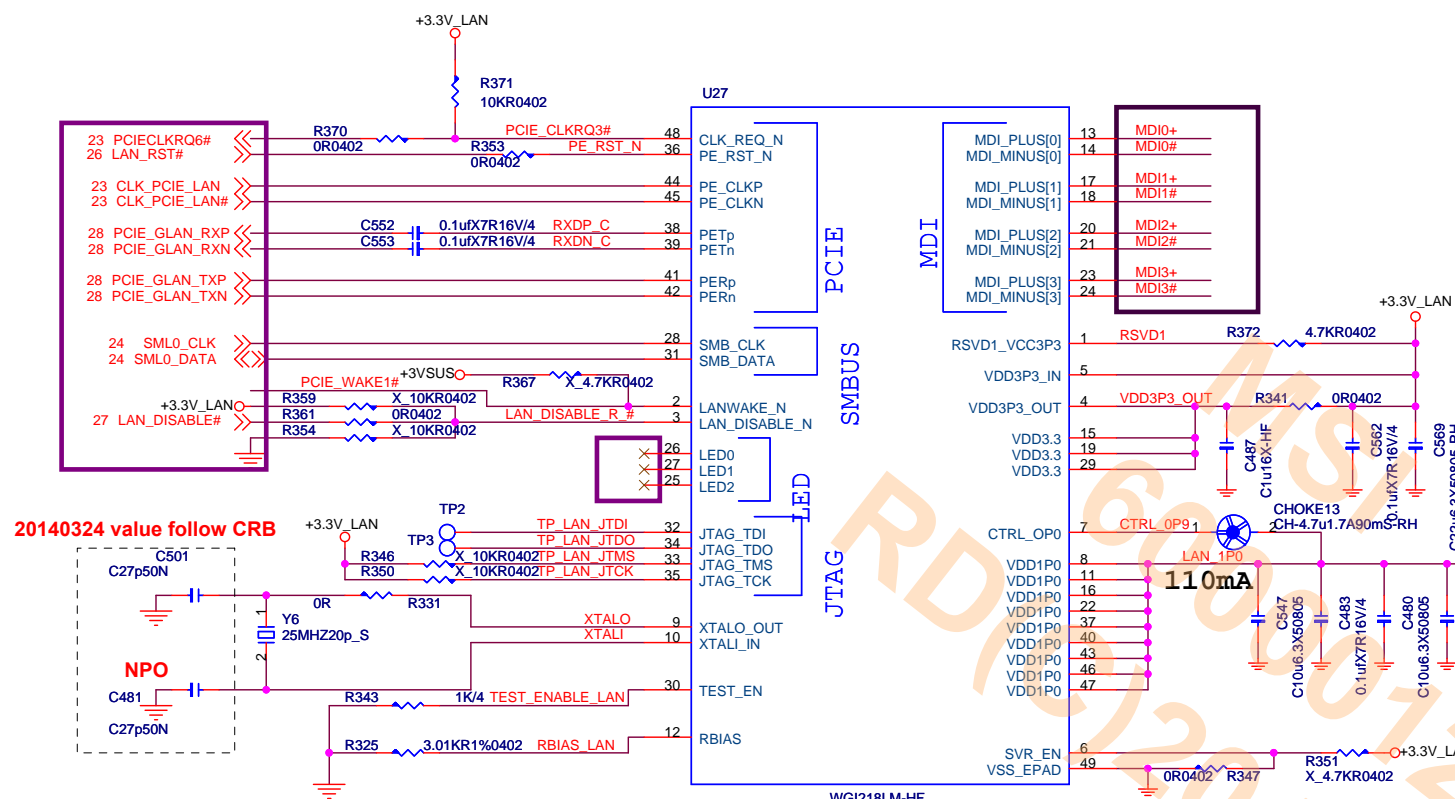
Title
CPU FAN/BTB CONN

Size
Document Number
MS-16H3

Rev
1.0

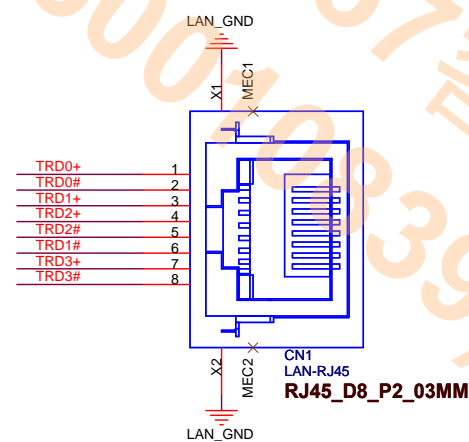
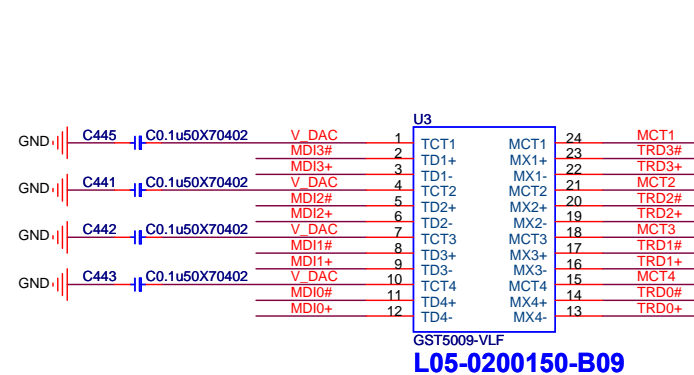
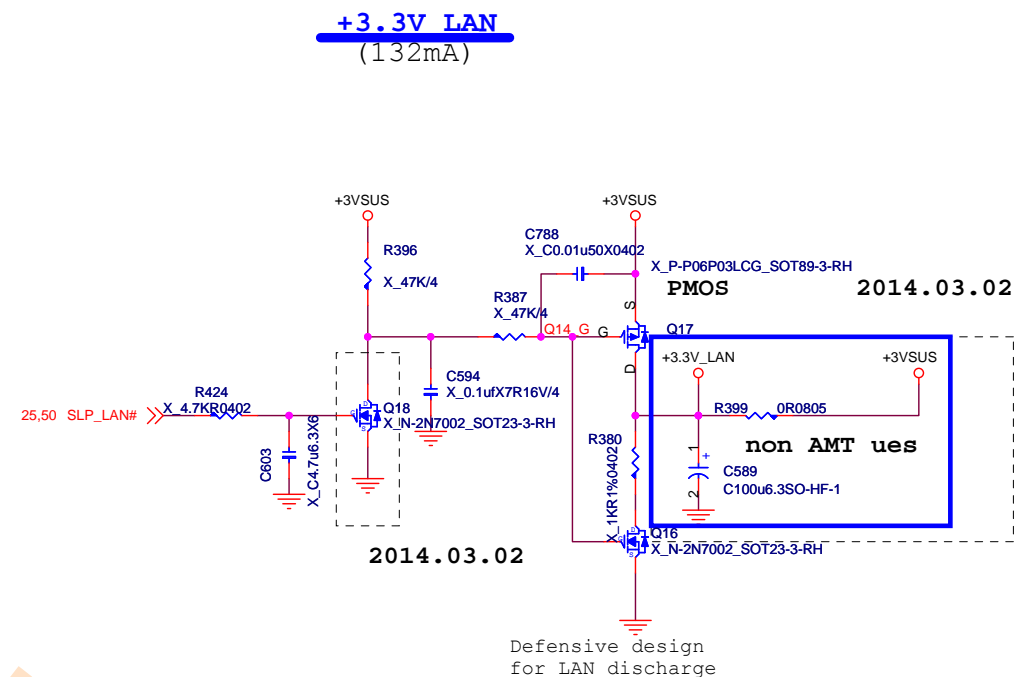
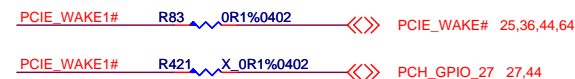
Date: Wednesday, June 25, 2014 Sheet 40 of 69

INTEL Clarkville LAN(I218LM)

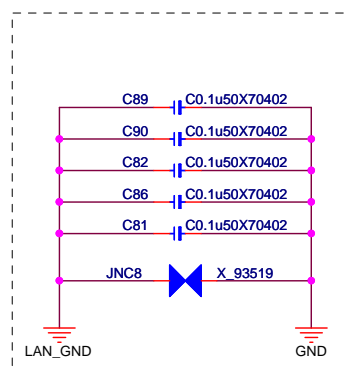
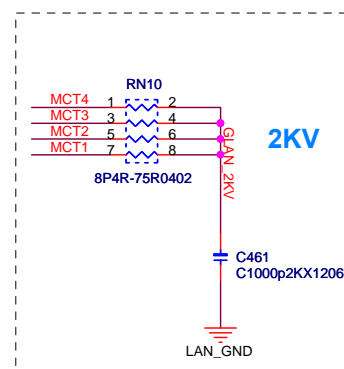
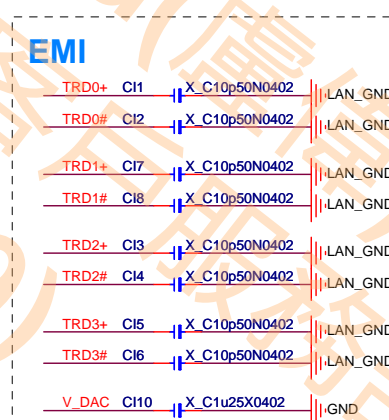


B06-218LM0C-I06

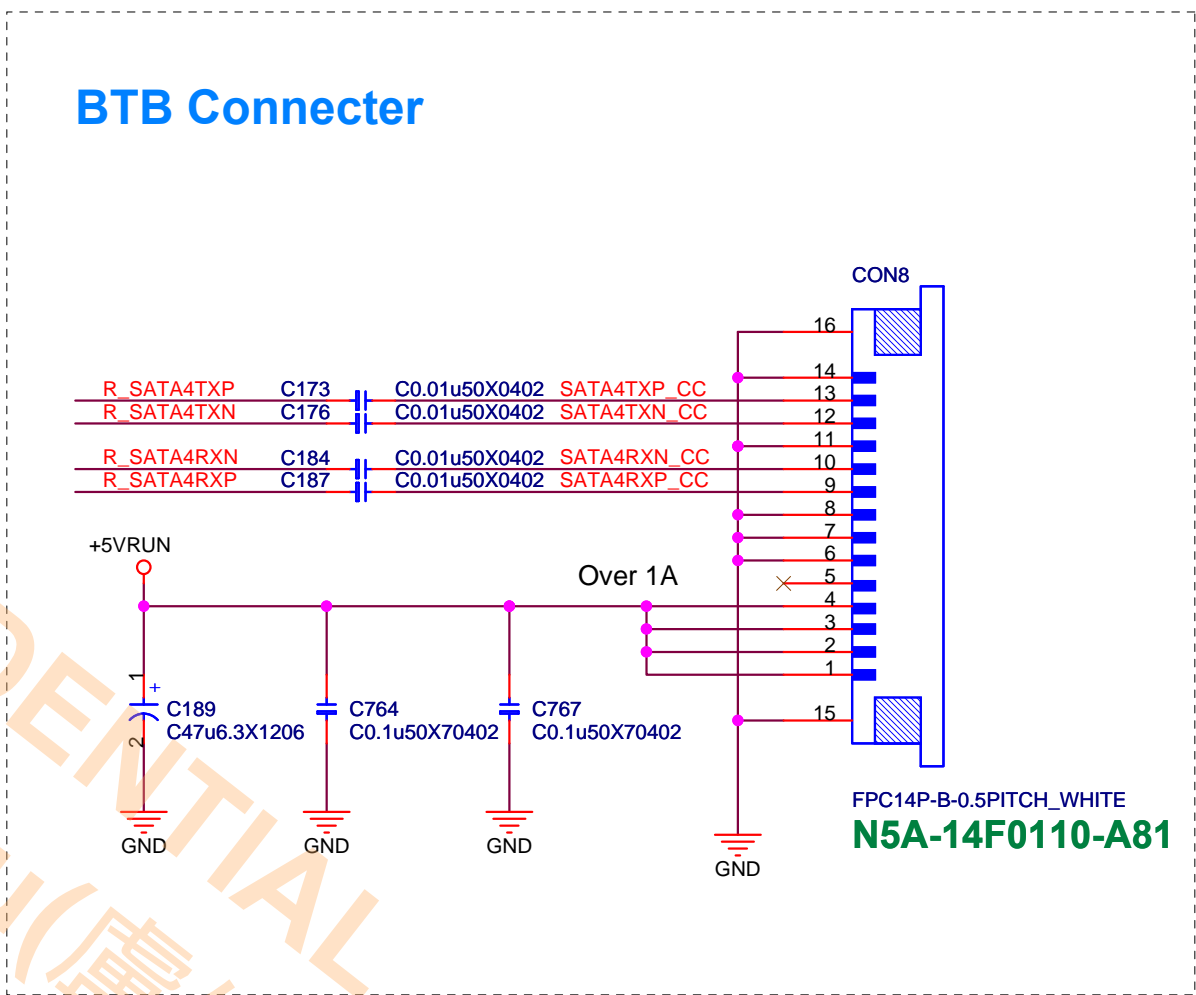
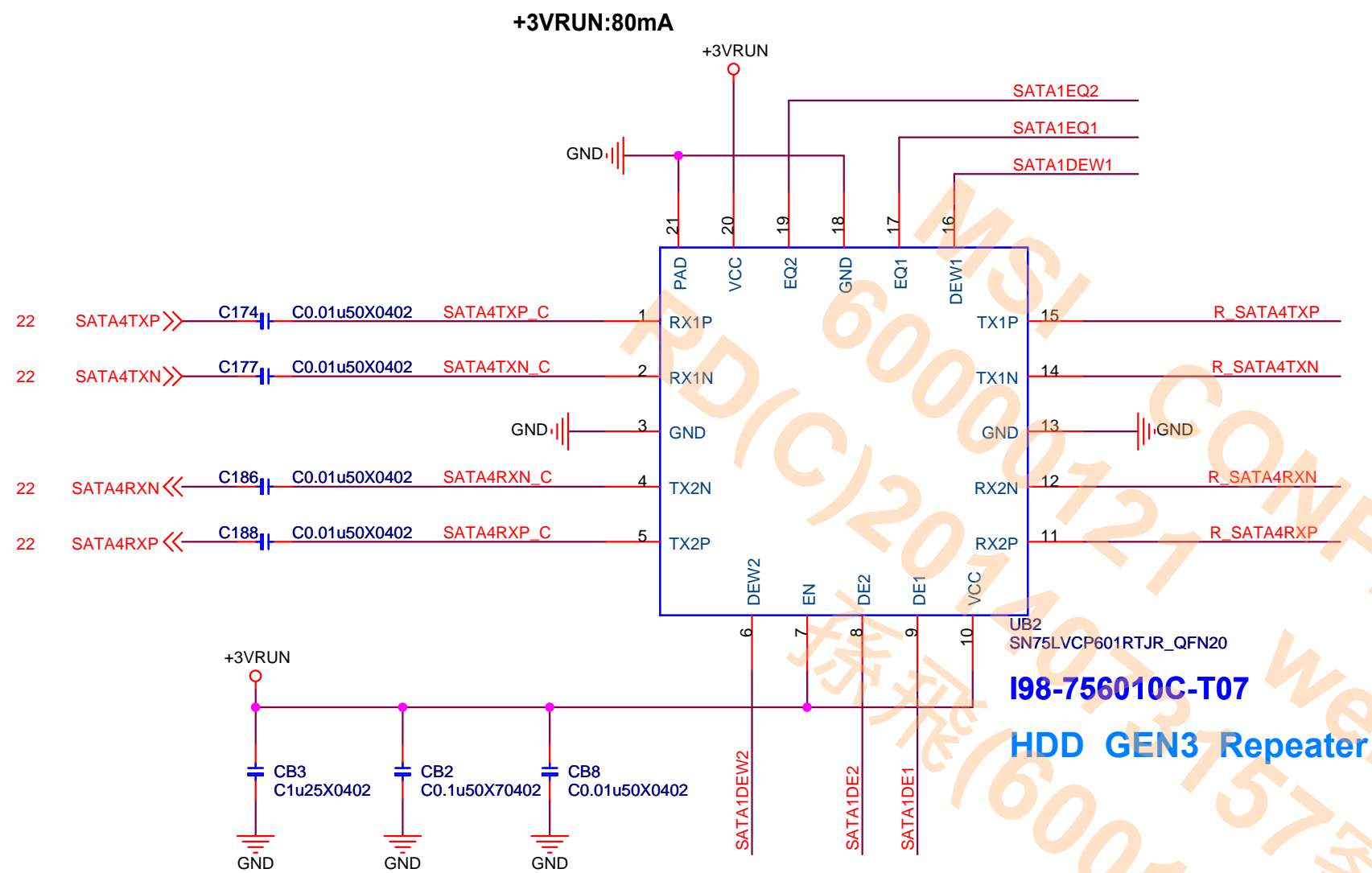
Note that the PHY SMBus address is 0xC and default MAC SMBus address is 0xE0.



N55-08F0691-AF2



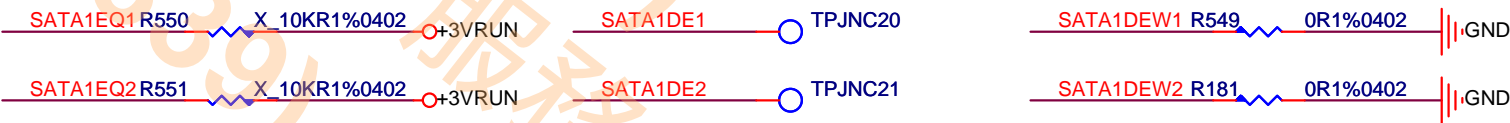
HDD (With Repeater)



TI SN75LVCP601RTJR HW Setting

DE1/DE2	CH1/CH2De-Emphasis dB (at 6Gbps)	EQ1/EQ2	CH1/CH2Equalization dB (at 6Gbps)
NC (<i>default</i>)	-4	NC (<i>default</i>)	0
0	0	0	7
1	-2	1	14

DEW1/DEW2	Device Function → DE Width for CH1/CH2
0	De-emphasis pulse duration, short (recommended setting when link operates at SATA 1.5/3/6 Gbps)
1 (<i>default</i>)	De-emphasis pulse duration, long (recommended setting when link operates at SATA 1.5/3 Gbps speed only)



MICRO-STAR INT'L CO.,LTD.

Title

HDD With Repeater

Size

Document Number

MS-16H3

Date

Wednesday, June 25, 2014

Sheet

42

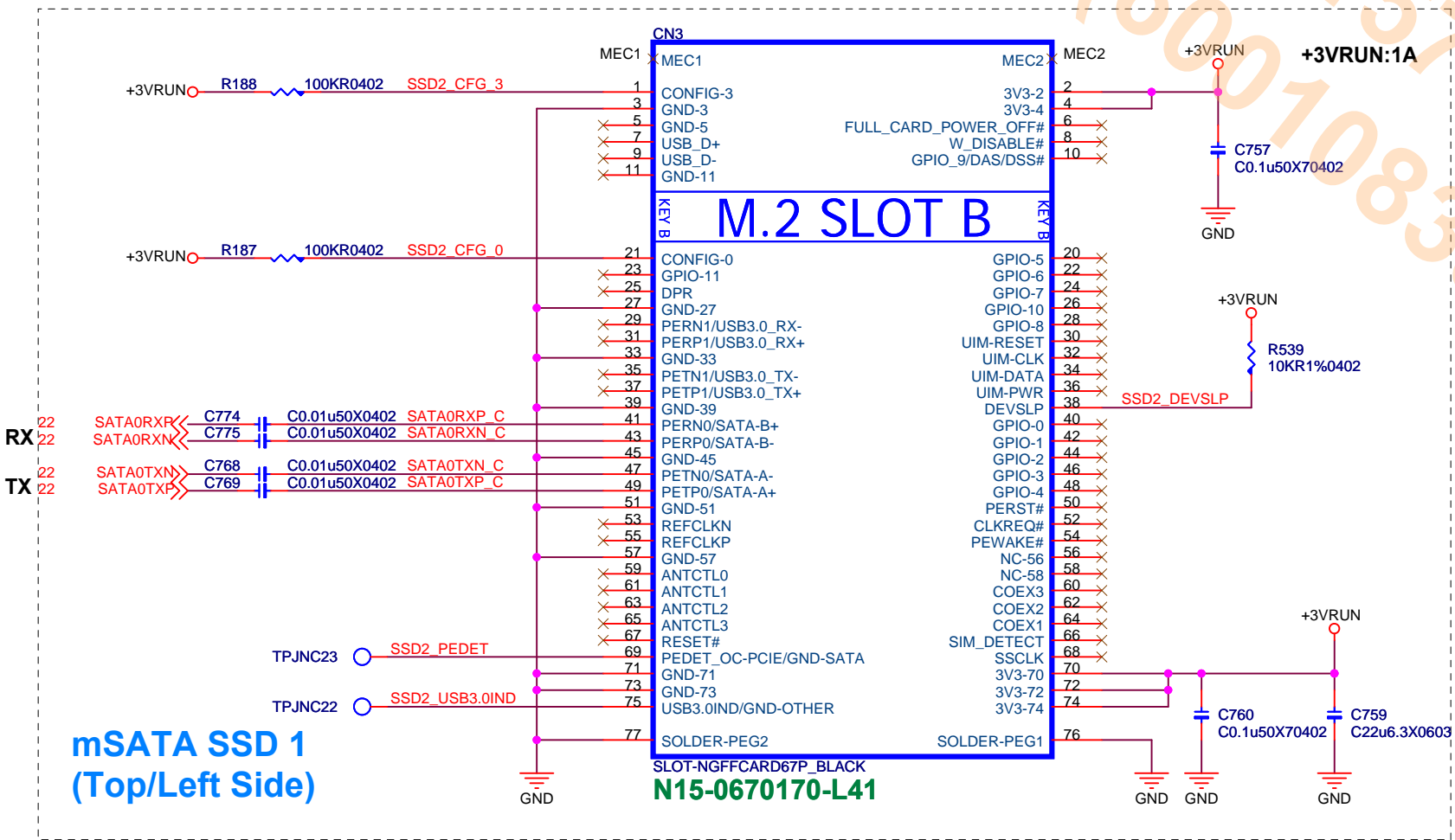
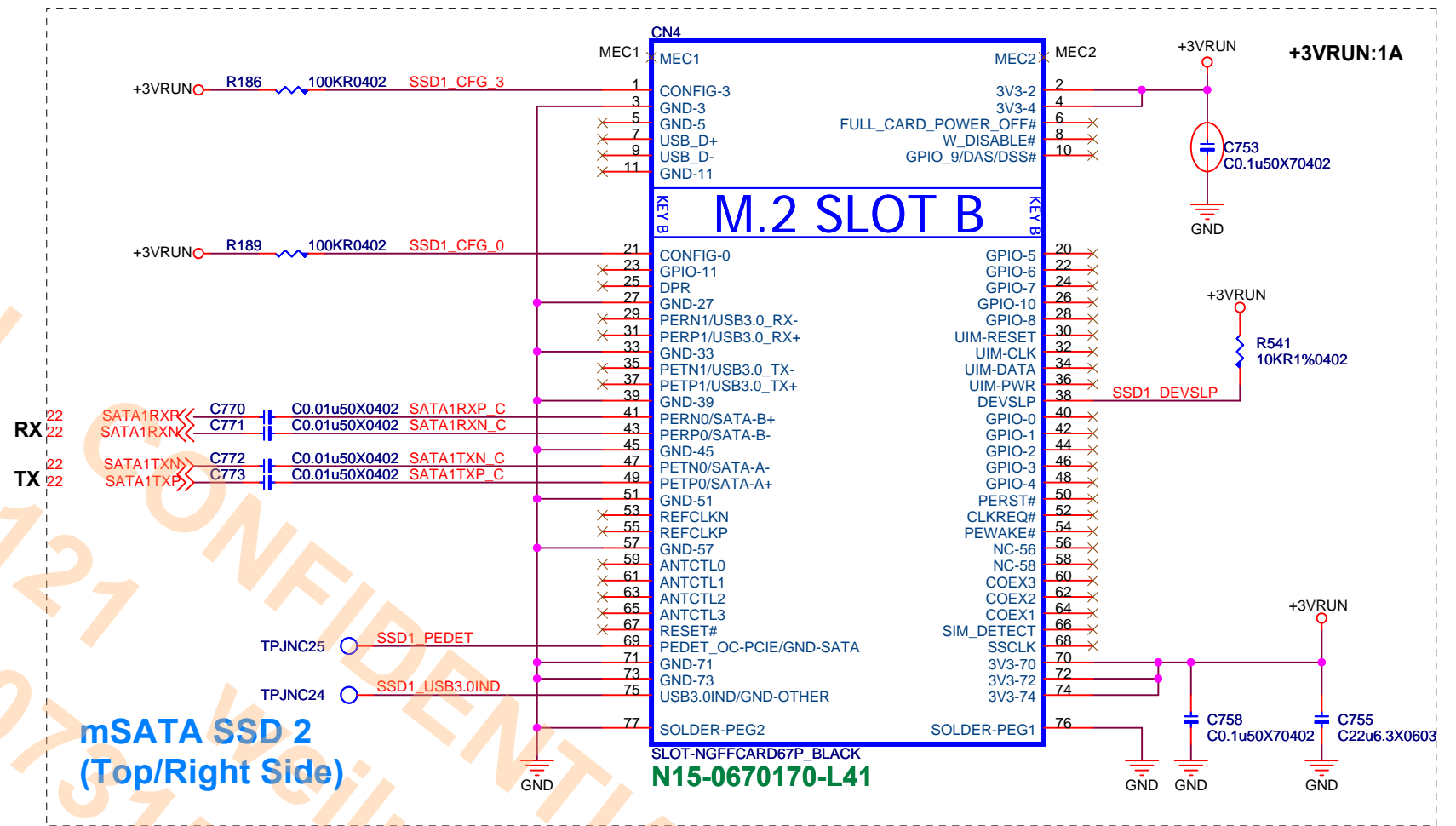
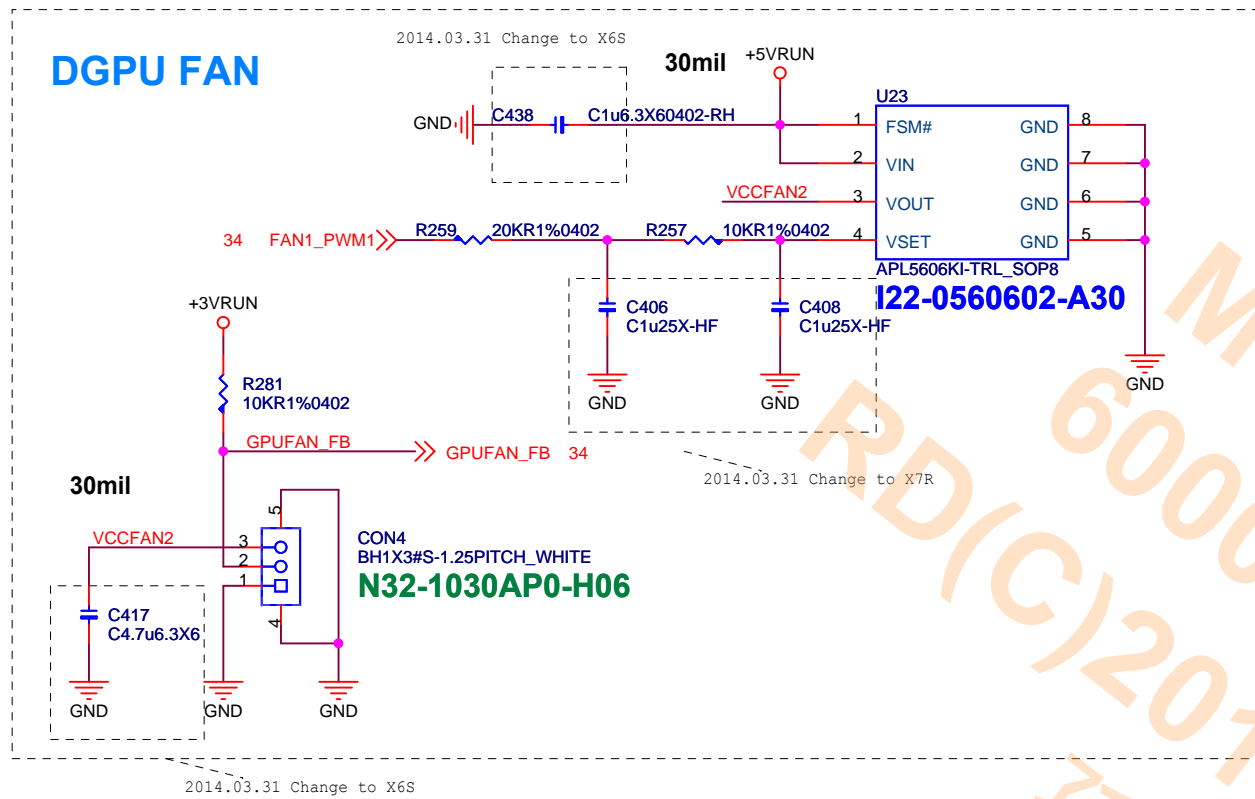
of

69

Rev

1.0

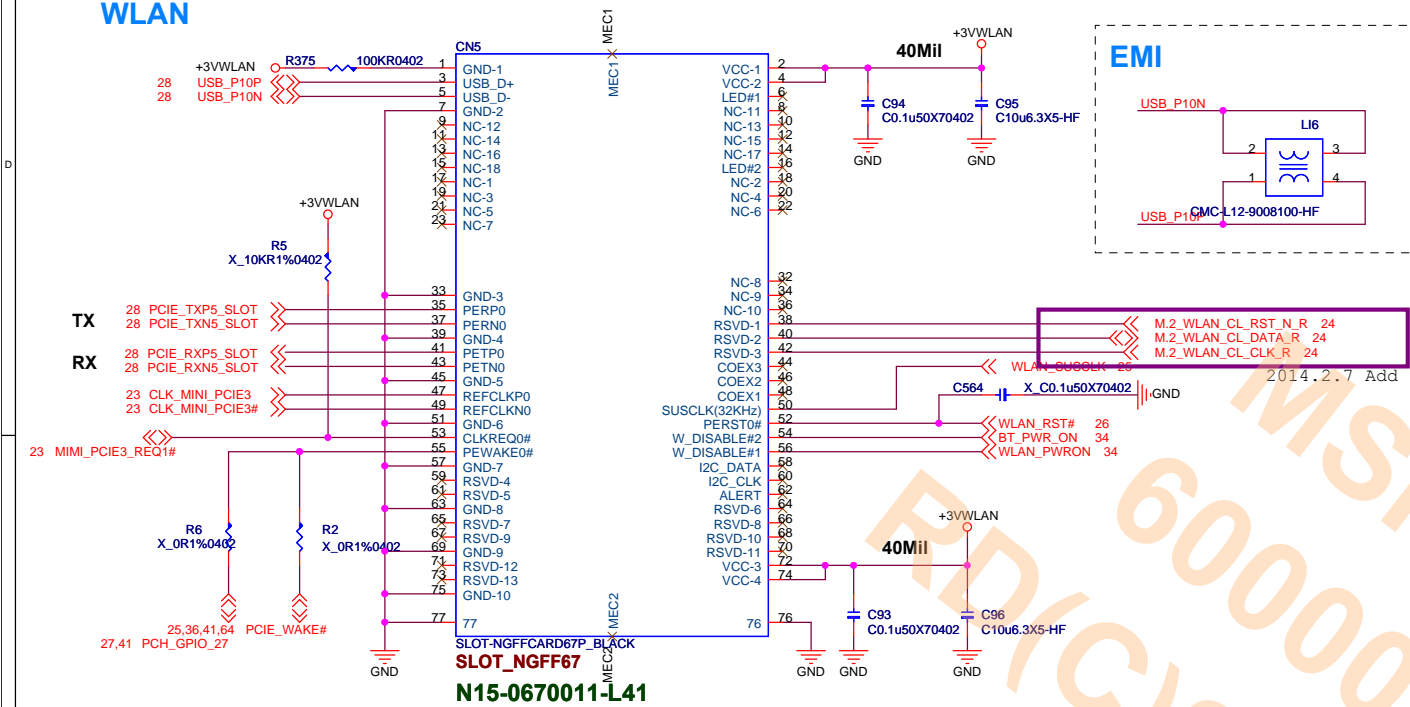
SSD/ DGPU FAN



40	NC	No Connect
41	SATA-B+/PERn0	Host receiver differential signal pair
42	NC	No Connect
43	SATA-B-/PERp0	Host receiver differential signal pair
44	NC	No Connect
45	GND	Ground
46	NC	No Connect
47	SATA-A-/PETn0	Host Transmitter differential signal pair
48	NC	No Connect
49	SATA-A+/PETp0	Host transmitter differential signal pair

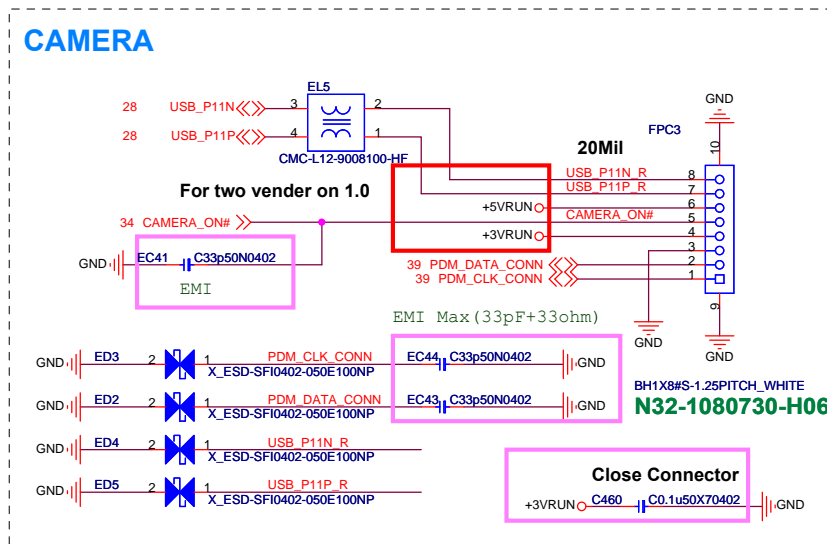
WLAN /Camera/ClickPad/FP

WLAN

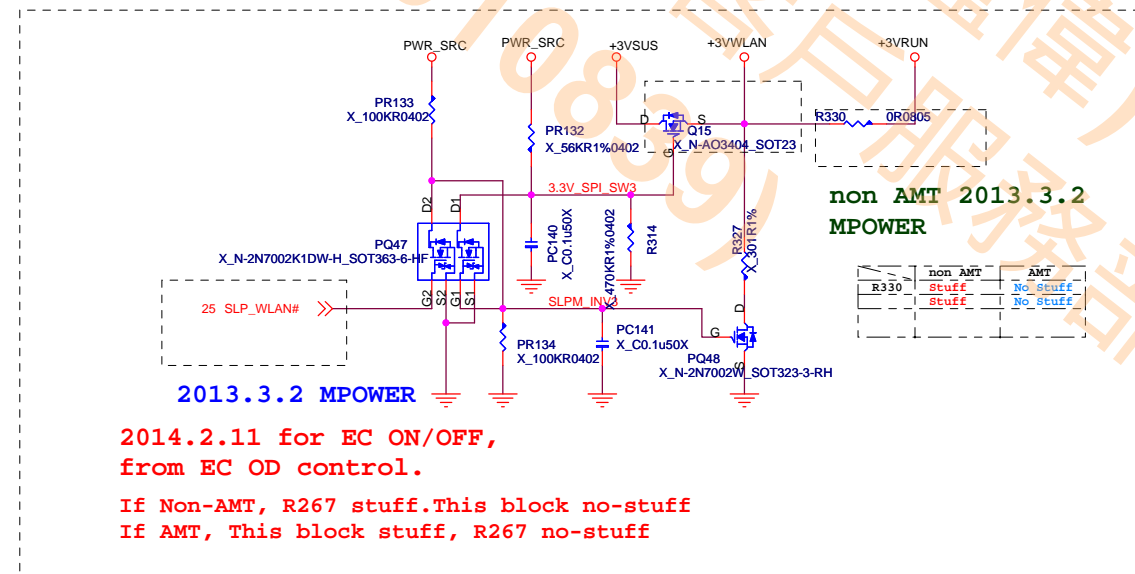
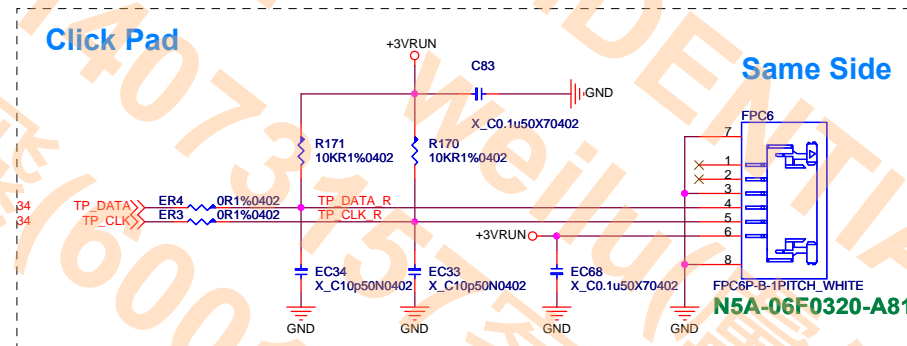


Pin 1	GND	Pin 2	3.3V
Pin 3	USB_D+	Pin 4	3.3V
Pin 5	USB_D-	Pin 6	LED1#
Pin 7	GND	Pin 8	Module Key
Pin 9	Module Key	Pin 10	Module Key
Pin 11	Module Key	Pin 12	Module Key
Pin 13	Module Key	Pin 14	Module Key
Pin 15	Module Key	Pin 16	LED2#
Pin 17	N/C	Pin 18	GND
Pin 19	N/C	Pin 20	N/C
Pin 21	N/C	Pin 22	N/C
Pin 23	N/C	Pin 24	Module Key
Pin 25	Module Key	Pin 26	Module Key
Pin 27	Module Key	Pin 28	Module Key
Pin 29	Module Key	Pin 30	Module Key
Pin 31	Module Key		
Pin 33	GND	Pin 32	N/C
Pin 35	PERP0	Pin 34	N/C
Pin 37	PERN0	Pin 36	N/C
Pin 39	GND	Pin 38	Clink Reset (I 3.3V)
Pin 41	PETP0	Pin 40	N/C
Pin 43	PETN0	Pin 42	N/C
Pin 45	GND	Pin 44	N/C
Pin 47	REFCLKP0	Pin 46	N/C
Pin 49	REFCLKN0	Pin 48	N/C
Pin 51	GND	Pin 50	N/C (SUSCLK (32kHz) for DSx)
Pin 53	CLKREQ0#	Pin 52	PERST0#
Pin 55	PEWAKE0#	Pin 54	BT_EN(W_DISABLE2#)
Pin 57	GND	Pin 56	WLAN_EN(W_DISABLE2#)
Pin 59	N/C	Pin 58	N/C
Pin 61	N/C	Pin 60	N/C
Pin 63	N/C	Pin 62	N/C
Pin 65	N/C	Pin 64	Receiver
Pin 67	N/C	Pin 66	N/C
Pin 69	GND	Pin 68	N/C
Pin 71	N/C	Pin 70	N/C
Pin 73	N/C	Pin 72	3.3V
Pin 75	GND	Pin 74	3.3V

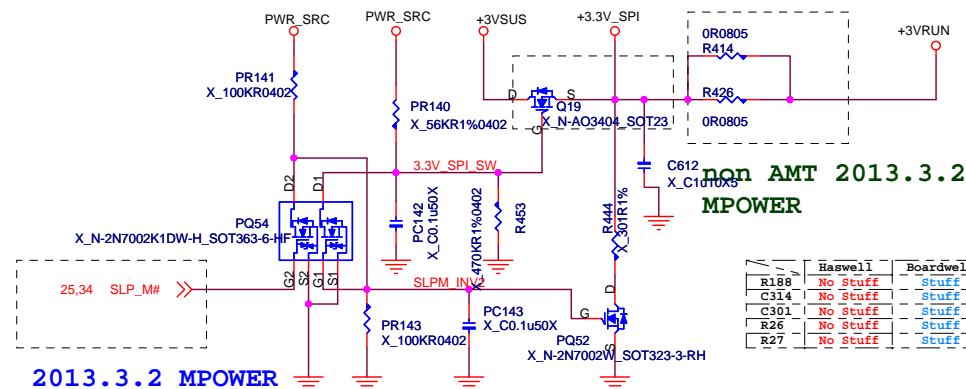
CAMERA



Click Pad

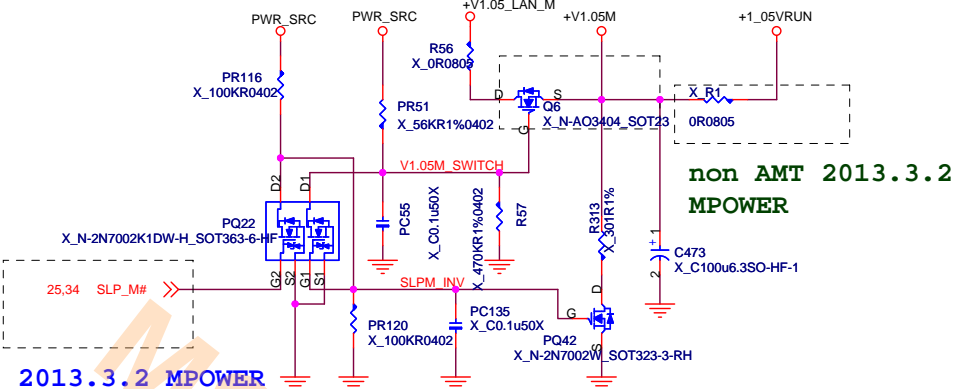


2A in 2013.3.2 +3.3V_SPI MPOWER



	Haswell	Boardwell
R188	No Stuf	Stuf
C314	No Stuf	Stuf
C301	No Stuf	Stuf
R26	No Stuf	Stuf
R27	No Stuf	Stuf

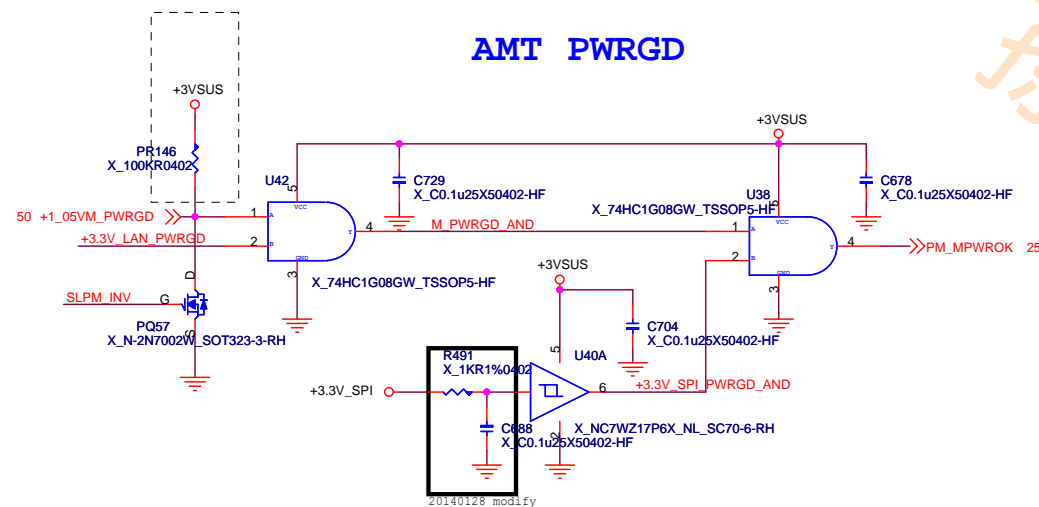
+V1.05M MPOWER



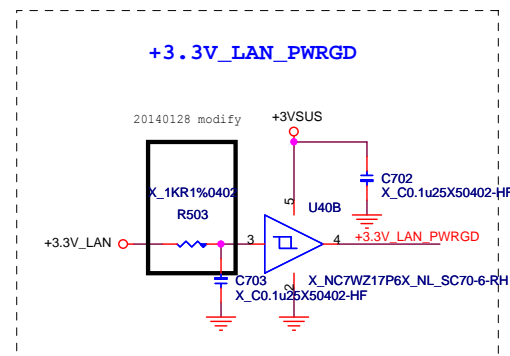
請靠近 PCH

2013.3.2 for AMT

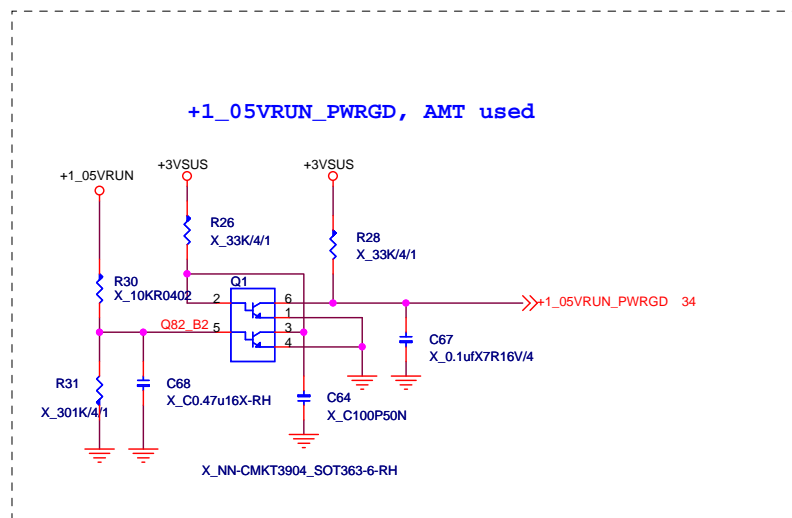
AMT PWRGD



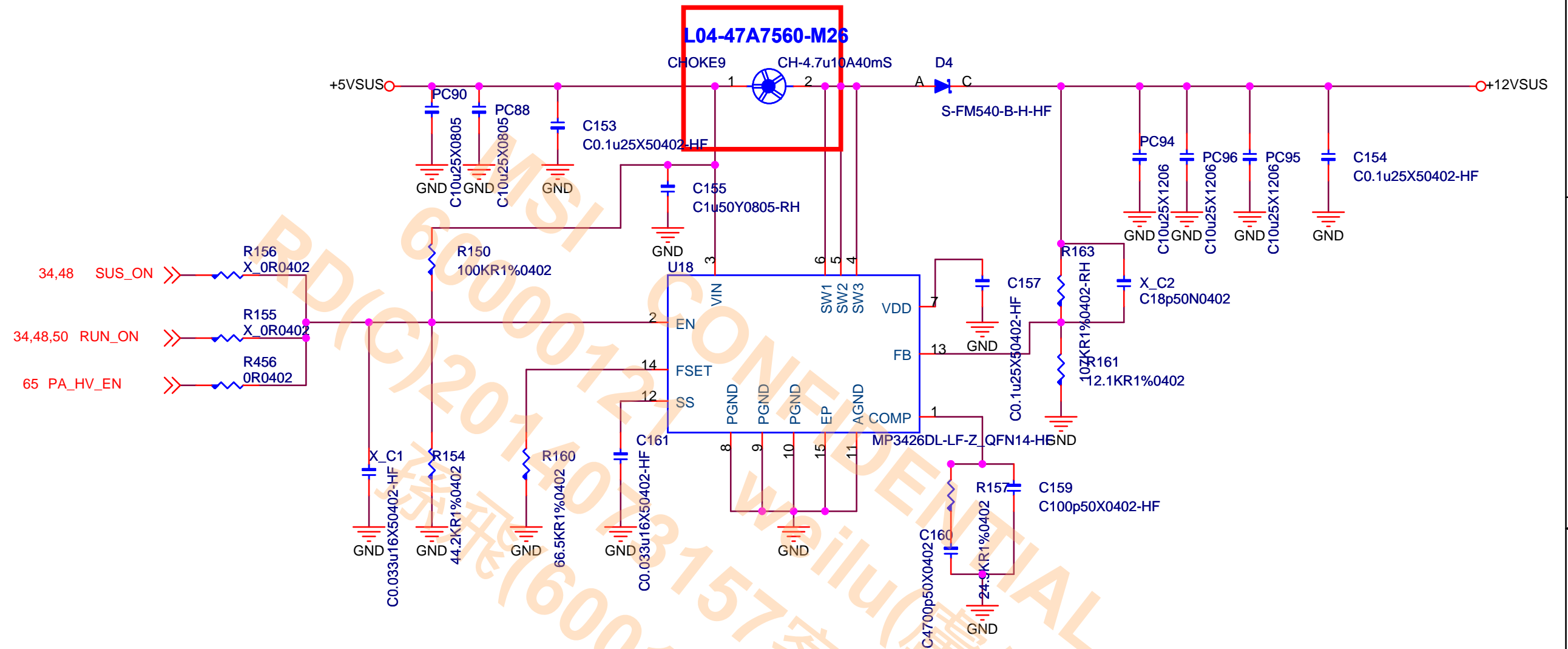
+3.3V_LAN_PWRGD



+1_05VRUN_PWRGD, AMT used

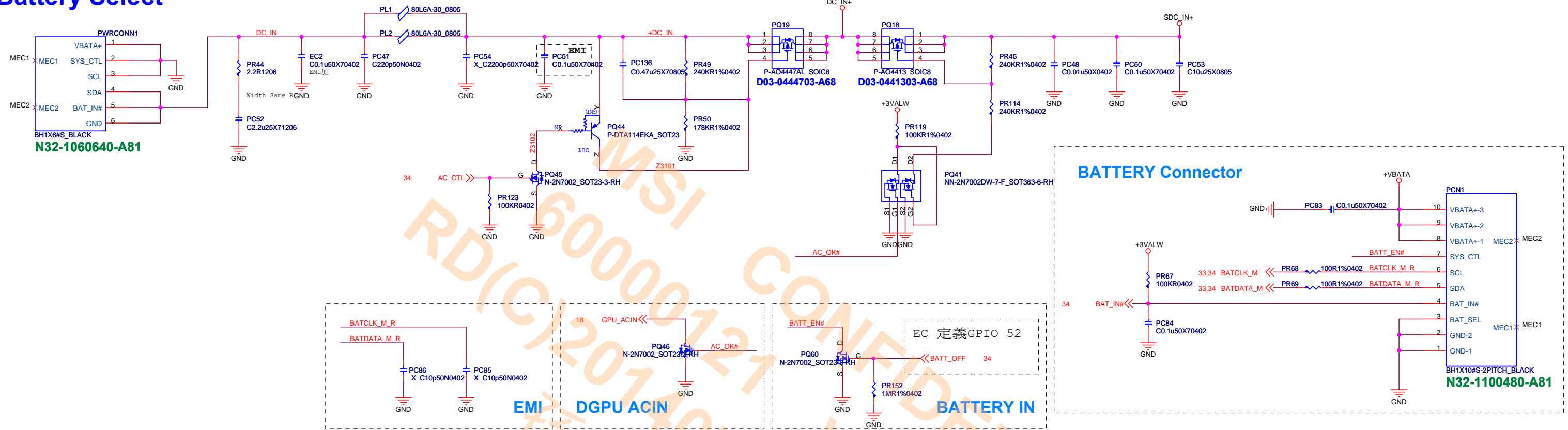


TBT Power 5V Boost 12V 1A

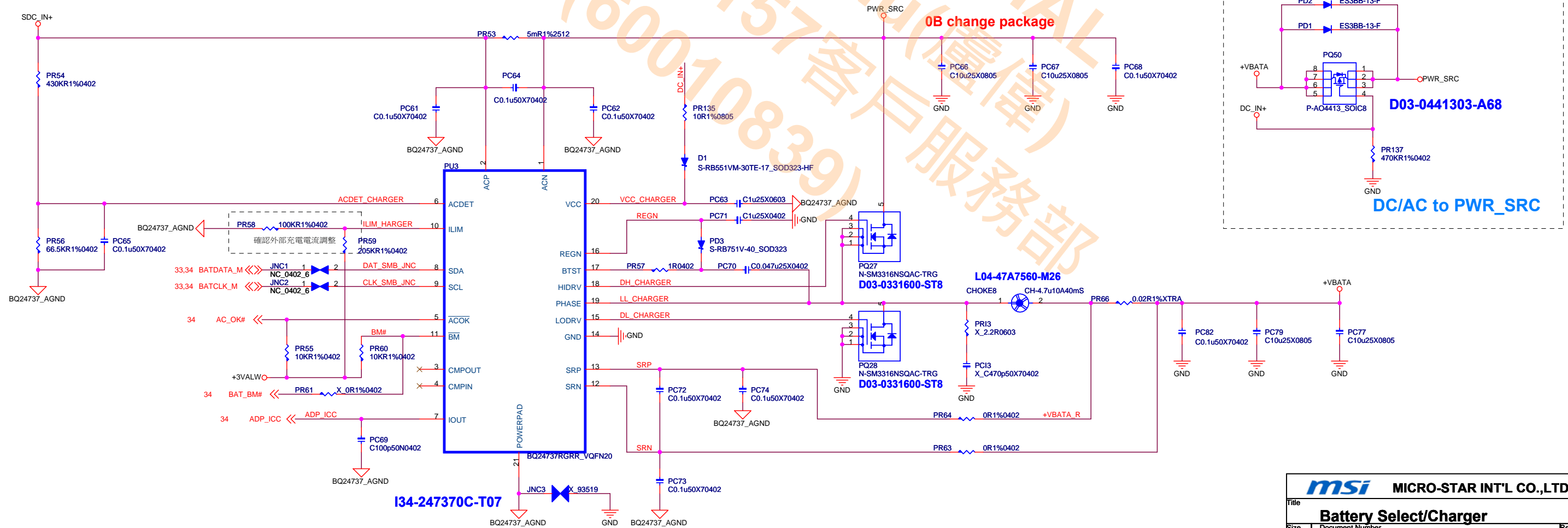


Battery Select/Charger

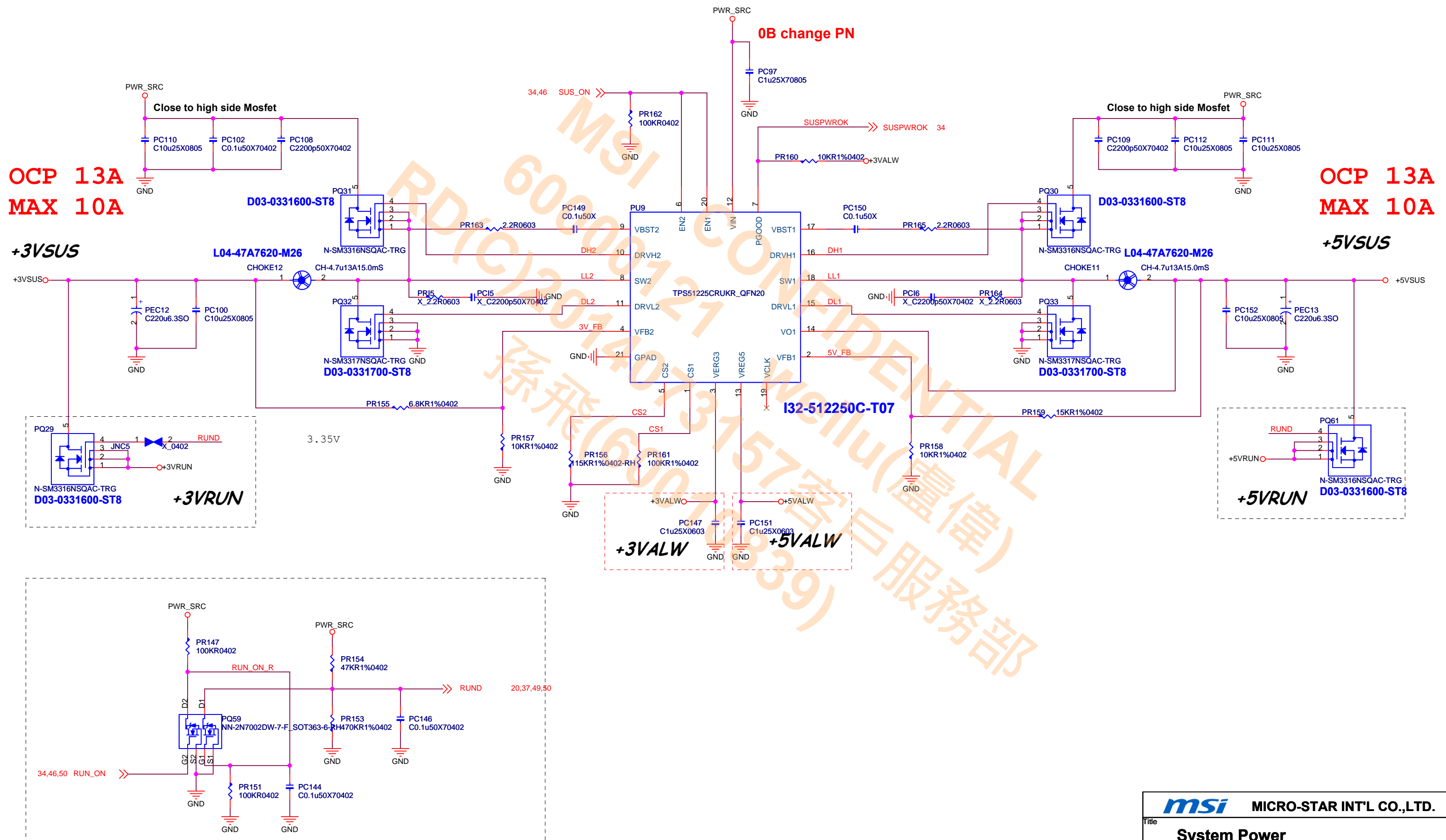
Battery Select



Battery Charger

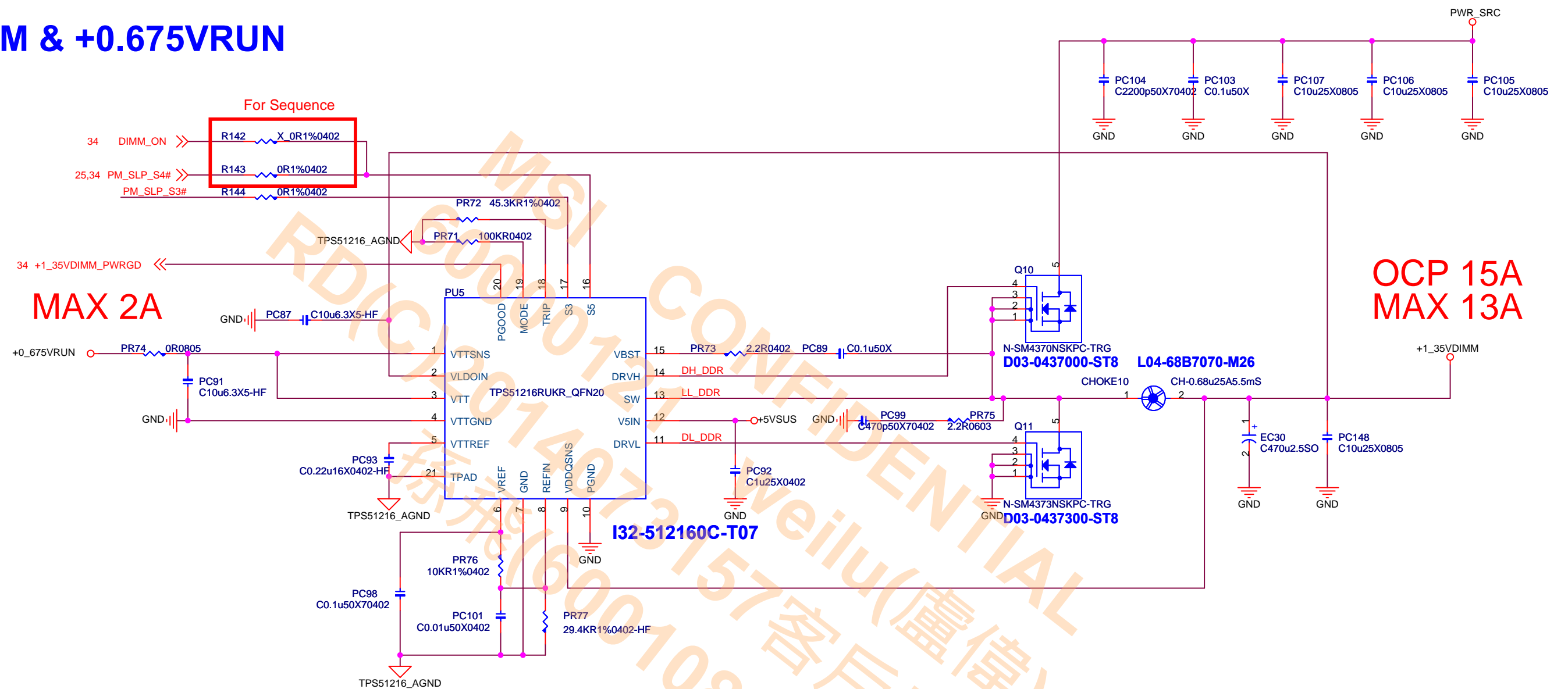


System Power

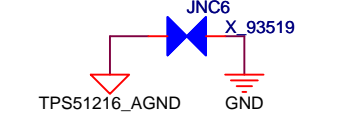
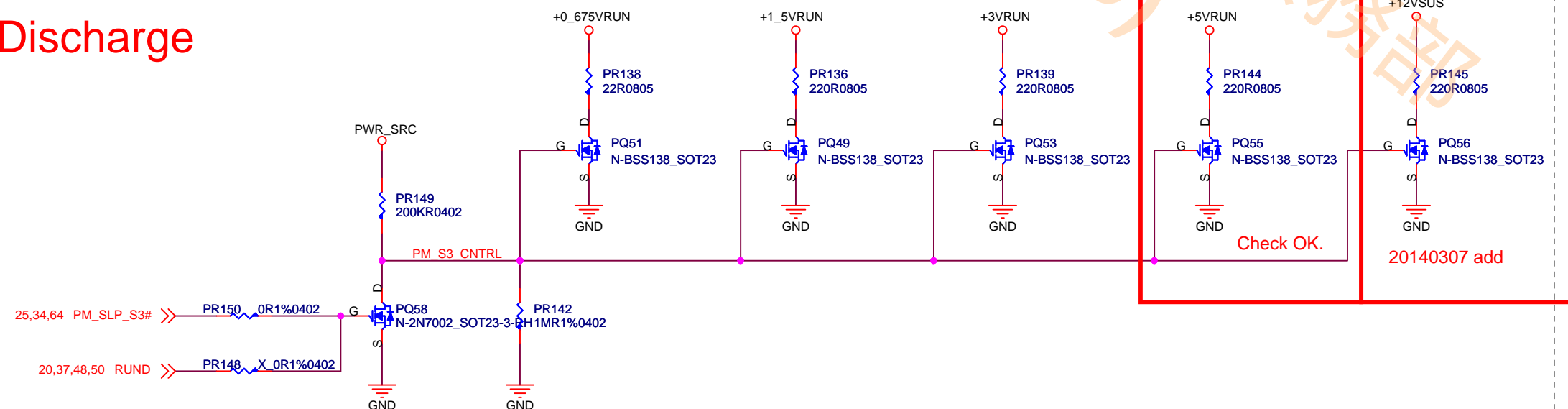


+1.35VDIMM/+0.675VRUN

+1.35VDIMM & +0.675VRUN



Discharge



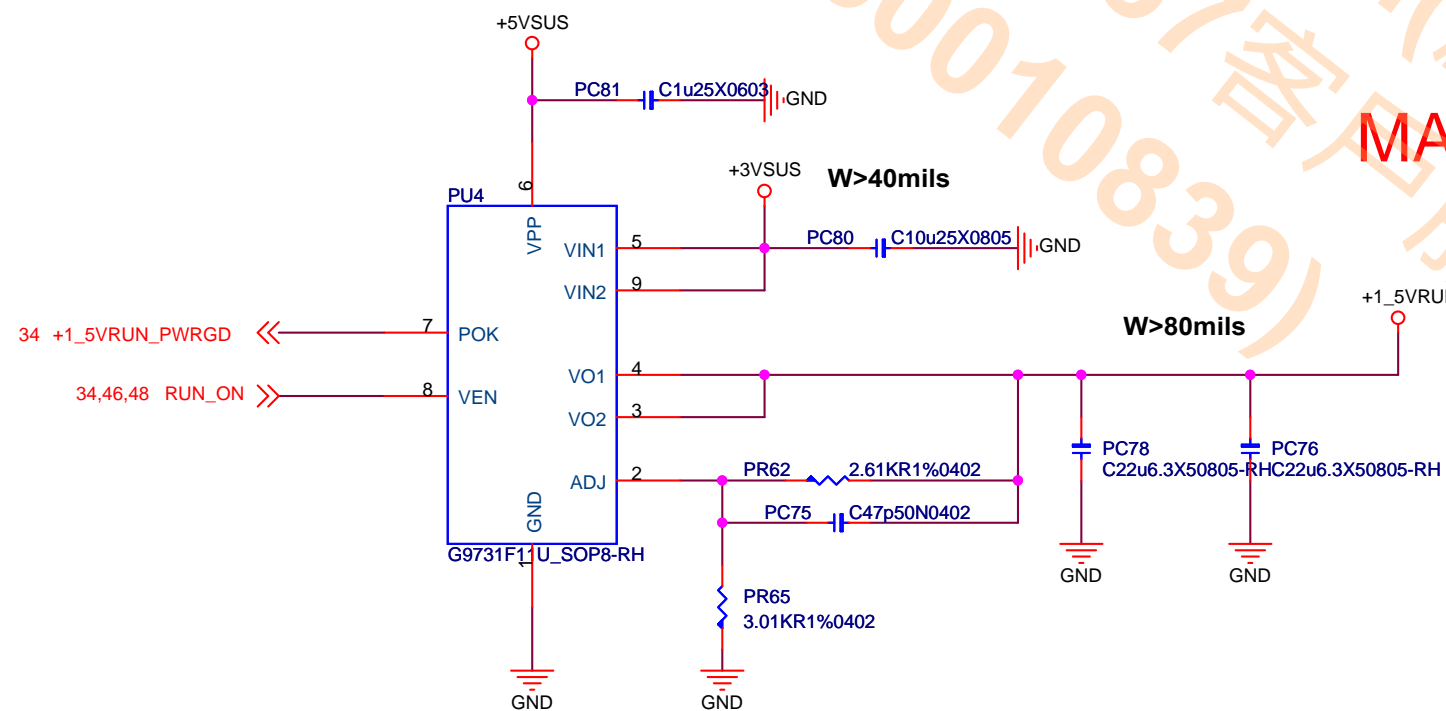
+1.05VRUN

+1_05VRUN / +1_5VRUN



+1.5V_{RUN}

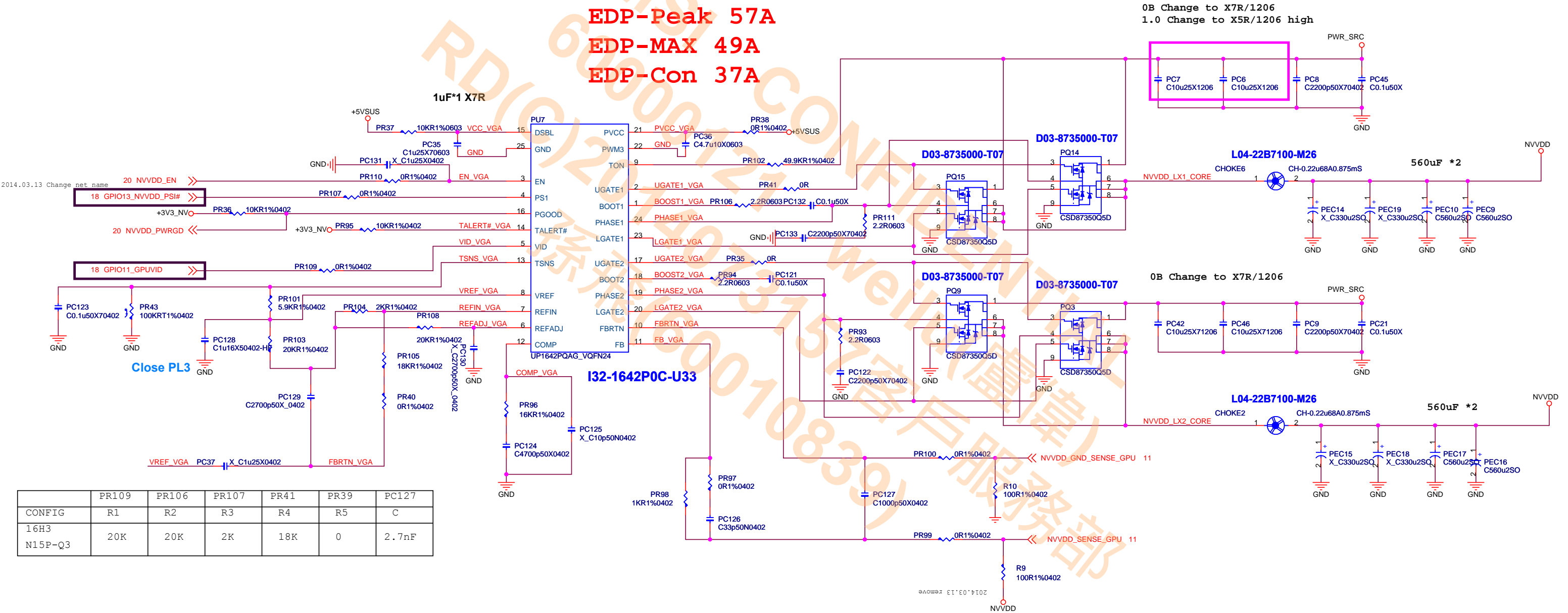
MAX 2A



DGPU POWER / UP1642PQAG

CONFIG B
V_{Boot}:0.9V
V_{min}:0.6V / V_{max}:1.2V

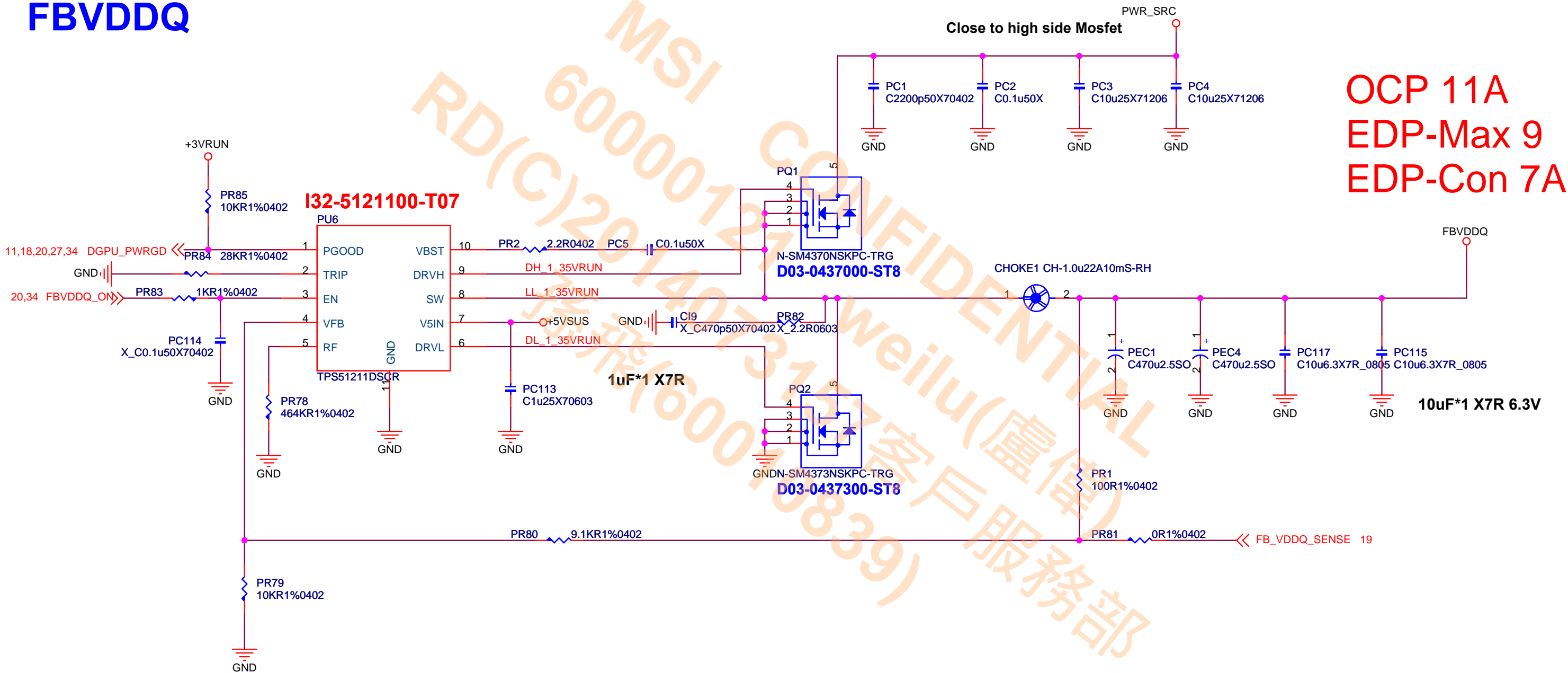
EDP-Peak 57A
EDP-MAX 49A
EDP-Con 37A



	PR109	PR106	PR107	PR41	PR39	PC127
CONFIG	R1	R2	R3	R4	R5	C
16H3 N15P-Q3	20K	20K	2K	18K	0	2.7nF

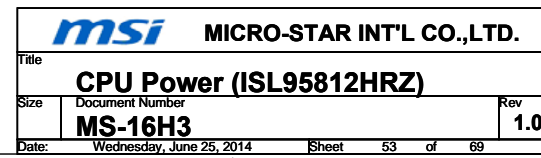
DGPU POWER FBVDDQ

FBVDDQ

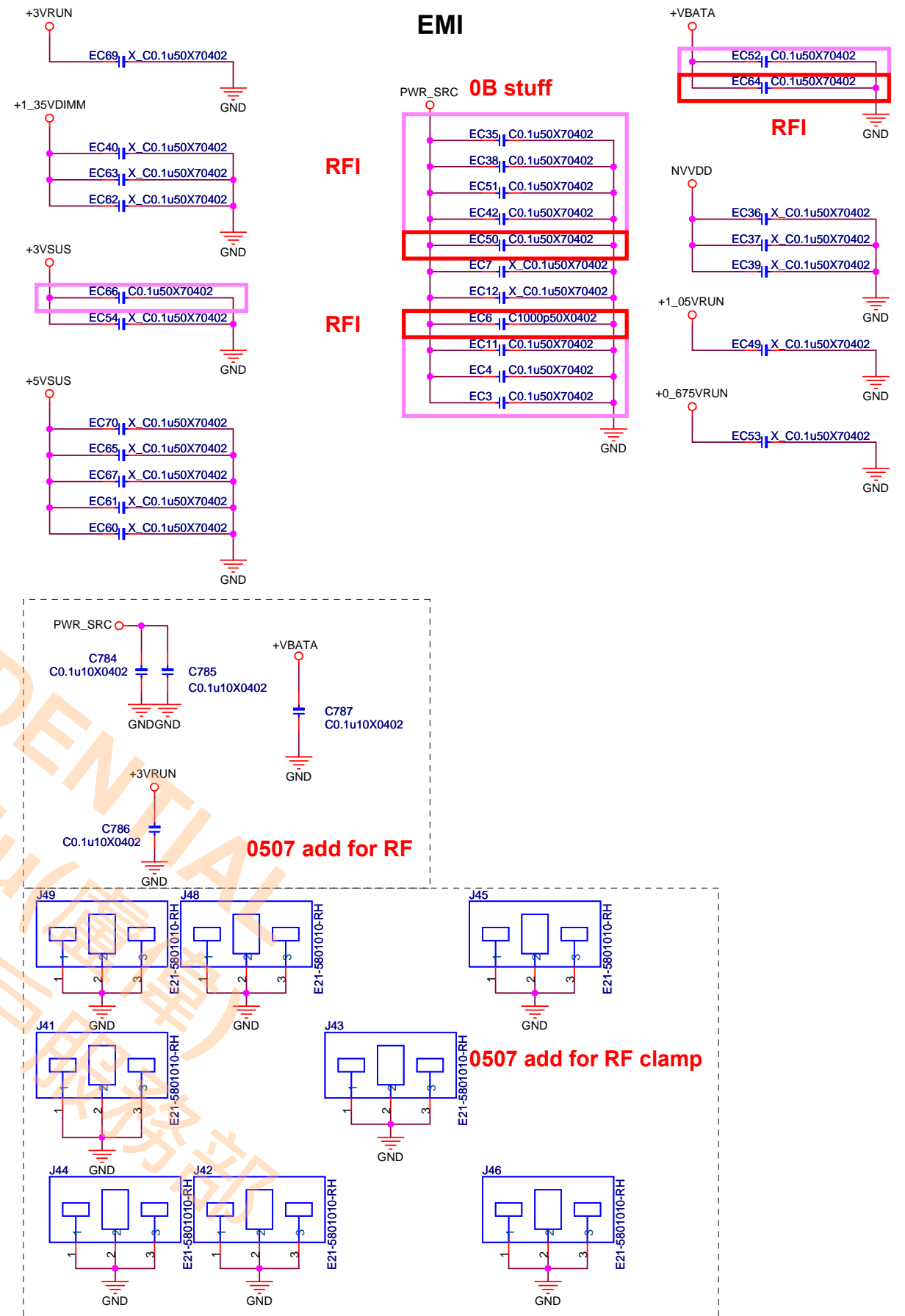


CPU Power (+VCC_CORE)

+VCC_CORE

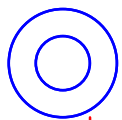


EMI/ Impedance

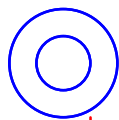


CPU/GPU Holes

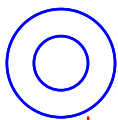
MCPU4
H_R200D150



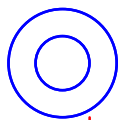
MCPU2
H_R200D150



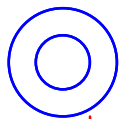
MCPU3
H_R200D150



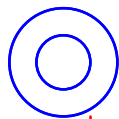
MCPU1
H_R200D150



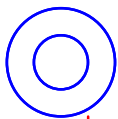
MGPU2
H_R276D169_PB



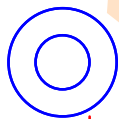
MGPU4
H_R276D169_PB



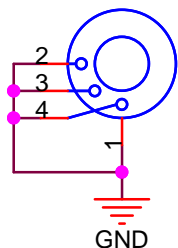
MGPU1
H_R276D169_PB



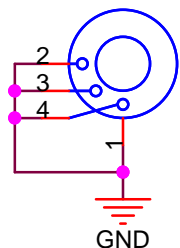
MGPU3
H_R276D169_PB



M1
X_H_R197D118_PT_V3
H_R197D118_PT_V3

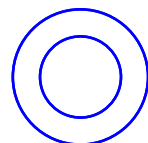


M6
X_H_R197D118_PT_V3
H_R197D118_PT_V3



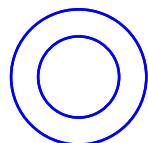
Fan Hole

MH4
H_R197D91
X_ME_SCREW HOLE

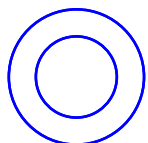


SSD Stand off

MH2
H_R220D146_PTB
E2B-16H2020



MH1
H_R220D146_PTB
E2B-16H2020



EMI

SPRING3
X_MECHCU,2.5*5.5*0.1mm

SPRING2
X_E2M-7213211-RH



GND
E2M-7213211-CA7



GND
E2M-2142011-CA7

SPRING1
X_E23-1029060-RH



GND
E23-1029060-CA7

SPRING4
X_E2M-7213211-RH



GND
E2M-7213211-CA7

MYLAR2



E2P-6H23111-Y42

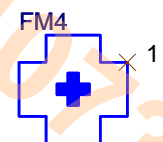
MYLAR

MYLAR3

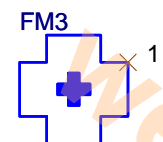


E2P-6H22711-Y42

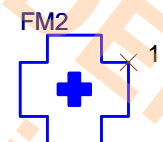
MYLAR



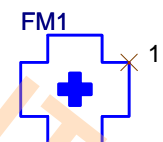
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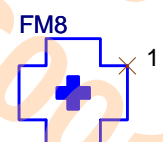
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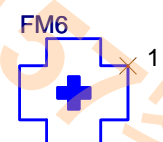
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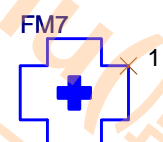
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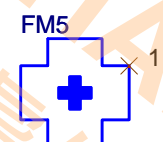
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1



1



1

RUBBER1



E2Y-6H20712-Y40

RUBBER

RUBBER2



E2Y-6H21312-Y40

RUBBER

RUBBER3



E2Y-6H21312-Y40

RUBBER

BRACKET1



307-6H20111-C22

CPU_BRACKET

BRACKET2



307-6H20111-C22

CPU_BRACKET

BRACKET3



307-6H20211-C22

GPU_BRACKET

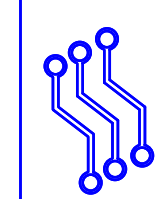
MYLAR1



E2P-6H22111-Y42

MYLAR

PCB1



PF0-16H3110-H73

PF0-16H3110-H73

Hannstar: PF0-16H2110-H73

TRIPOD: PF0-16H2110-T53

MYLAR4



E2P-6G13911-Y42

MYLAR

MYLAR5



E2P-6H30111-Y42

MYLAR

MYLAR6



E2P-6H30211-Y42

MYLAR

UME1

HDMI
Lable

HDMI ROYALTY

Y01-RHDMI03-000

For MP

UME2

BIOS
Lable

BIOS_LABEL

G51-LA01678-A09

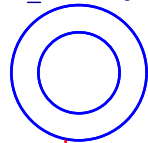
MYLAR7



E2Y-X043611-CA7

Gaste

MH3
NPTH157
X_NPTH157



msi

MICRO-STAR INT'L CO.,LTD.

Title

Screw/ME

Size

Document Number

MS-16H3

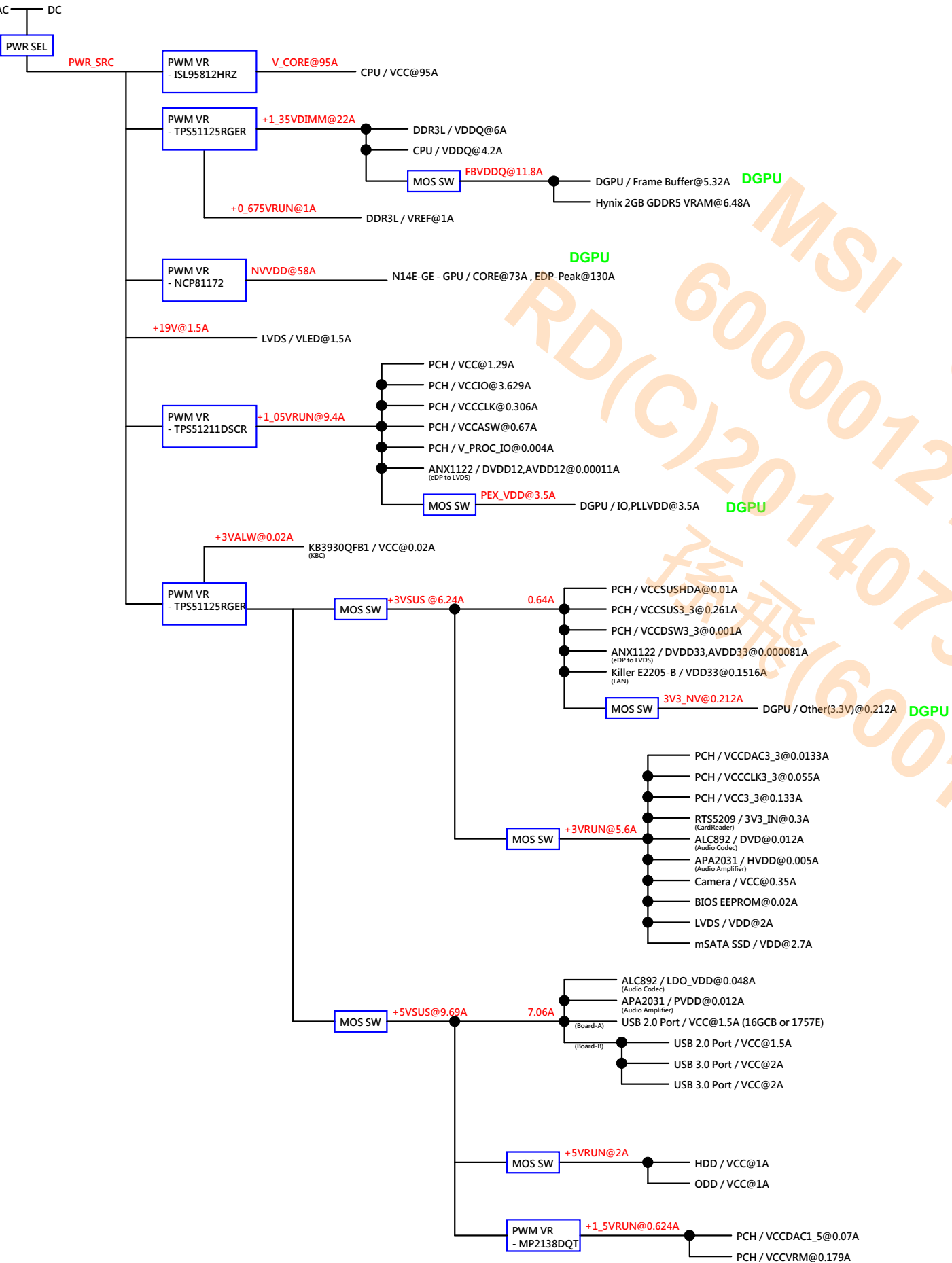
Rev

1.0

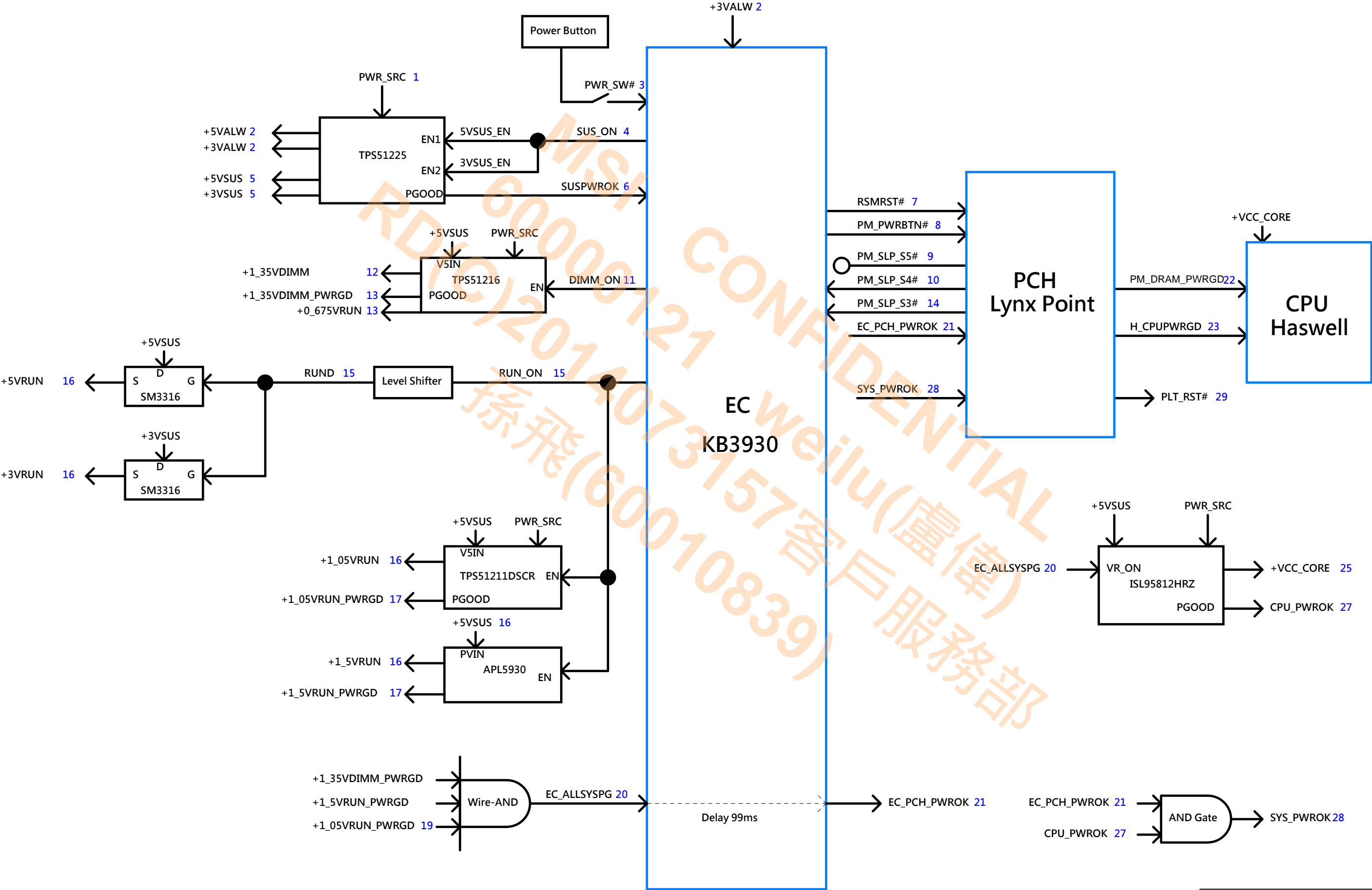
Date: Wednesday, June 25, 2014

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MS-16H2 Power Delivery Chart

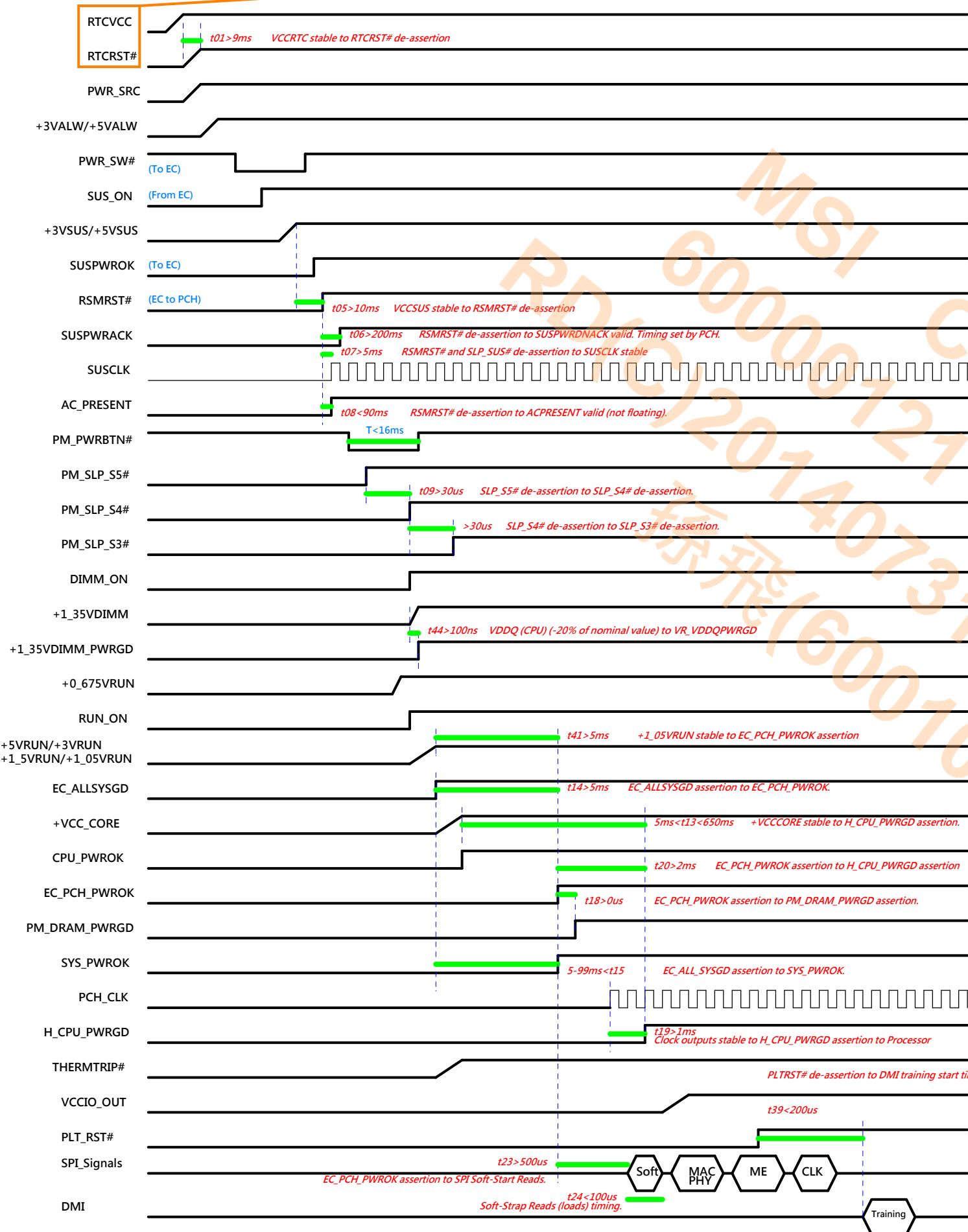


MS-16H2 Power on Block Diagram

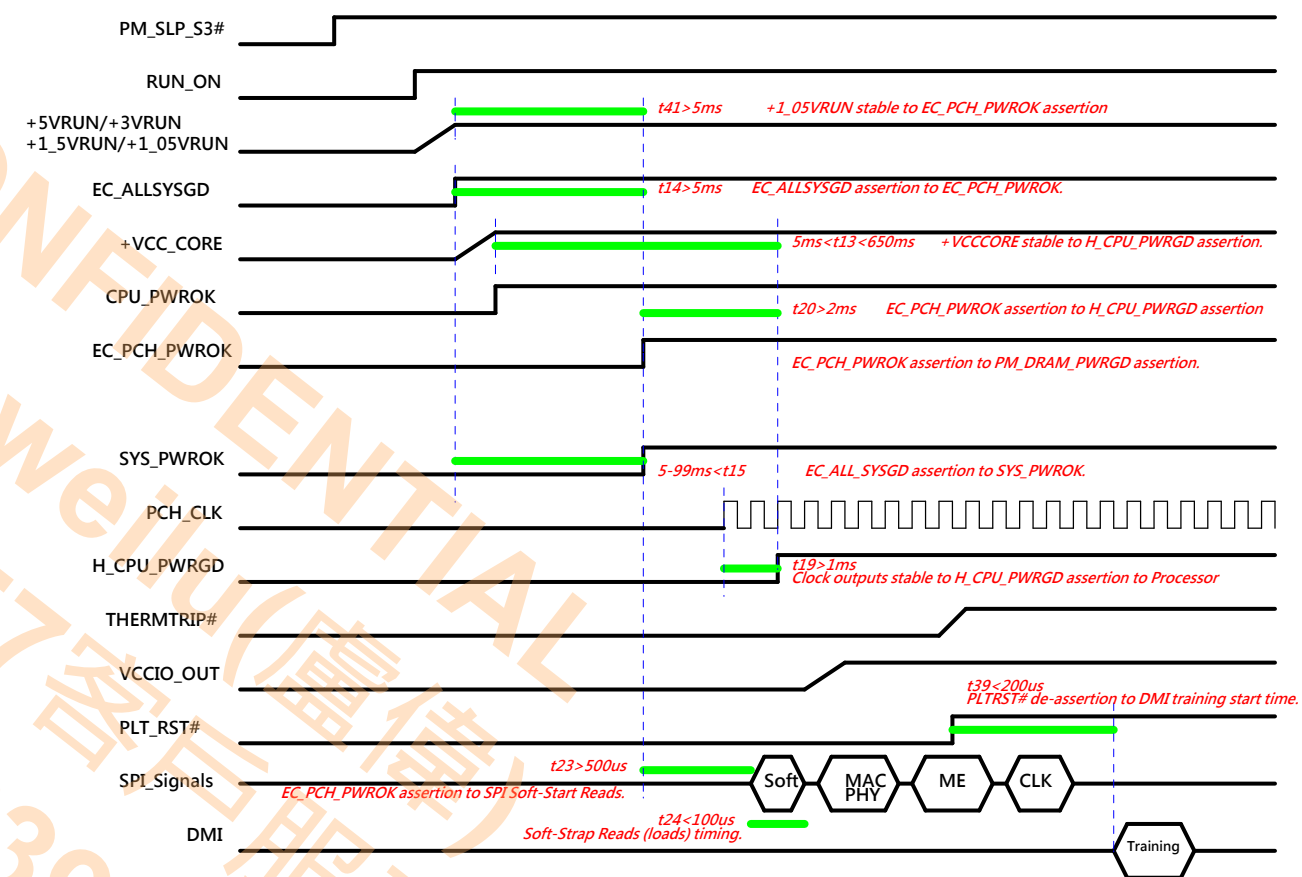


Power on Sequence

G3 -> S0

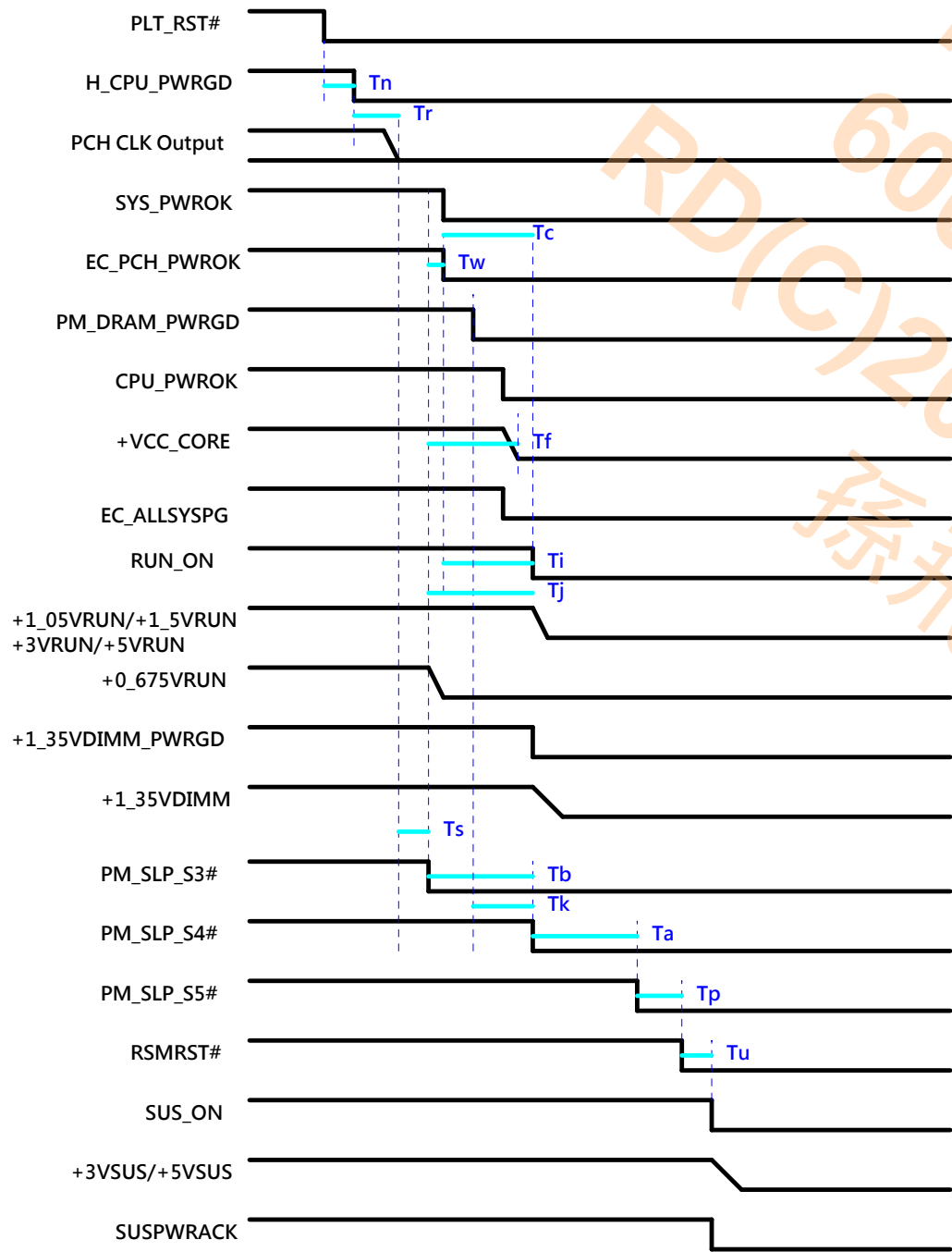


S3 -> S0



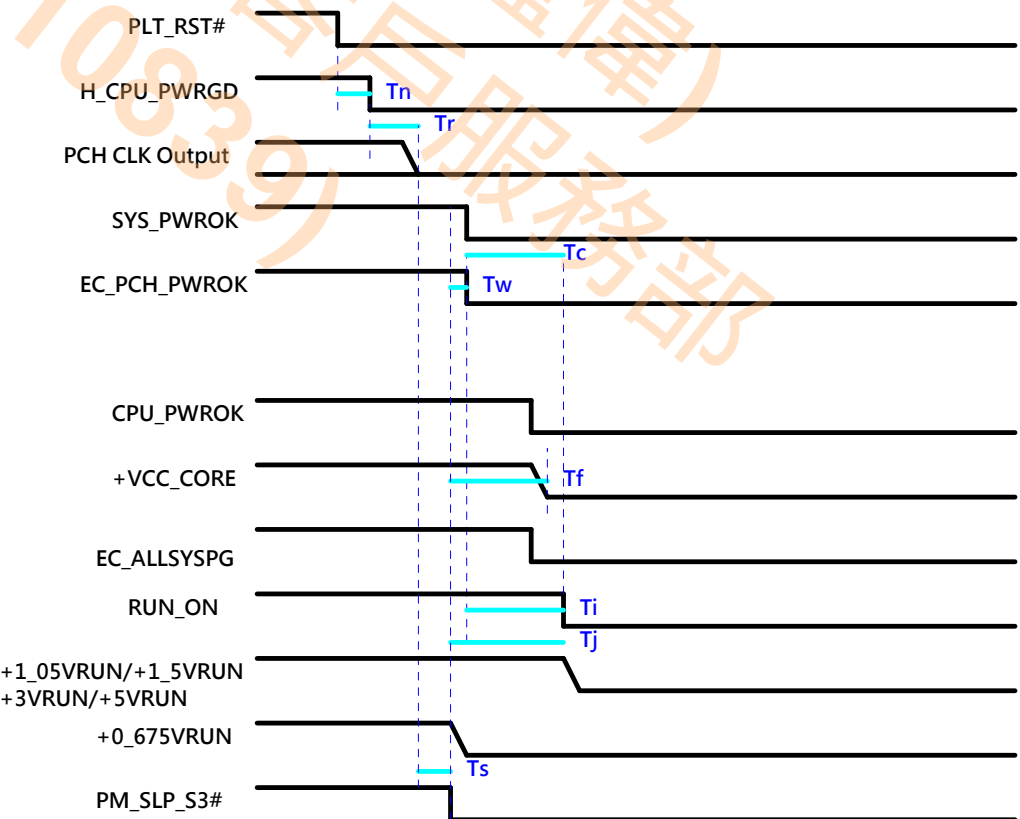
Power down Sequence

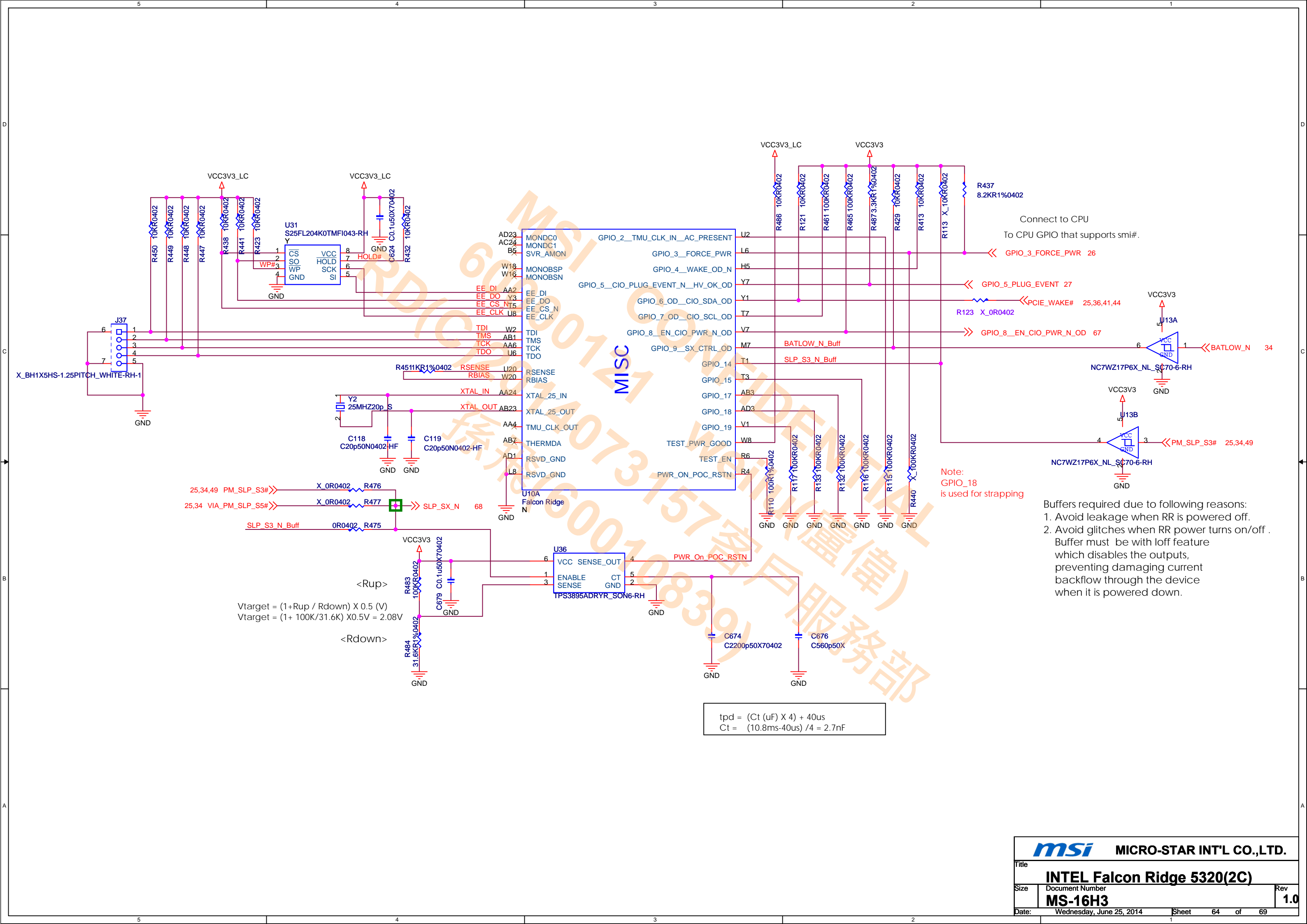
S0 -> G3

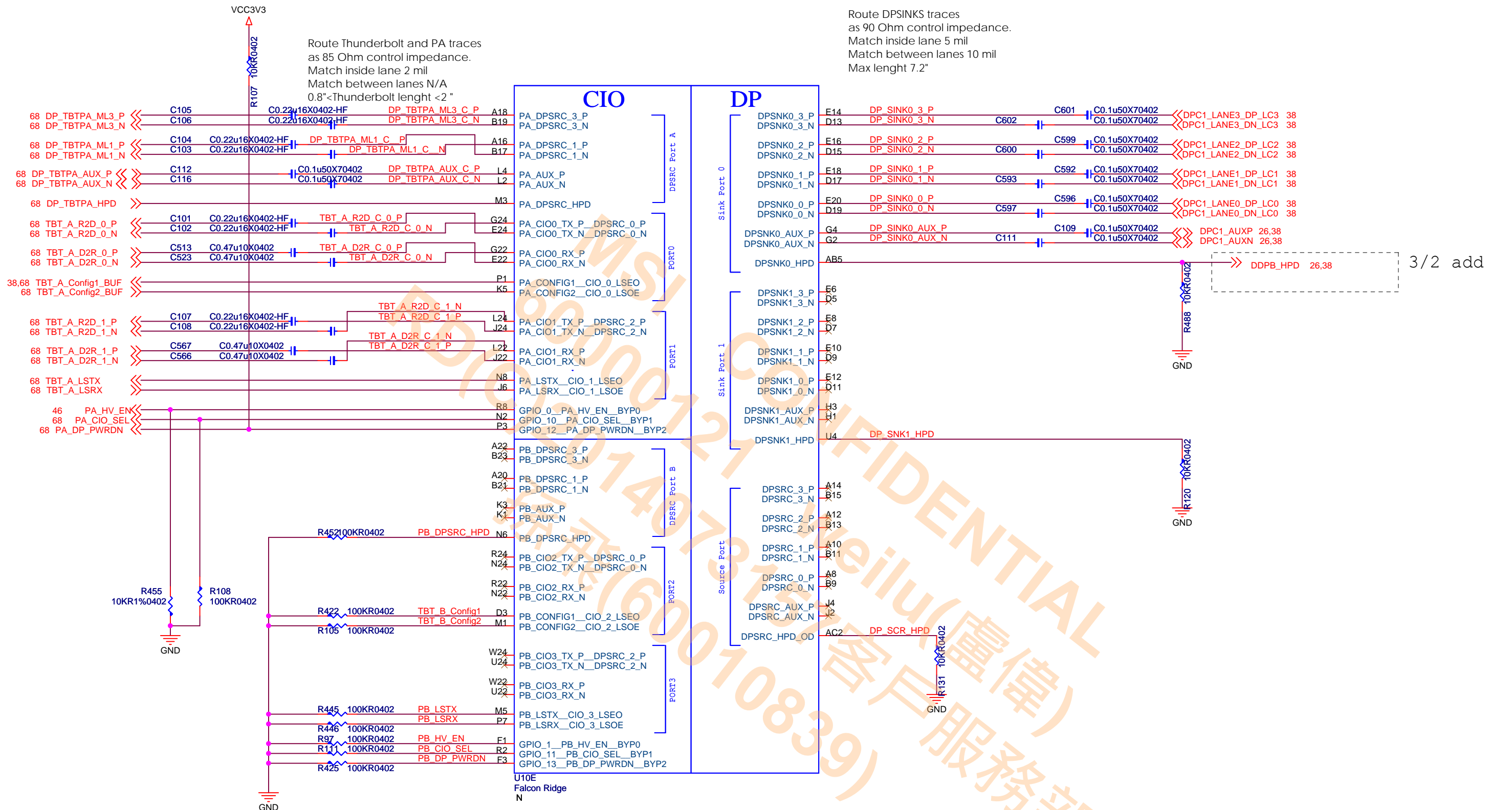


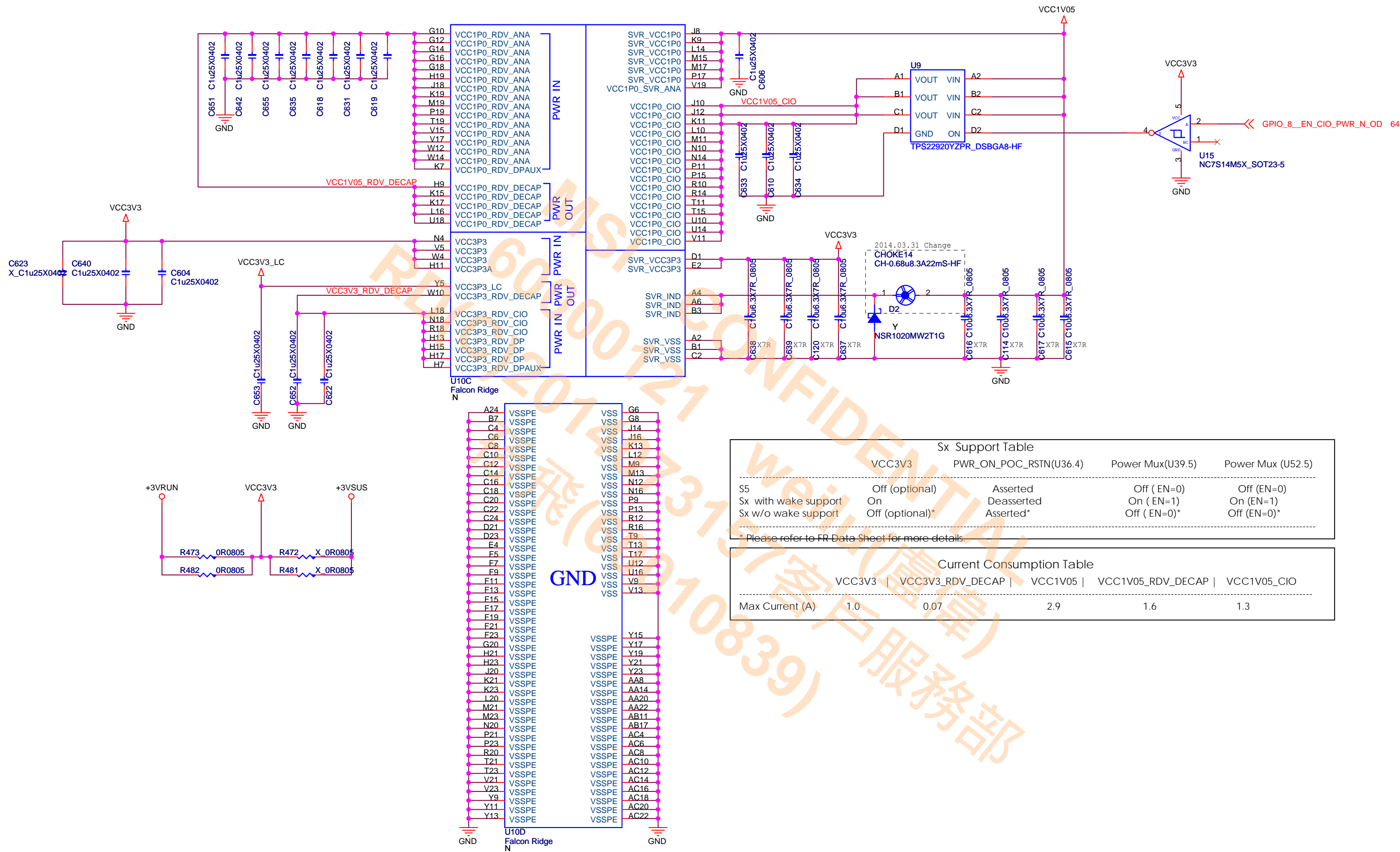
	MIN	MAX	Units	Description
Ta	30		us	SLP_S4# assertion to SLP_S5# assertion.
Tb	30		us	SLP_S3# assertion to SLP_S4# assertion.
Tc	40		ns	APWROK de-assertion to VCCASW/VCCSPI rails falling.
Tf		500	ms	SLP_S3# assertion to VCCIN(CPU) rail completely off.
Ti	40		ns	PWROK de-assertion to VCCCore (PCH) rail falling (-5% of nominal value).
Tj	5		us	SLP_S3# assertion to VCCCore (PCH) rails falling (-5% of nominal value).
Tk	-100		ns	DRAMPWROK de-assertion to SLP_S4# assertion
Tn	30		us	PLTRST# assertion to CPUPWRGOOD de-assertion.
Tp	500		us	Last SLP_Sx# or SLP_A# assertion to RSMRST# assertion
Tr	10		us	CPUPWRGOOD de-assertion to PCH clock outputs turning off.
Ts	1		us	PCH Clock outputs turning OFF to SLP_S3# assertion.
Tu	40		ns	RSMRST# assertion to VCCSUS rails falling (-5% of nominal value).
Tw	0		ms	SLP_S3# assertion to PWROK de-assertion.

S0 -> S3

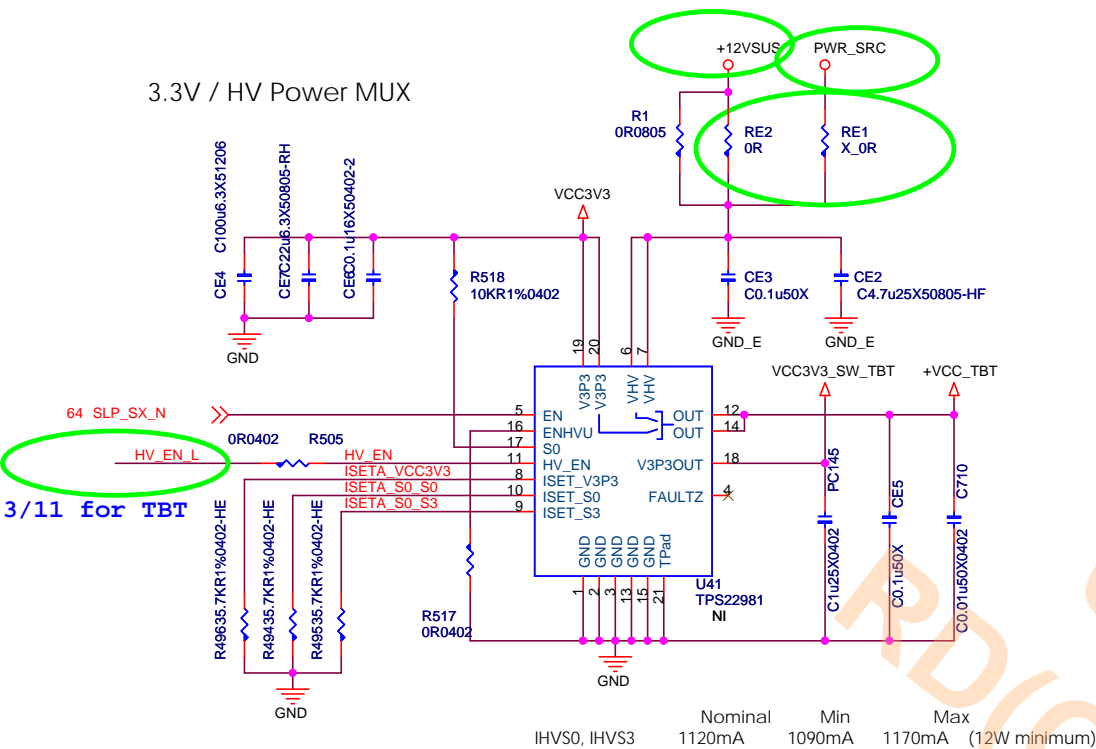




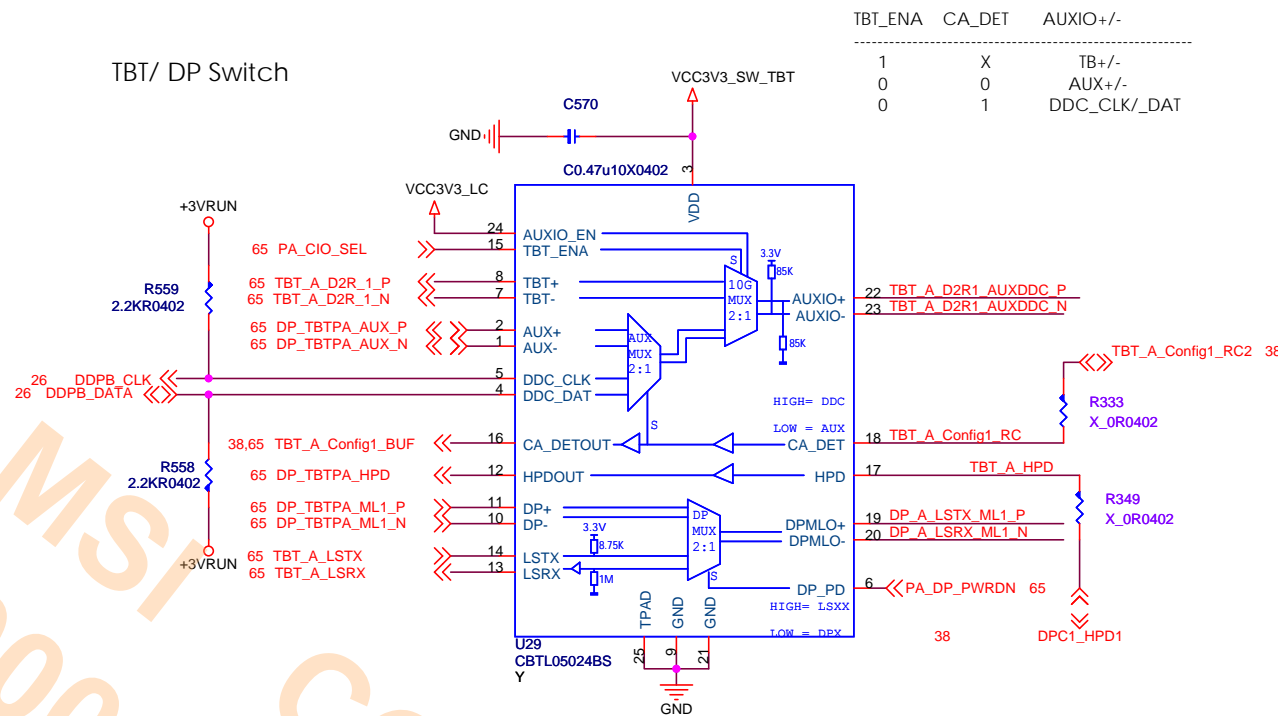




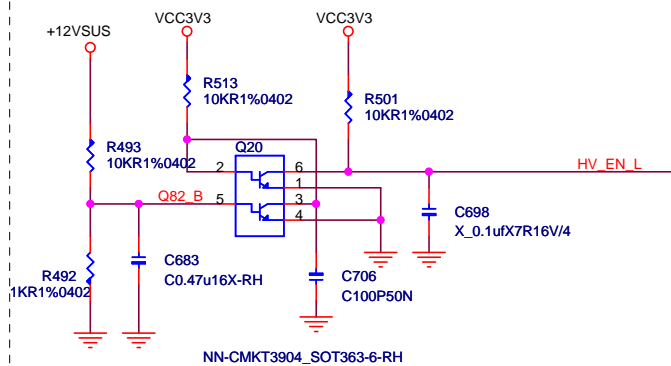
3.3V / HV Power MUX



TBT/ DP Switch

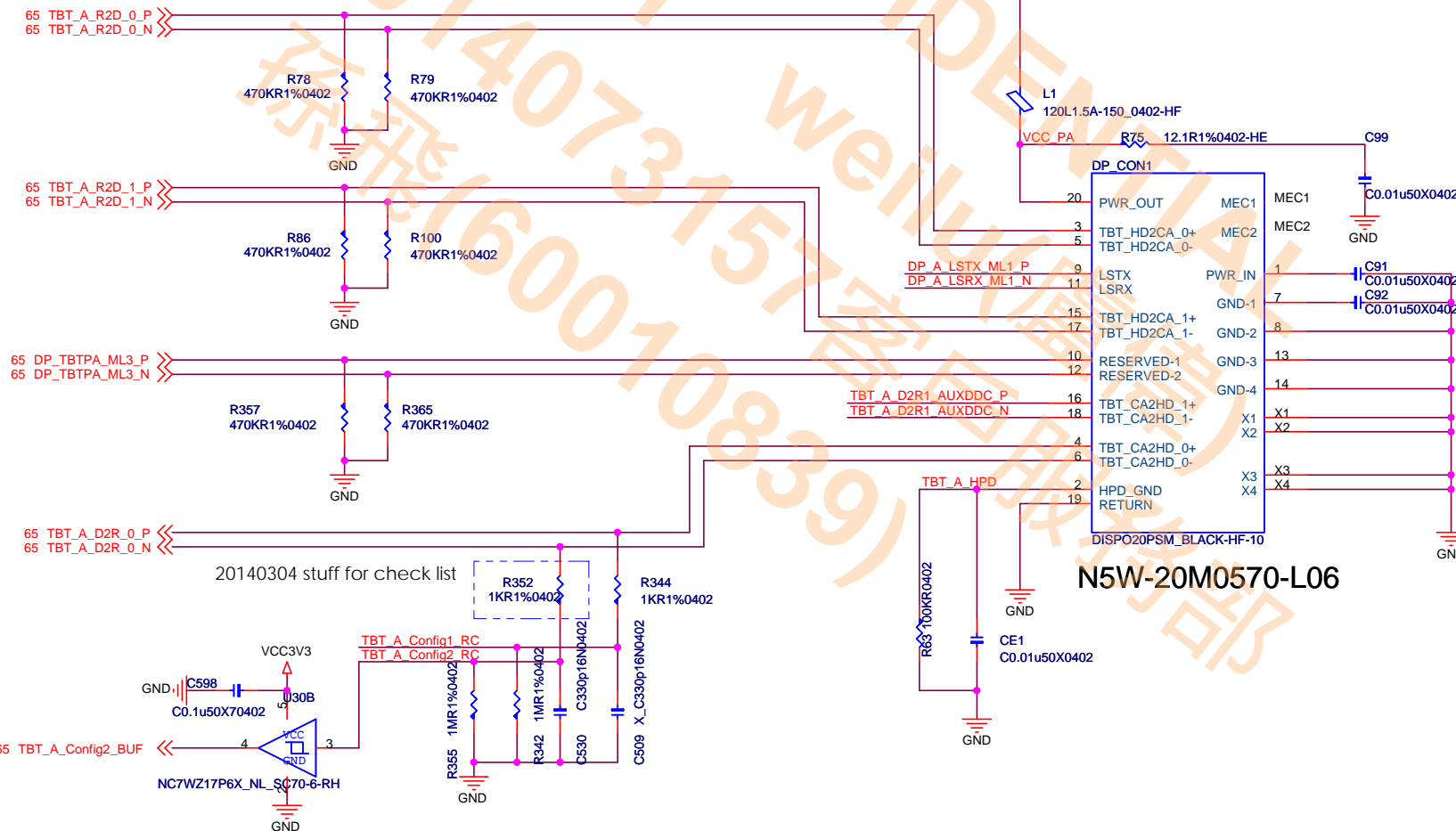


3/11 for TBT



Power mux will be on when VCC12V0 >=4.5V and off when VCC12V0 <=3.4V
 $V_{be} = 770mV @ I_c = 10mA \rightarrow 4.5V \times 2.05K / (10K + 2.05K) = 0.766V$


Note:
 If generating the 12v from a supply different than 3.3v - resistors values of R52 and R53 should be different
 Example: If VCC12V0 is boosted from 5V, the R52 is 10K ohm and R53 is 1K ohm



History

0A: Hardware part

- 01.RB4 , RB6 RB5 , RB7 , RB9 , RB10 470R change to 680R
- 02. Modify WLAN CLKREQ SCH , add R101
- 03. R440 unstuff , R437 stuff
- 04. Add TBT DDC Pull-high 2.2K , R558 and R559
- 05. RA2 and RA6 unstuff
- 06. Add U46 sch for ASM1042 1.05VRUN
- 07. Modify HDMI SCH , D3 change to D01-BAT5429-D07 ,add C782 and C783
- 08. CPU change part number for each item.
- 09. Samsung VRAM EOL , change to Hynix
- 10. Add C785 and C784 for PWR_SCR
- 11. Add C786 for 3VRUN
- 12. Add C787 for VBATA
- 13. R396 change connect to 3VSUS
- 14. rename 3V3_NV to +3V3_NV
- 15. Swap RTC pin
- 16. change EL3 , ELA5 , ELA2 and LI6 PN to L12-9008100-I05
- 17. R30 change to 10k and C67 , C68 unstuff for EC_ALLSYSPG sequency
- 18. Revese Q6, Q15, Q19 DS pin for power on sequence
- 19. C594 unstuff
- 20. R40 change to 0ohm and C77 unstuff
- 21. Add eight RF clamp
- 22. remove F1
- 23. R387 change to 47K
- 24. Add PQ62 sch for DGPU power control
- 25. EC59 stuff
- 26. ASM 1042 SCH unstuff

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